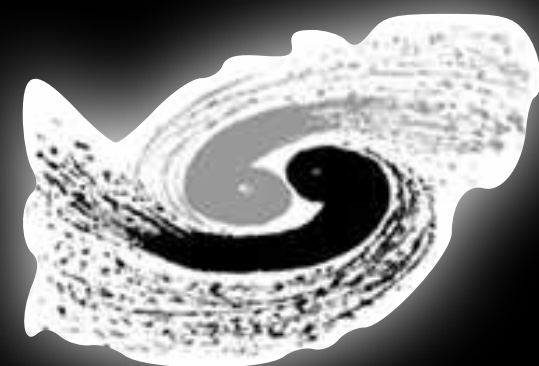


Detectors for Future Colliders

New Tools for the Next Generation of Particle Physics and Cosmology
Gordon Research Conference

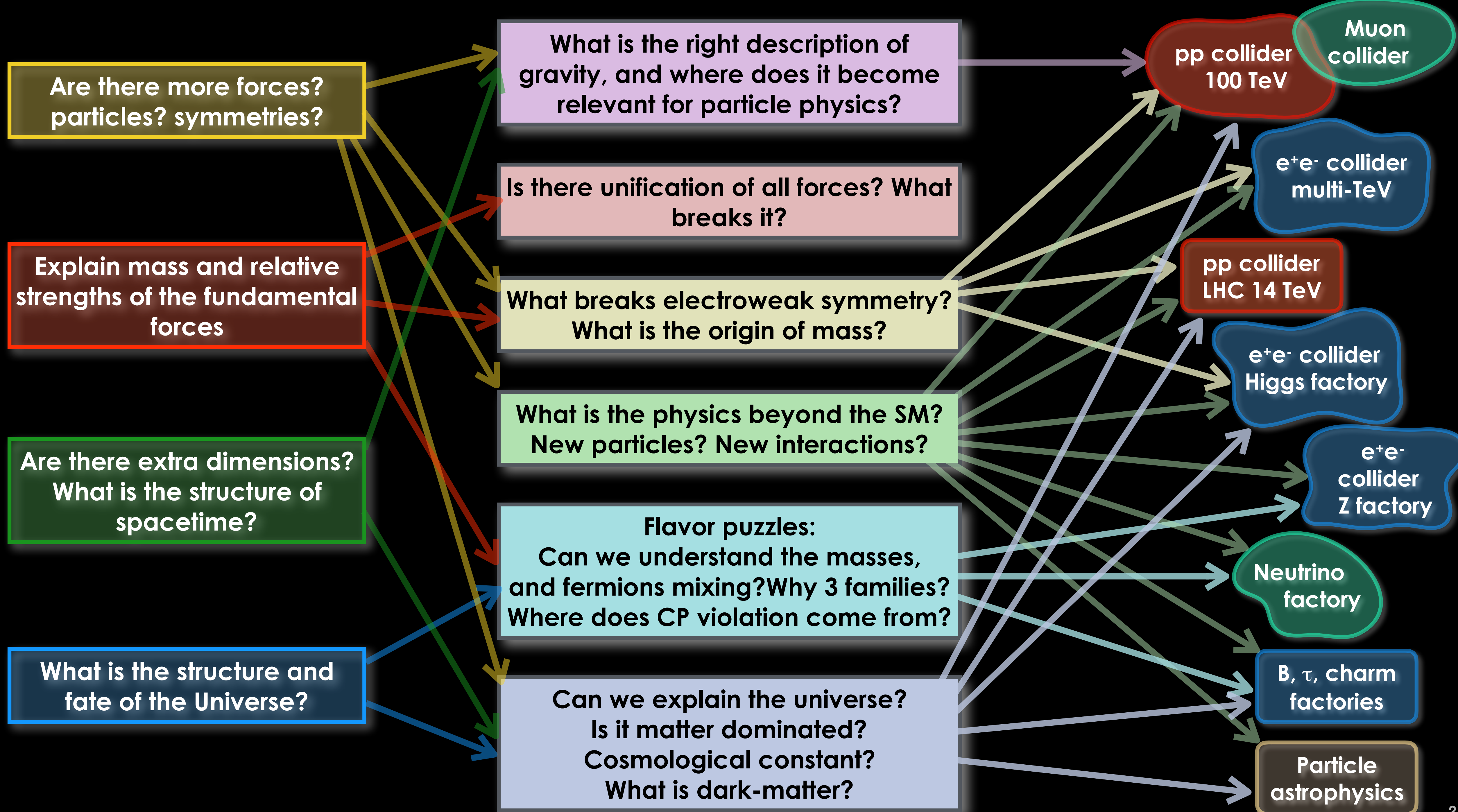
Institute for Advanced Study, HK University of Science and Technology
June 30 - July 5, 2019

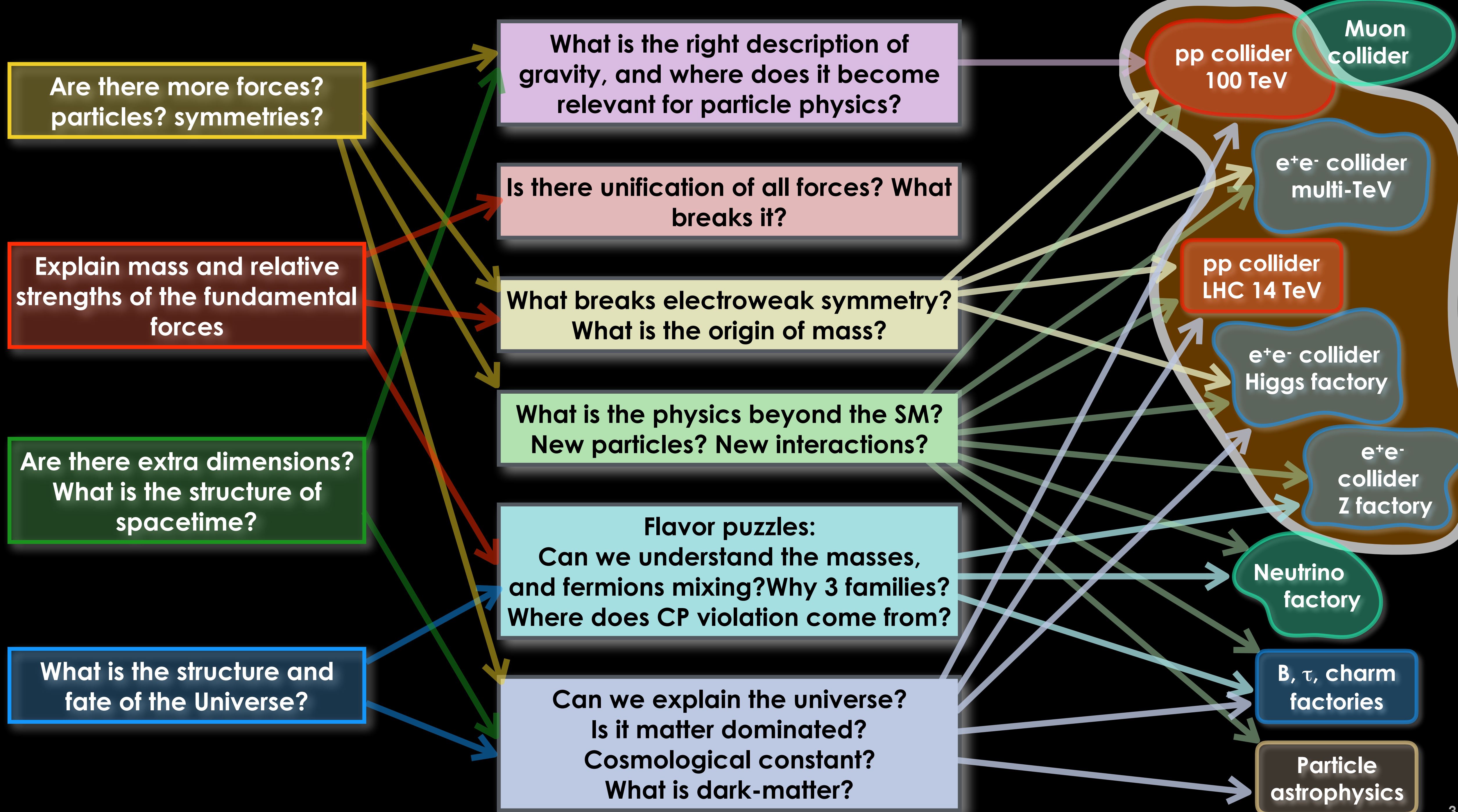
João Guimarães da Costa



中国科学院高能物理研究所

*Institute of High Energy Physics
Chinese Academy of Sciences*





The highest **energy** possible

The highest **luminosity** possible

As **low backgrounds** as possible

After the Higgs boson discovery, no other new physics found
Need to also pursue outstanding precision

- PRECISION IS ESSENTIAL -

High Energy Colliders

Hadron Colliders

LHC, HL-LHC 2026-2036

HE-LHC: pp 27 TeV

pp 100 TeV, 100 km collider
40/50 TeV?

SppC, FCC-hh

Lepton Colliders

Electron-positron Colliders

Linear machines

ILC, CLIC

Circular machines

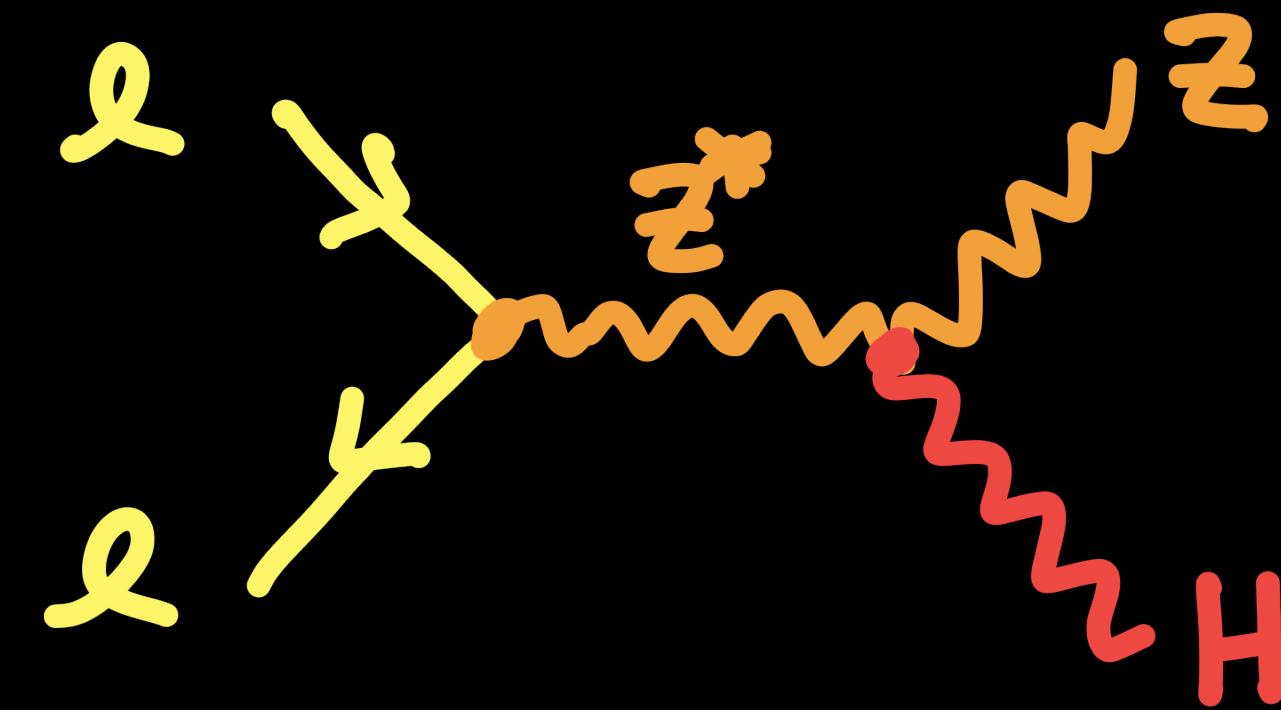
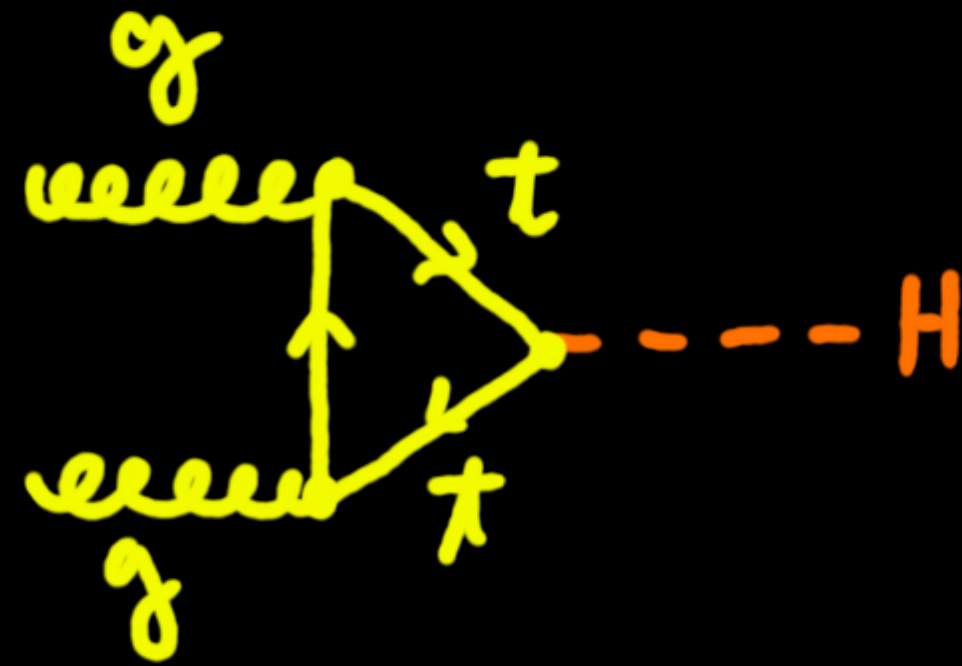
CEPC, FCC-ee

Muon Colliders

Proton driver (MAP)
Low emittance (LEMMA)

EIC, LHeC, FCC-eh and VHEeP: e-hadron scattering — precision PDF

Hadron versus lepton colliders



1. Protons are compound objects

- Initial state unknown (particle and momentum)
- Limits achievable precision

2. High rates of QCD background $S/B \sim 10^{-10}$

- Complex triggers
- High levels of radiation
 - Detector design focus on radiation hardness of many sub-detectors

3. Very high-energy circular colliders feasible

1. Electrons are point-like particles

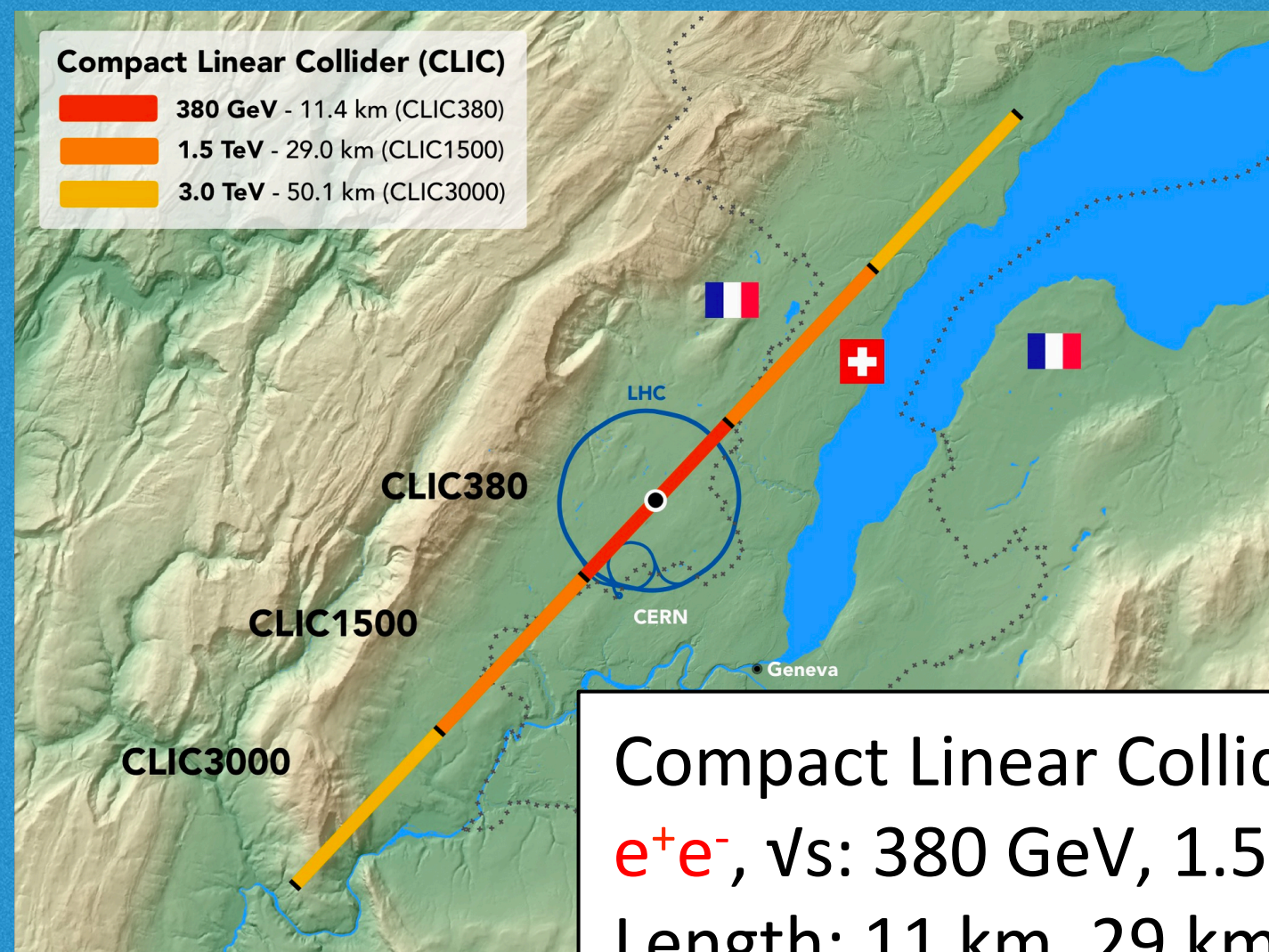
- Initial state well-defined (particle, energy, polarization?)
- High-precision measurements

2. Clean experimental environment $S/B \sim 10^{-3}$

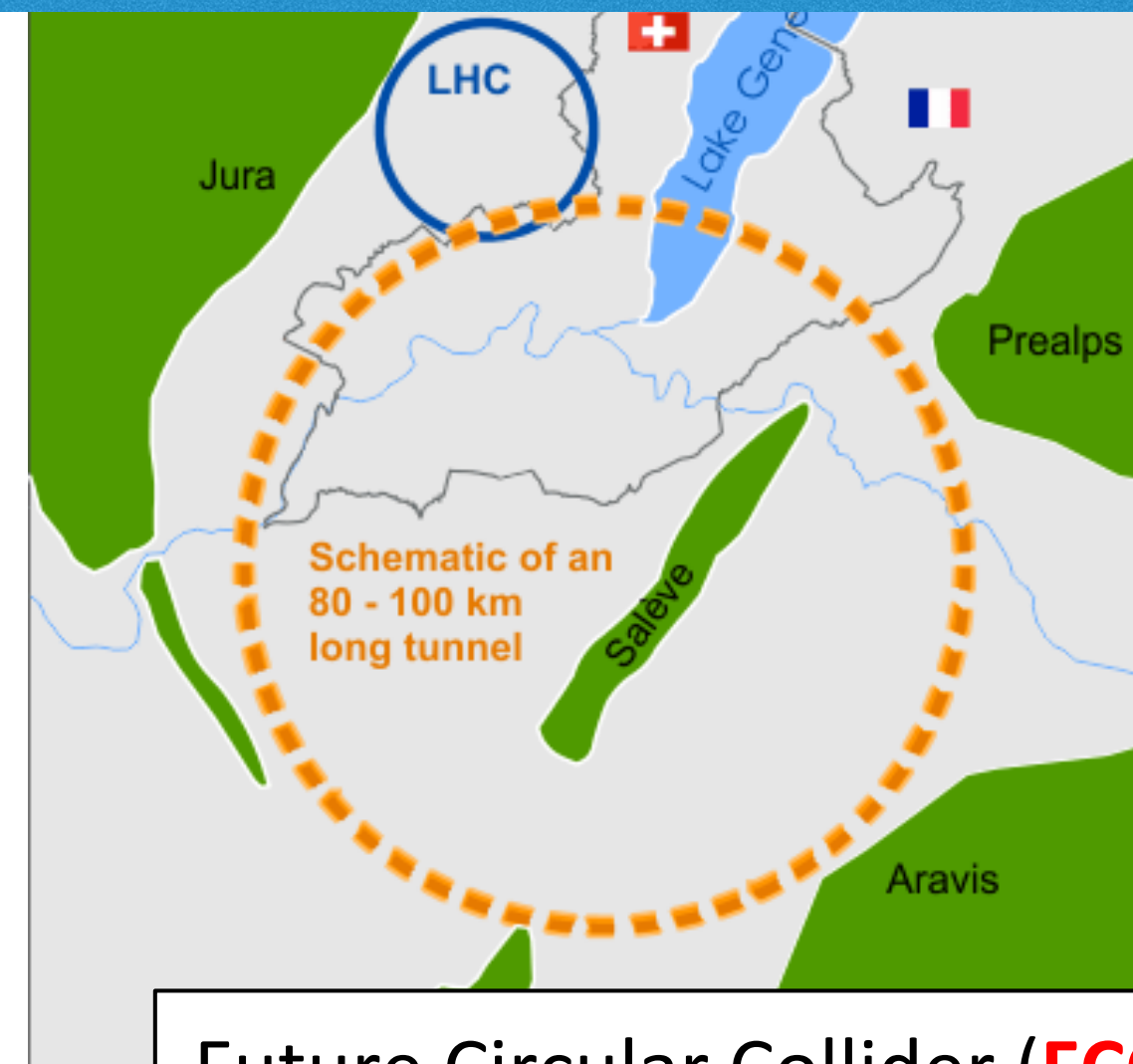
- No (less) need for triggers
- Lower levels of radiation

3. Very high-energies require linear colliders

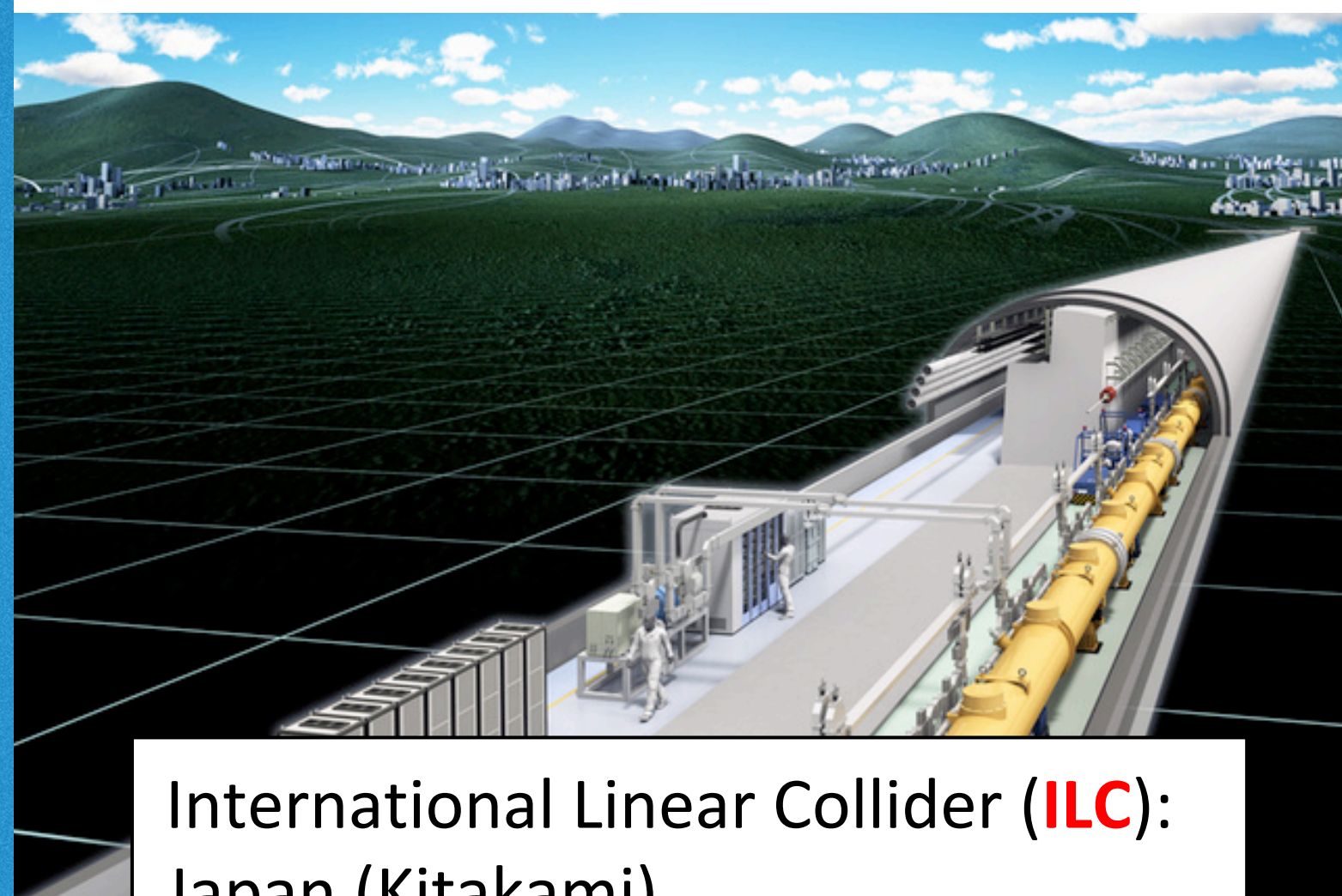
High-energy e^+e^- collider projects



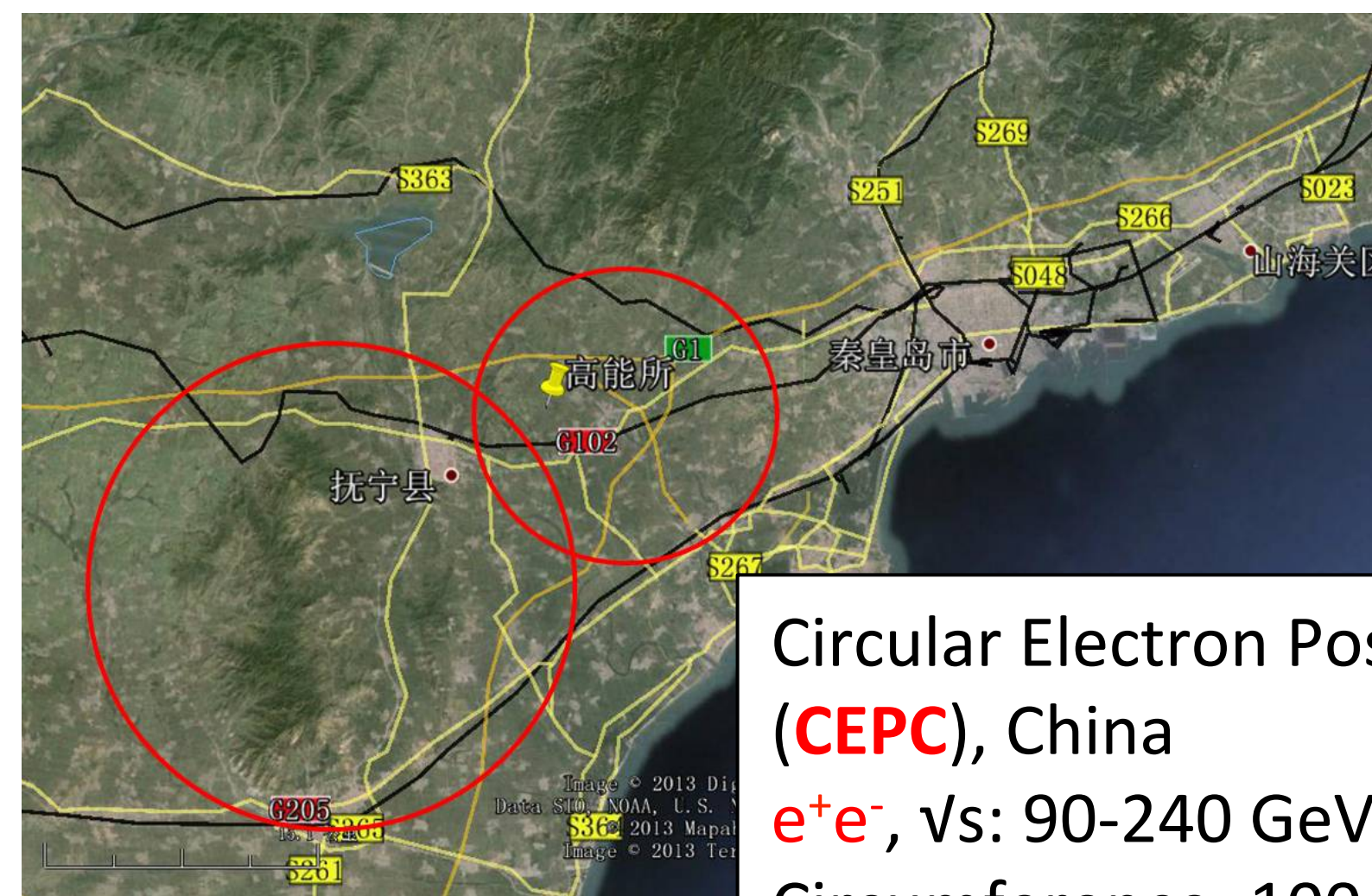
Compact Linear Collider (**CLIC**): CERN
 e^+e^- , vs: 380 GeV, 1.5 TeV, 3 TeV
 Length: 11 km, 29 km, 50 km



Future Circular Collider (**FCC-ee**): CERN
 e^+e^- , vs: 90 - 350 (365) GeV; FCC-hh pp
 Circumference: 97.75 km

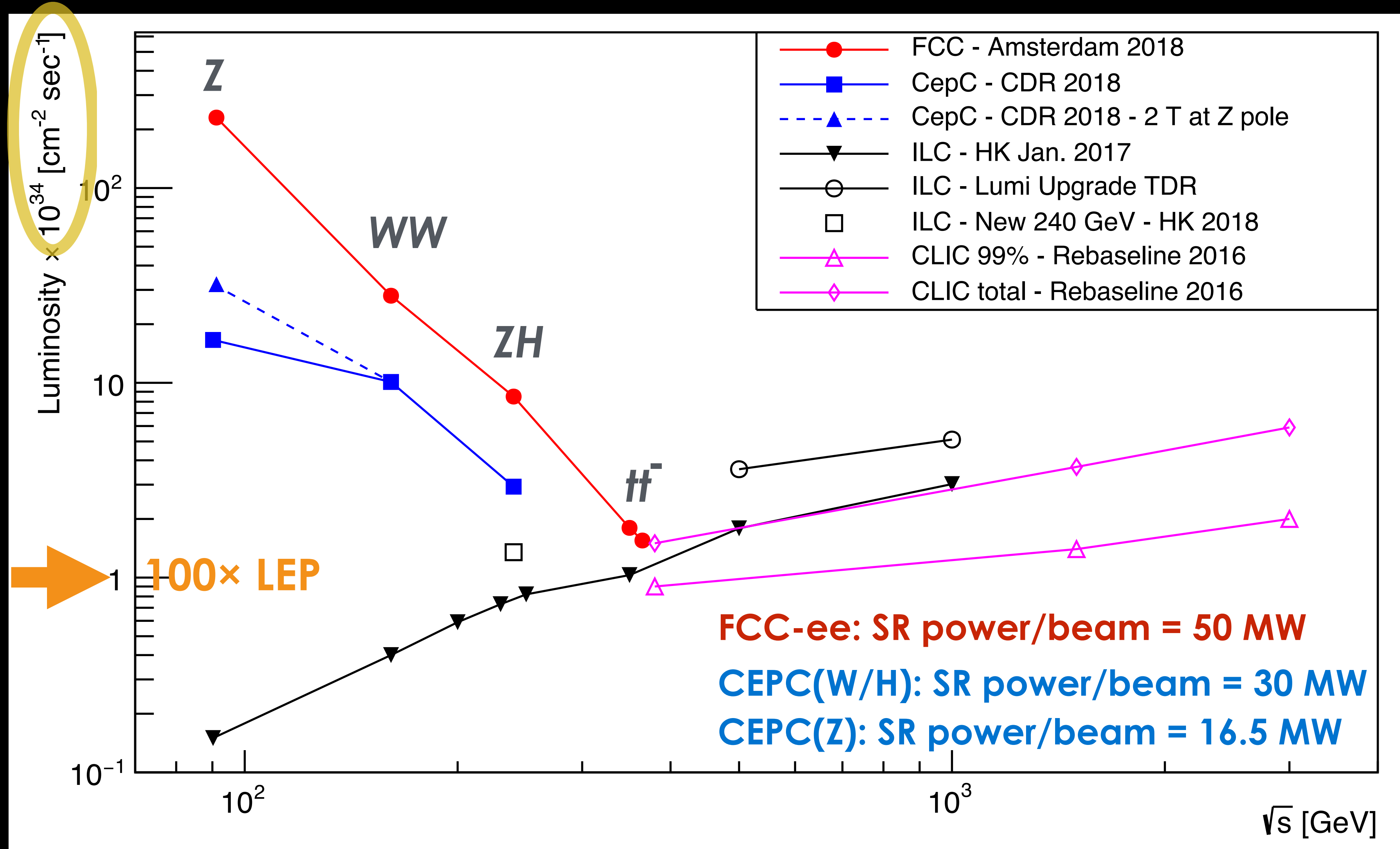


International Linear Collider (**ILC**):
 Japan (Kitakami)
 e^+e^- , vs: 250 - 500 GeV (1 TeV)
 Length: 17 km, 31 km (50 km)



Circular Electron Positron Collider (**CEPC**), China
 e^+e^- , vs: 90-240 GeV; SPPC pp,
 Circumference: 100 km

Luminosity performance in e^+e^- colliders



Linear Colliders

- Can reach much higher energy
- Luminosity increases with increasing energy
- Beam polarization possible at all energies

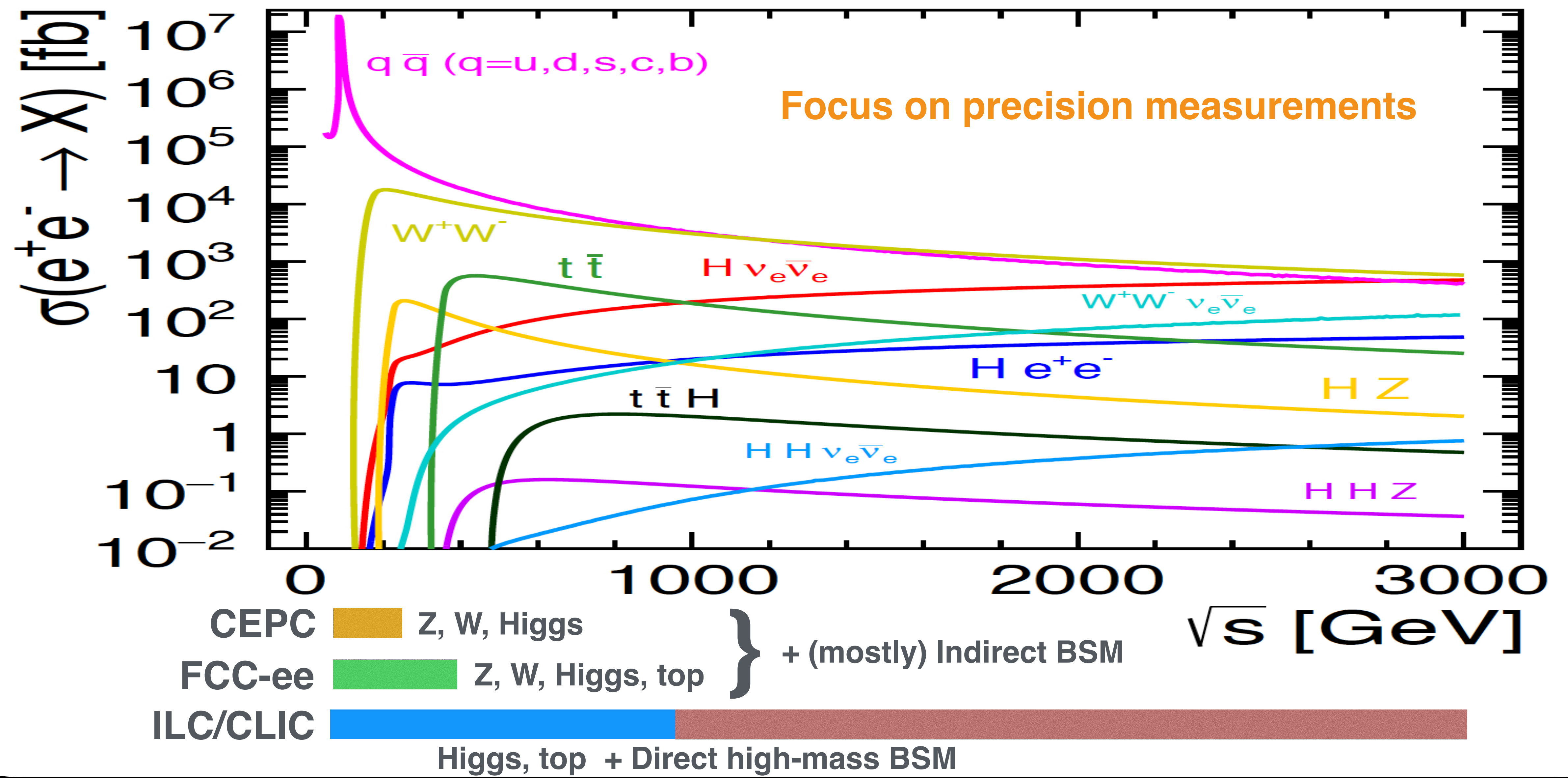
- Small beam size and high beam power
- **Beamstrahlung, energy spread**

Circular Colliders

- Luminosity increases with decreasing energy
- Huge luminosity at lower energies
- Expensive to run at higher energies

Peak luminosity at LEP2 (209 GeV) was $\sim 10^{32} \text{ cm}^{-2}\text{s}^{-1}$

Physics programs — depending on energy reach



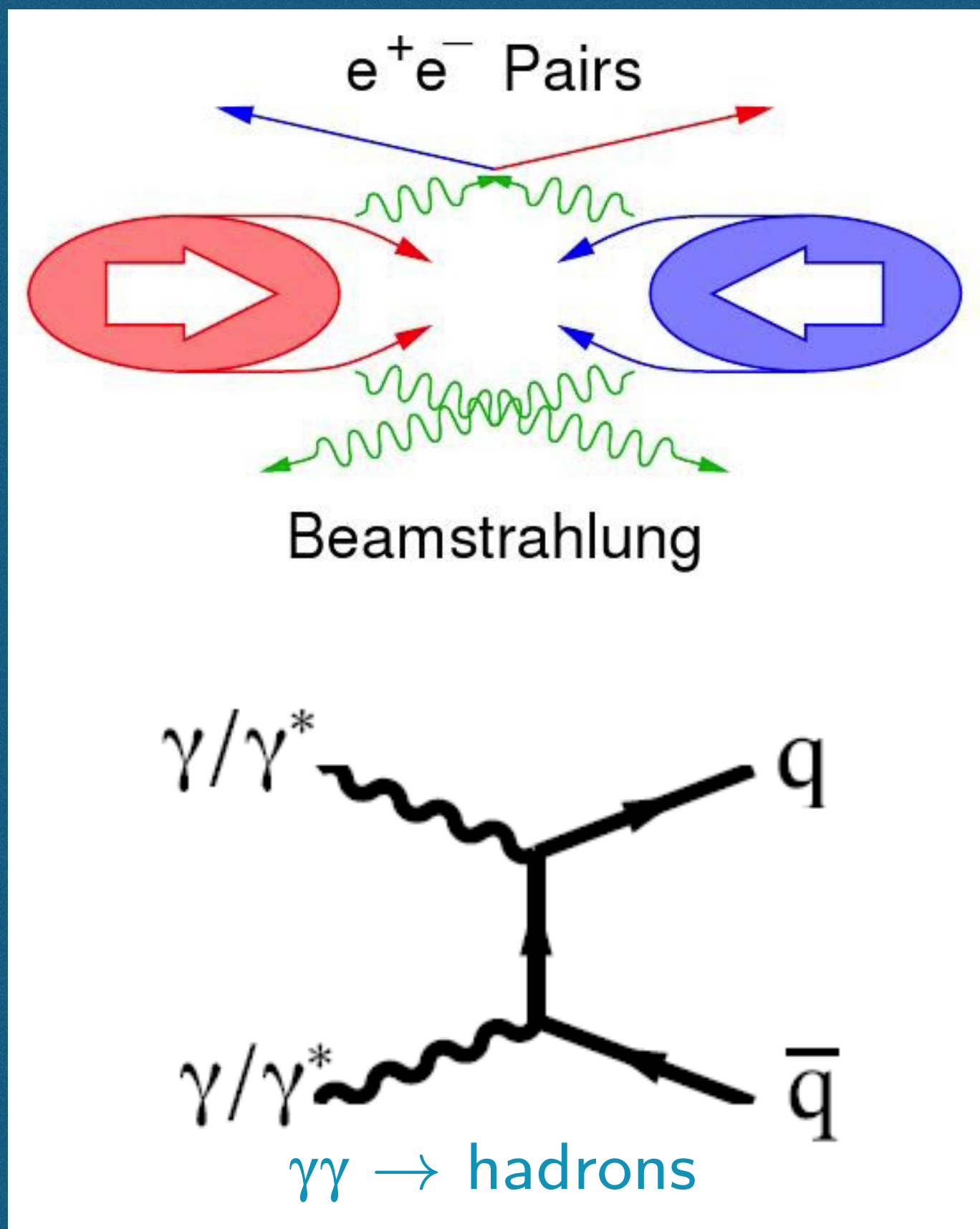
Experimental conditions in linear and circular colliders

Impact on detector design

Beam-induced backgrounds

Linear collider: Achieve high luminosities by using extremely small beam sizes

3 TeV CLIC: Bunch size: $\sigma_{x:y:z} = \{40 \text{ nm}; 1 \text{ nm}; 44 \mu\text{m}\} \rightarrow$ beam-beam interactions



Main Backgrounds ($p_T > 20 \text{ MeV}, \theta > 7.3^\circ$)

Incoherent e⁺e⁻ pairs:

- 19k particles/bunch train at 3 TeV
- High occupancies
 \rightarrow Impact on detector granularity

$\gamma\gamma \rightarrow$ hadrons:

- 17k particles/bunch train at 3 TeV
- Main background in calorimeters and trackers
 \rightarrow Impact on detector granularity and physics

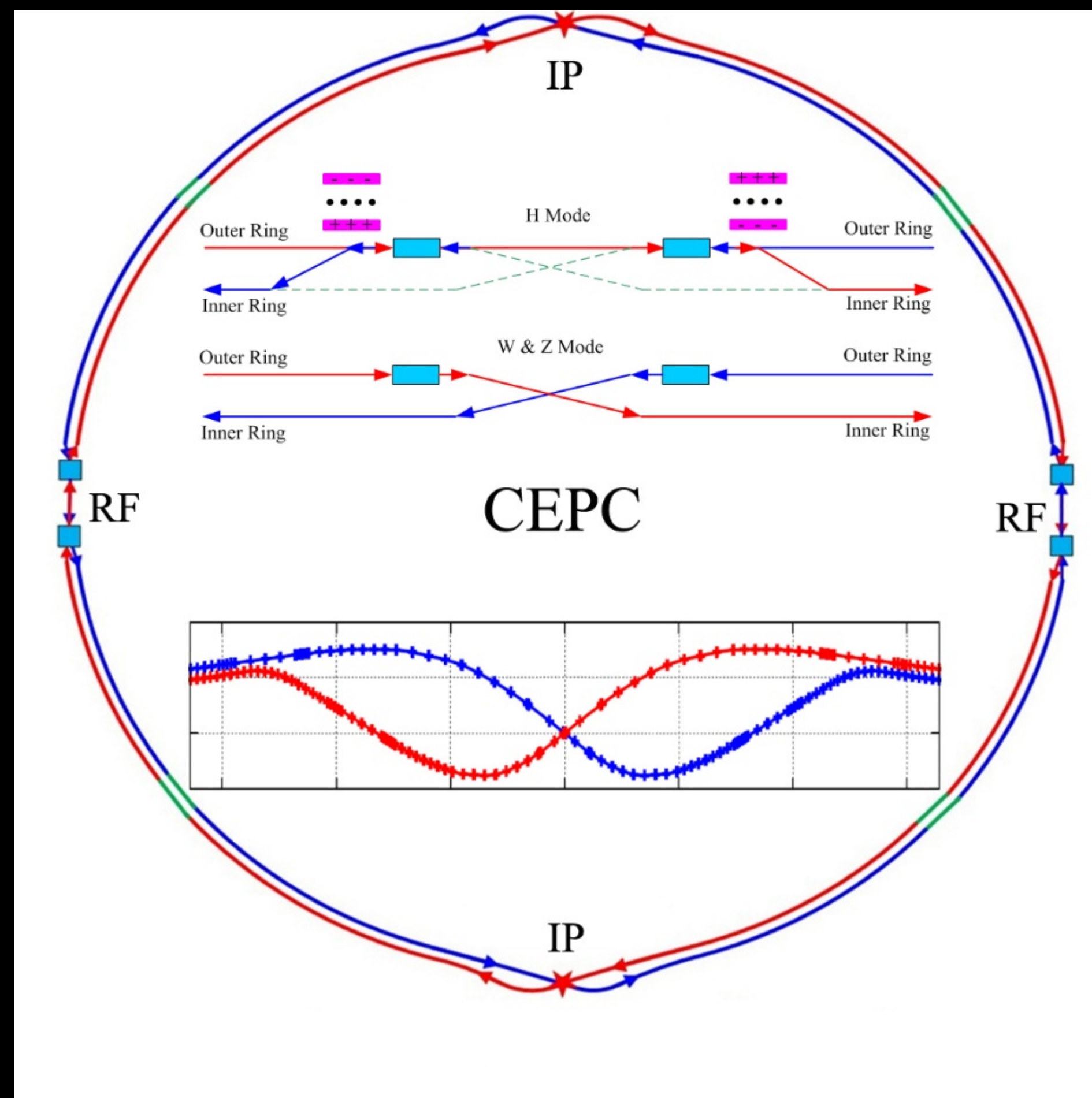
Circular collider: same processes but to much low extent, plus synchrotron radiation

Synchrotron radiation in circular colliders

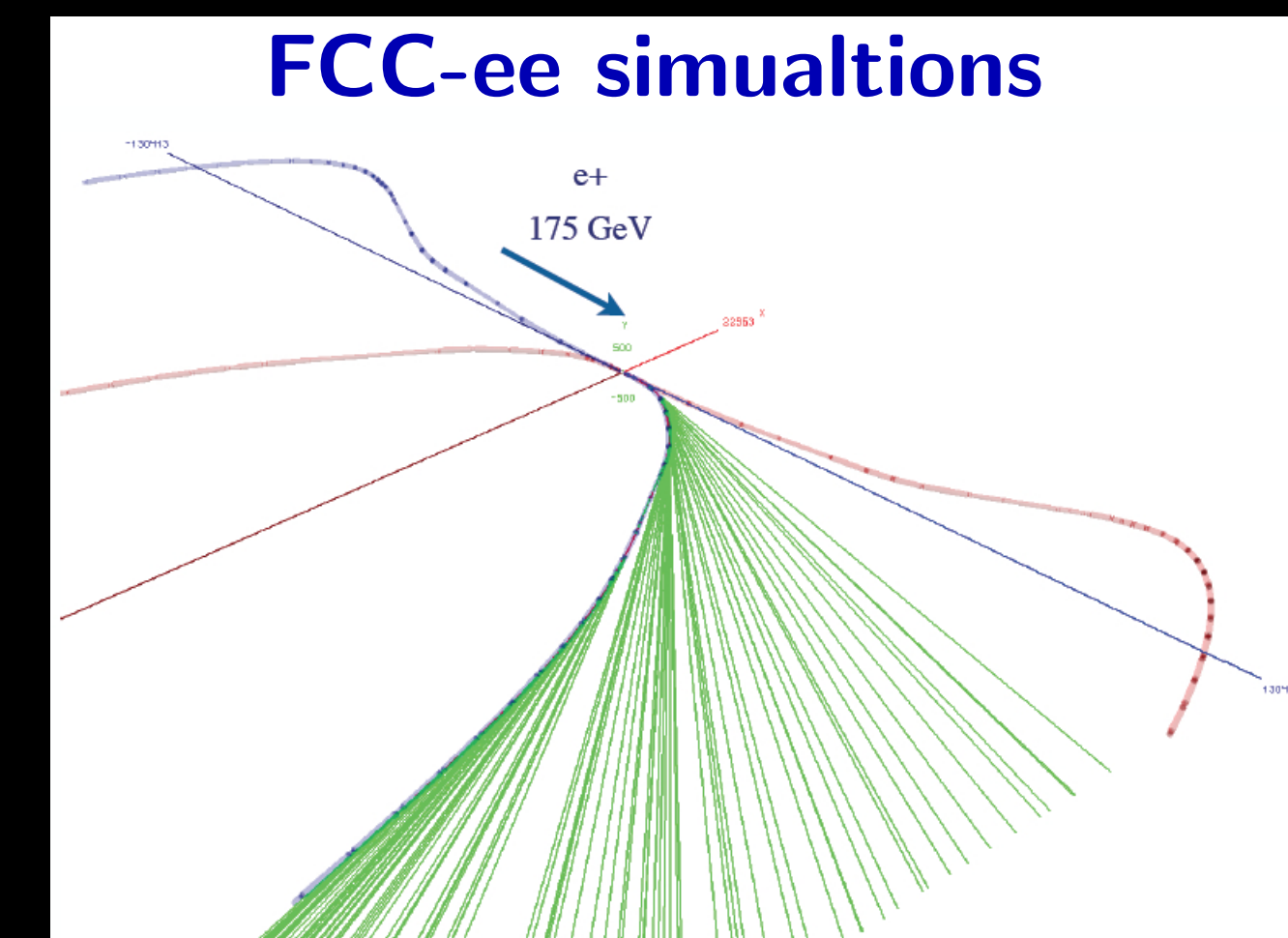
Synchrotron radiation:

$$\sim \frac{E_{beam}^4}{m_e^4 \times r}$$

2.75 GeV/turn lost at LEP at E = 105 GeV
(0.09 GeV/turn at E = 45 GeV)



asymmetric layout



Property

FCC-ee (100 km)

CEPC (100 km)

Beam energy (GeV)

45.6

80

120

175

45.6

80

120

Energy loss/turn (GeV)

0.03

0.33

1.67

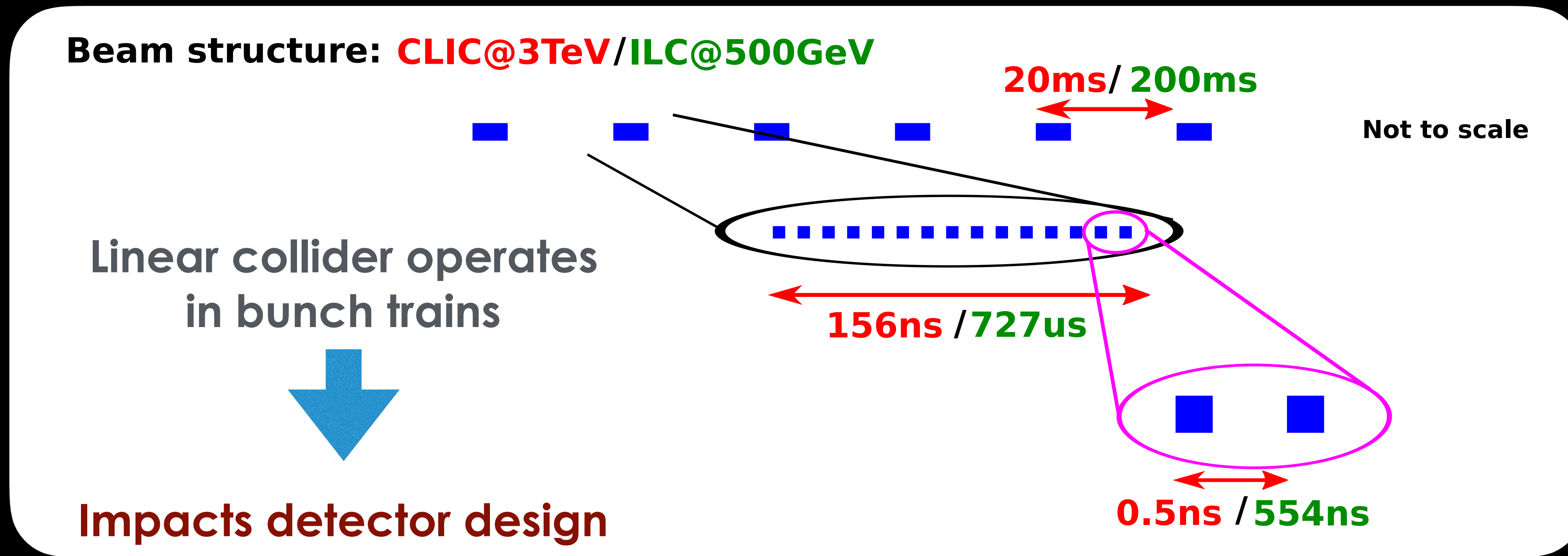
7.55

0.036

0.34

1.73

Duty cycle and bunch separation in **linear colliders**



Property	ILC		CLIC	
	500 GeV	1 TeV	380 GeV	3 TeV
\sqrt{s}				
Repetition rate	5 Hz	4 Hz	50 Hz	50 Hz
Train duration	727 μ s	897 μ s	178 ns	156 ns
BX / train	1312	2450	356	312
Bunch separation	554 ns	366 ns	0.5 ns	0.5 ns
Duty cycle	0.36%	0.36%	0.00089%	0.00078%

→ **Low duty cycle**

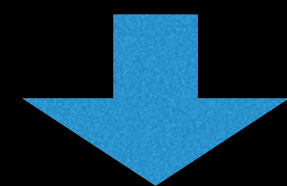
→ **Possibility to power pulse the detectors**

ILC 250 GeV similar specs

High luminosities in circular colliders

Property	FCC-ee (100 km)				CEPC (100 km)		
Beam energy (GeV)	45.6	80	120	175	45.6	80	120
Luminosity/IP ($10^{34}\text{cm}^{-2}\text{s}^{-1}$)	230	28	8.5	1.5	32	10	3
Bunches/beam	16640	2000	393	48	12000	1524	242
Bunch separation (ns)	20	160	830	8300	25	260	680

Luminosity up to $\sim 10^{36} \text{ cm}^{-2}\text{s}^{-1}$



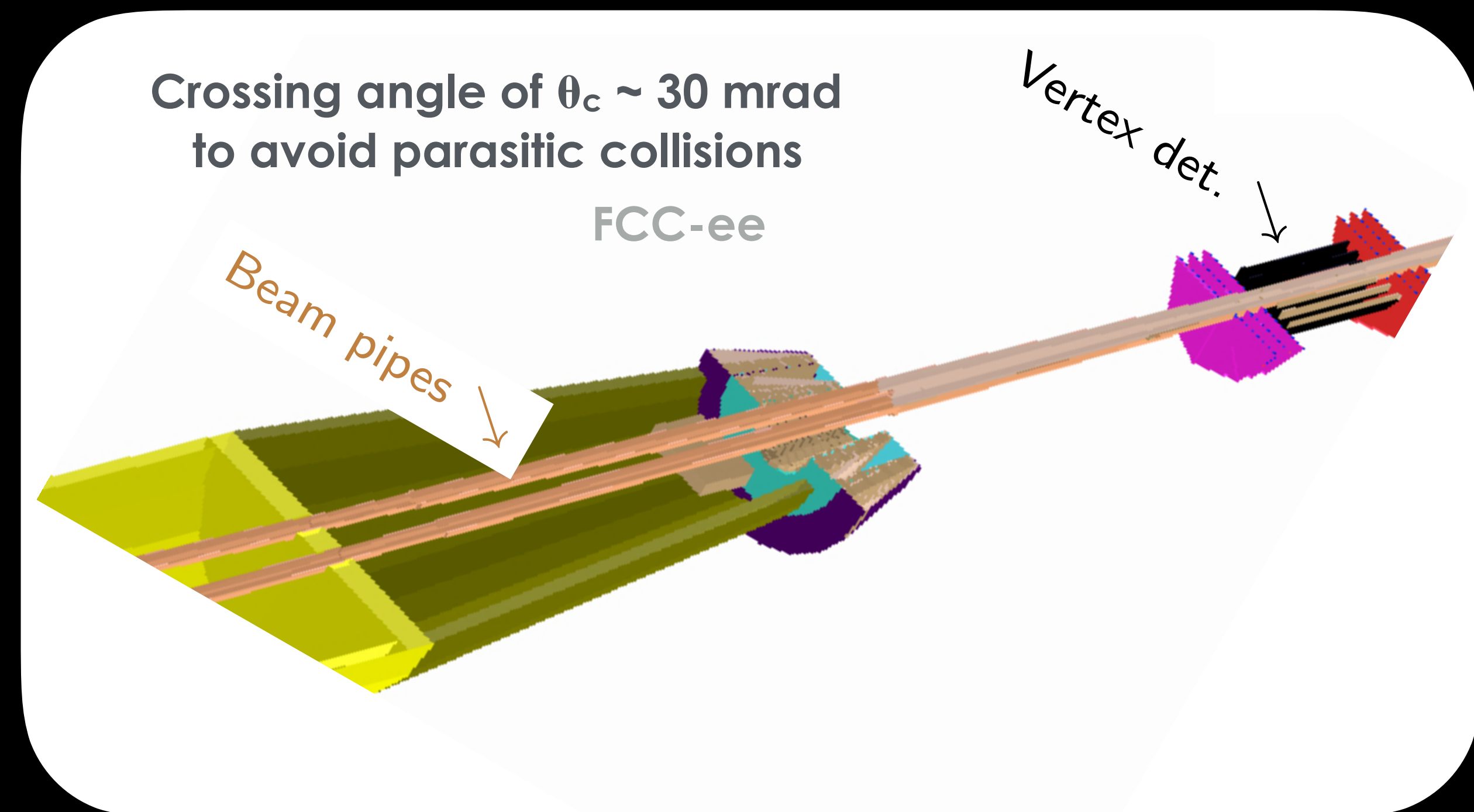
Large number of bunches

Consequences for detector design

Crossing angle at IP

Bunch separation impacts overall designs

No power pulsing of detectors



Detector requirements from physics

Momentum resolution :

- Higgs recoil mass, Higgs coupling to muons, smuon endpoint

$$\sigma_{p_T}/p_T^2 \sim 2 \times 10^{-5} \text{GeV}^{-1} \text{ for high-}p_T$$

Impact parameter resolution:

- c/b-tagging, Higgs branching ratios

$$\sigma_{r\phi} \sim a \oplus b/(p[\text{GeV}]\sin^2 \theta) \mu\text{m}$$

$a = 5 \mu\text{m}, b = 10-15 \mu\text{m}$

Jet energy resolution:

- Separation of W/Z/H in di-jet modes

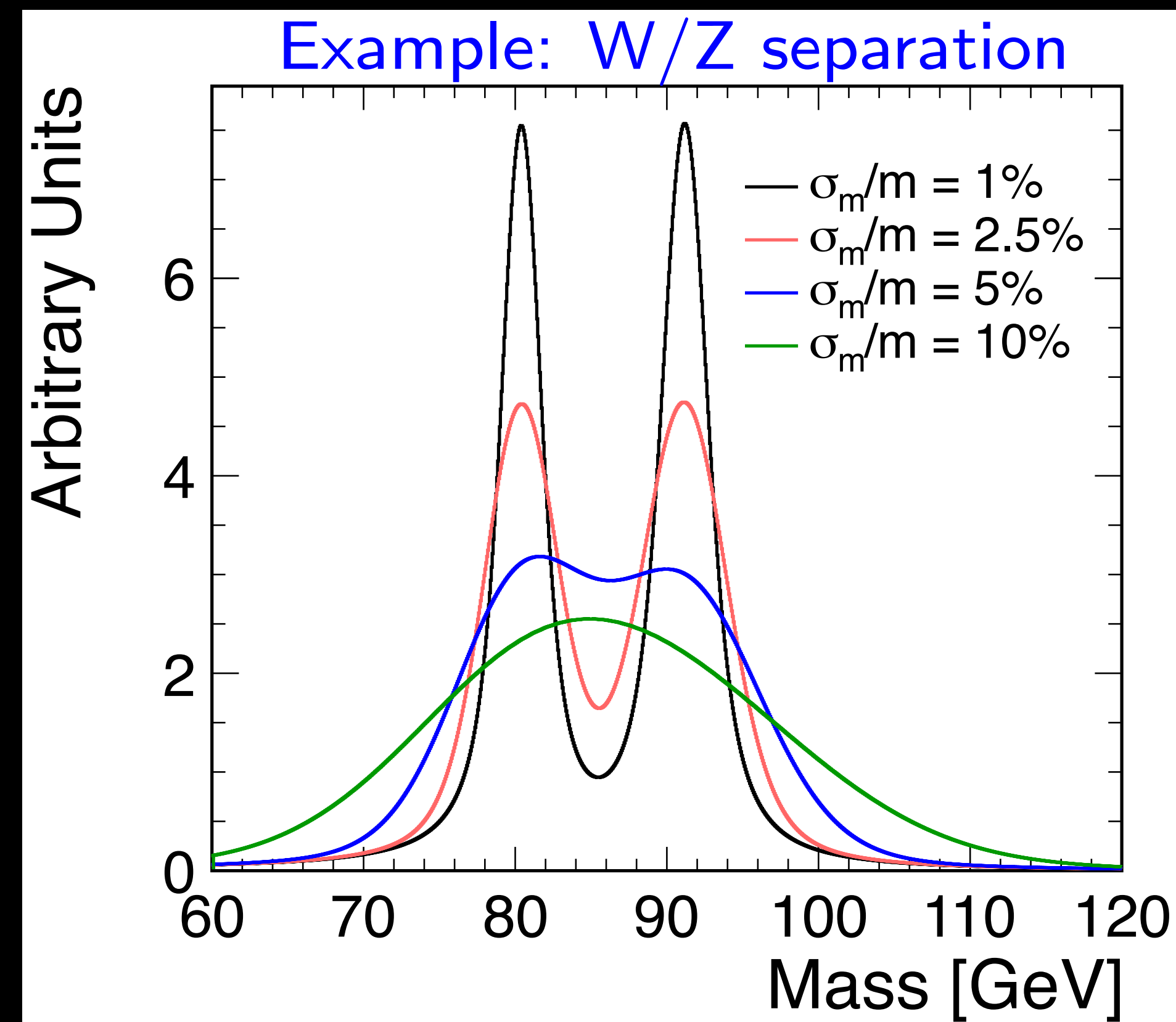
$$\sigma_E/E \sim 3.5\% \text{ for jets above } 50 \text{ GeV}$$

Large angular coverage

- Forward electron and photon tagging

Requirements from beam environment

- Solenoid field, beam structure, beam induced backgrounds



Generic detector requirements for high-energy e^+e^- colliders

Precision measurements

Require excellent **momentum resolution and flavor tagging**

Low-mass vertex and tracking detectors, high granularity

Require excellent **energy resolution**

Employ excellent calorimeters (particle flow, dual readout)

No major concerns about radiation hardness, unless for very forward detectors and inner most layer of vertex detector

Complementary subsystems

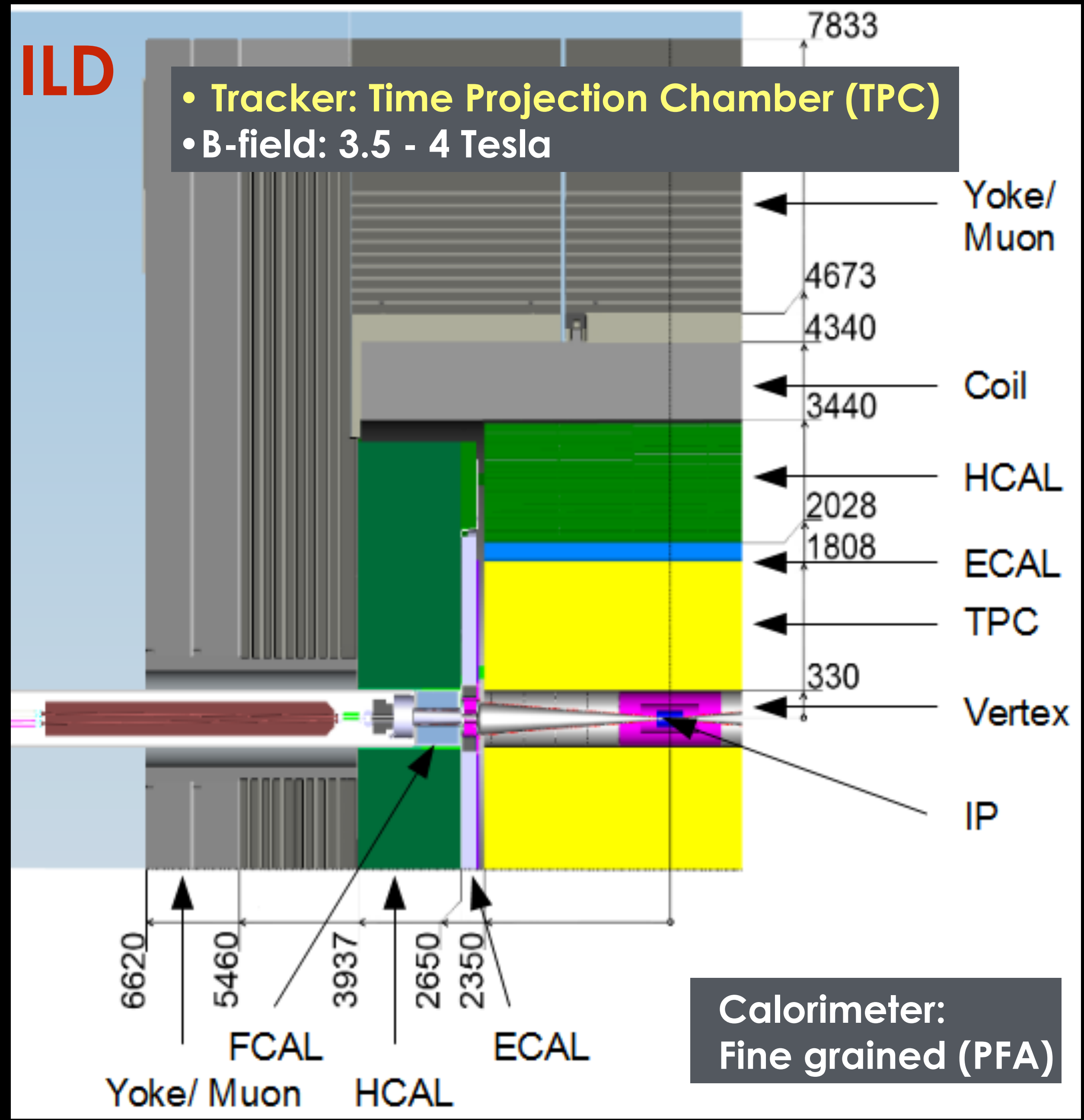
Subsystem	Measurement
Vertex detector	vertex position impact parameter → helps determine flavor
Tracking detector	track momenta of charged particles
ECAL: electromagnetic calorimeter	track momenta of charged particles
HCAL: hadronic calorimeter	energy of γ , e^\pm and hadrons
Magnet system	energy of hadrons (including neutrals)
Muon system	bend charged particles → momentum measurement
Hermicity	identify muons
Luminosity detectors	missing energy (e.g. ν)
	luminosity

Detector Concepts

ILC Detectors

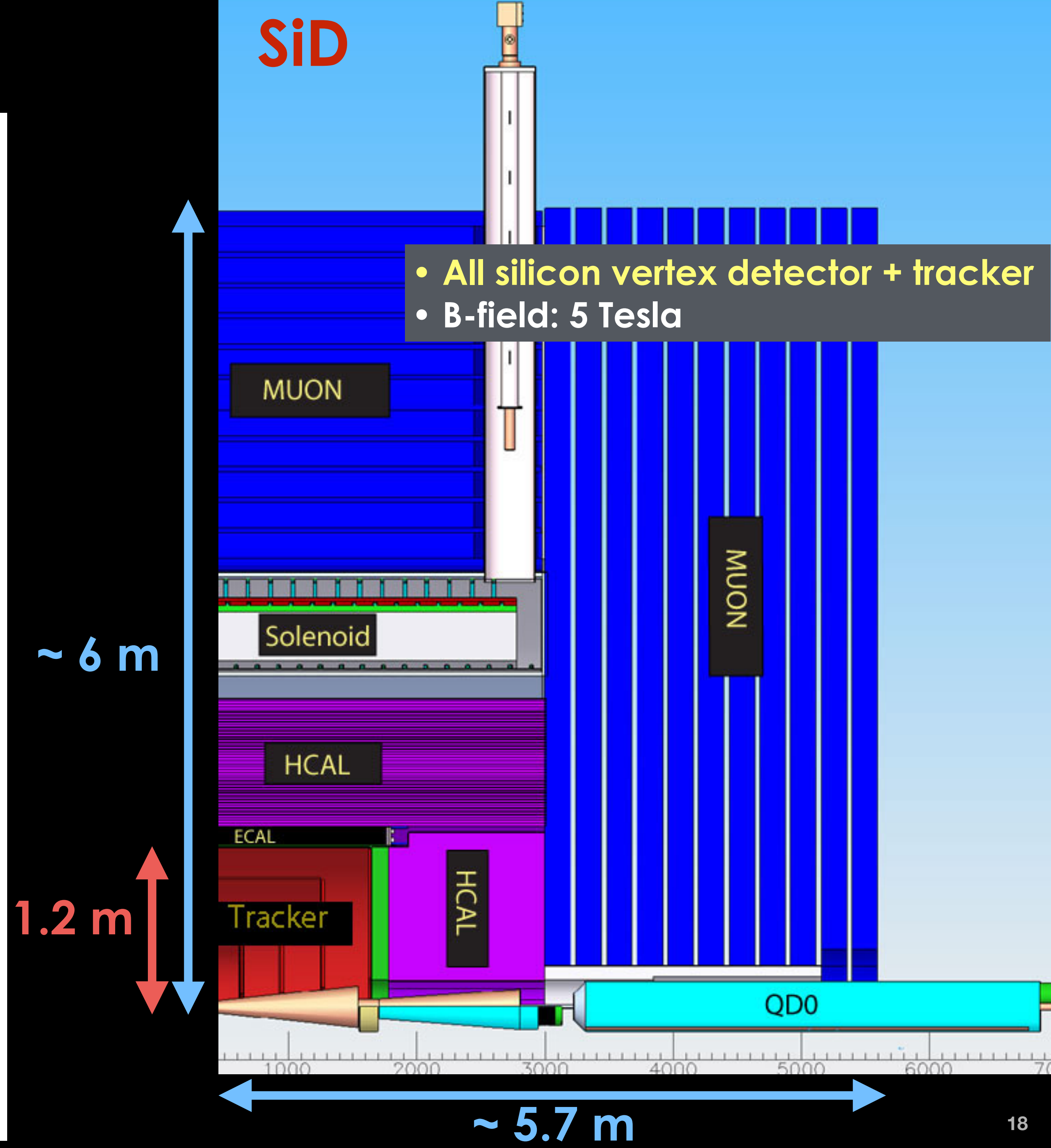
ILD

- Tracker: Time Projection Chamber (TPC)
- B-field: 3.5 - 4 Tesla



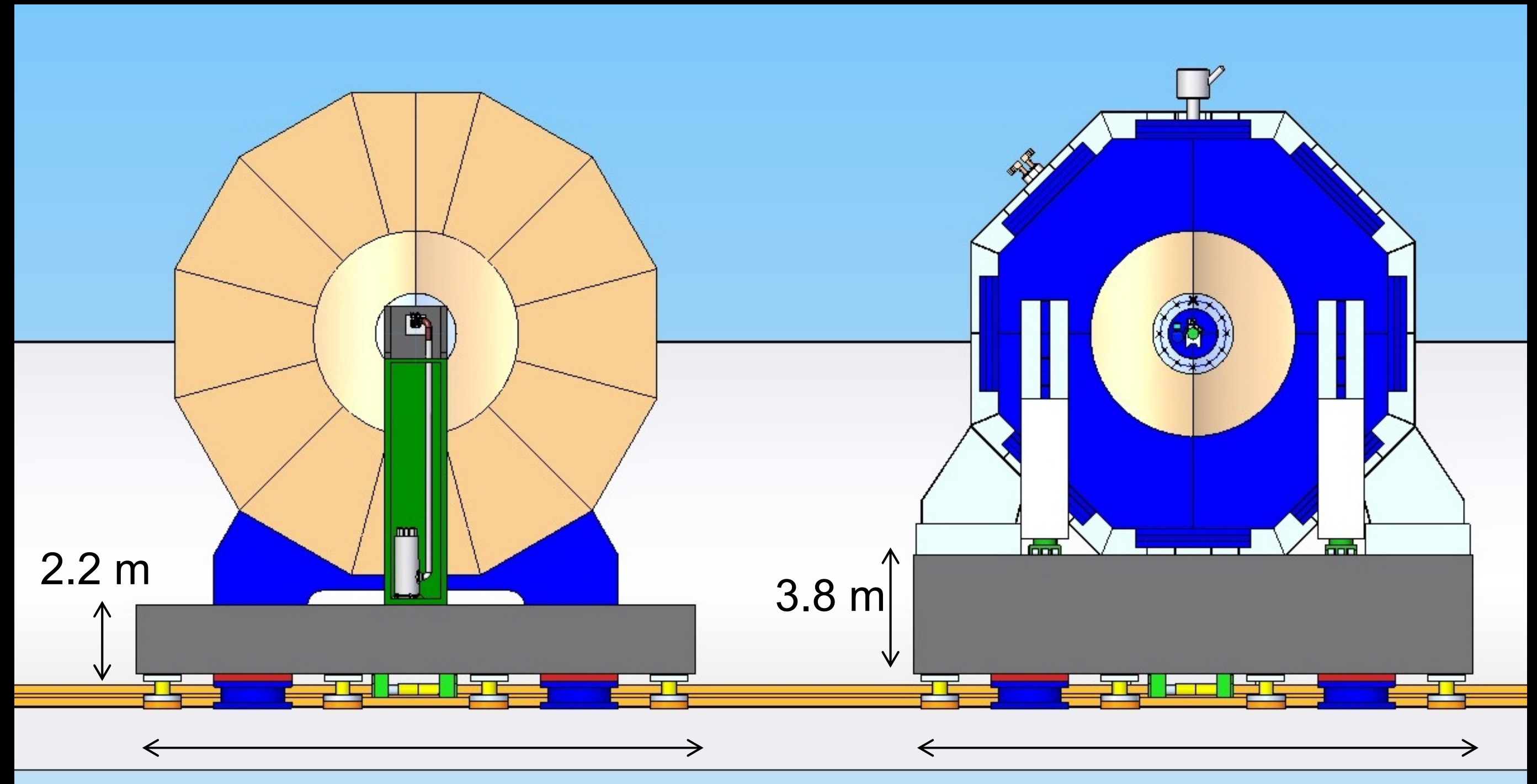
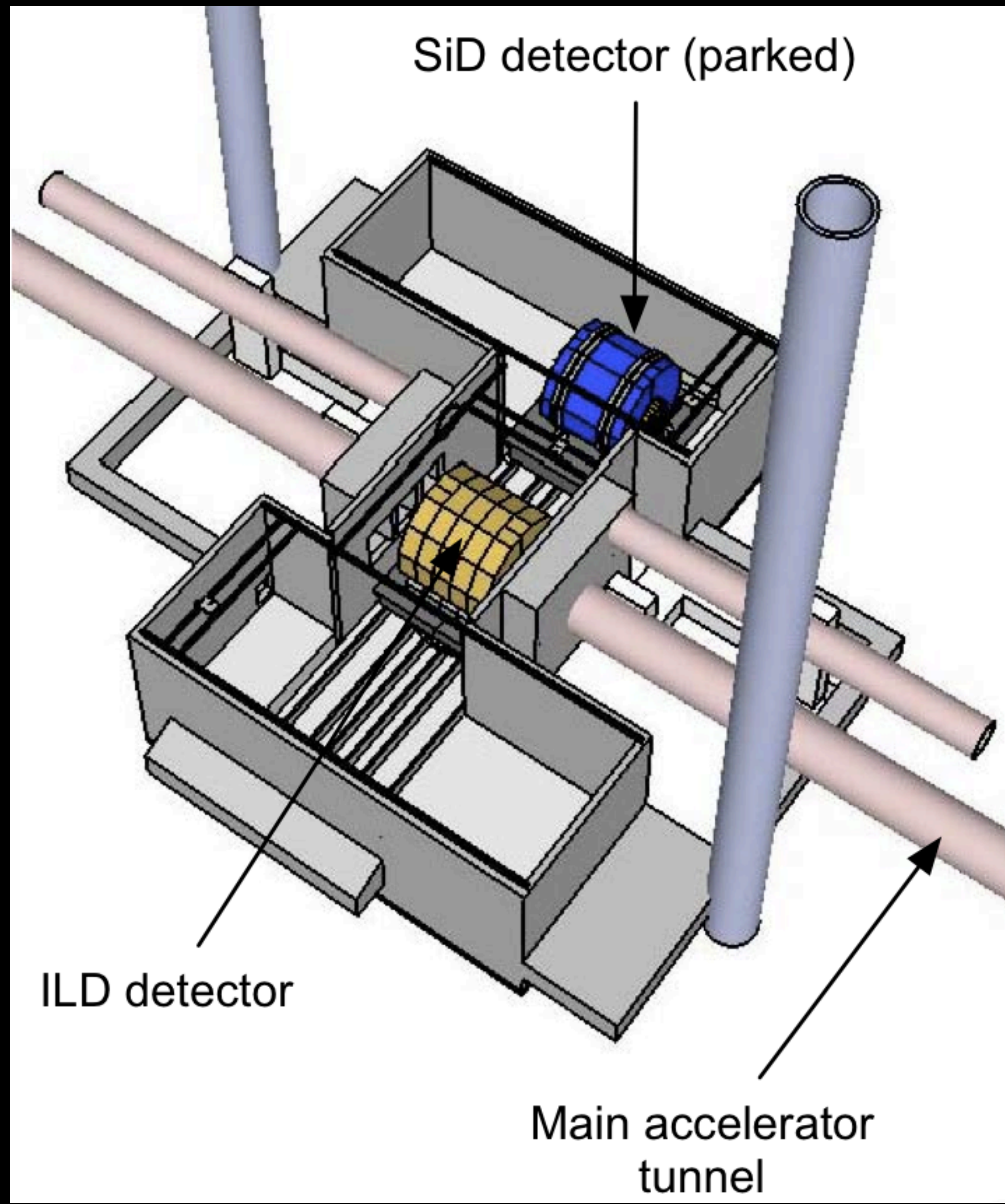
SiD

- All silicon vertex detector + tracker
- B-field: 5 Tesla



ILC detectors: Push-Pull (SiD \leftrightarrow ILD)

Only one interaction point at a linear collider  Swap detectors IN and OUT

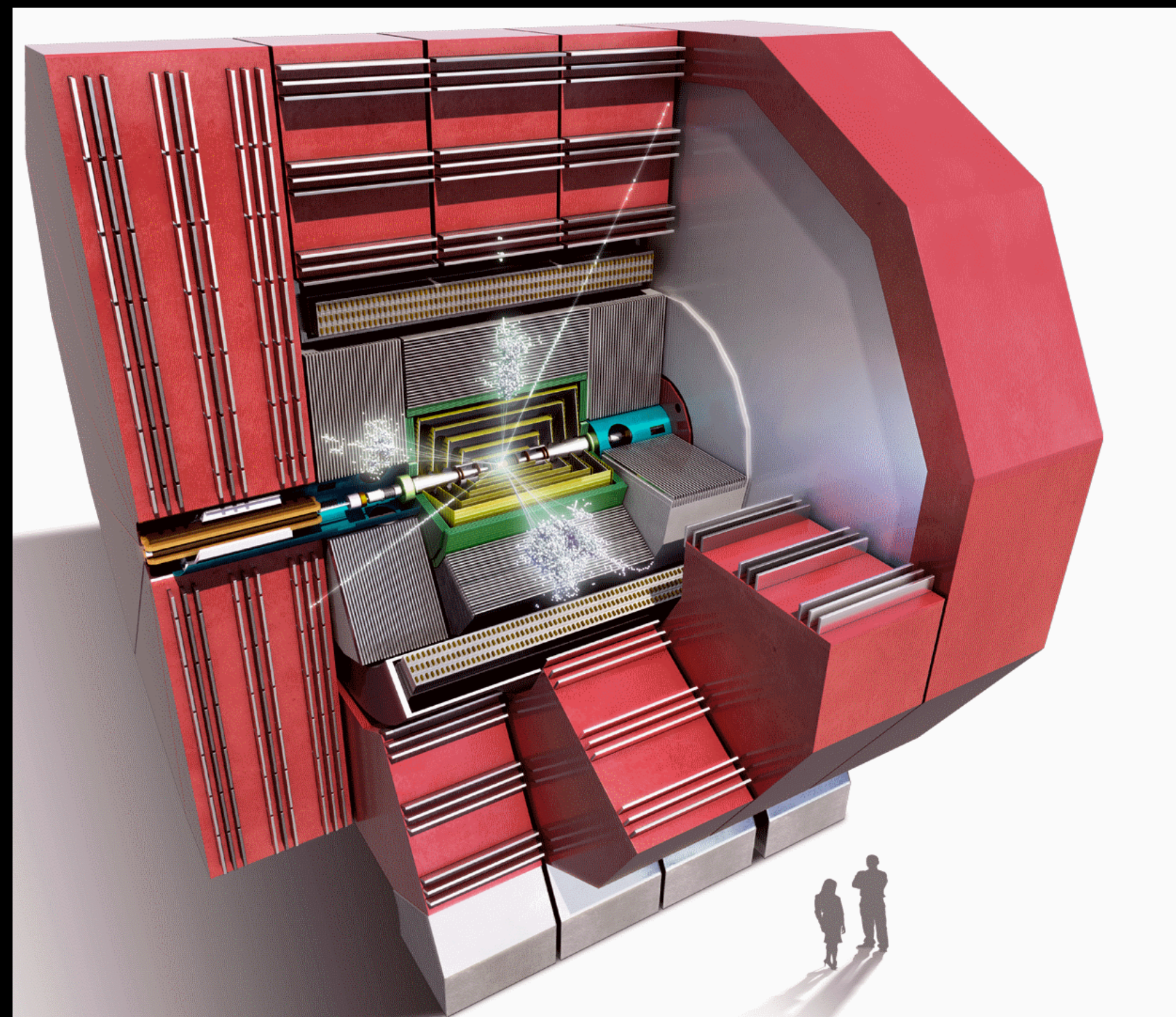


Movable platforms, keeping services connected and allowing fast re-alignment

Full process to take about two days

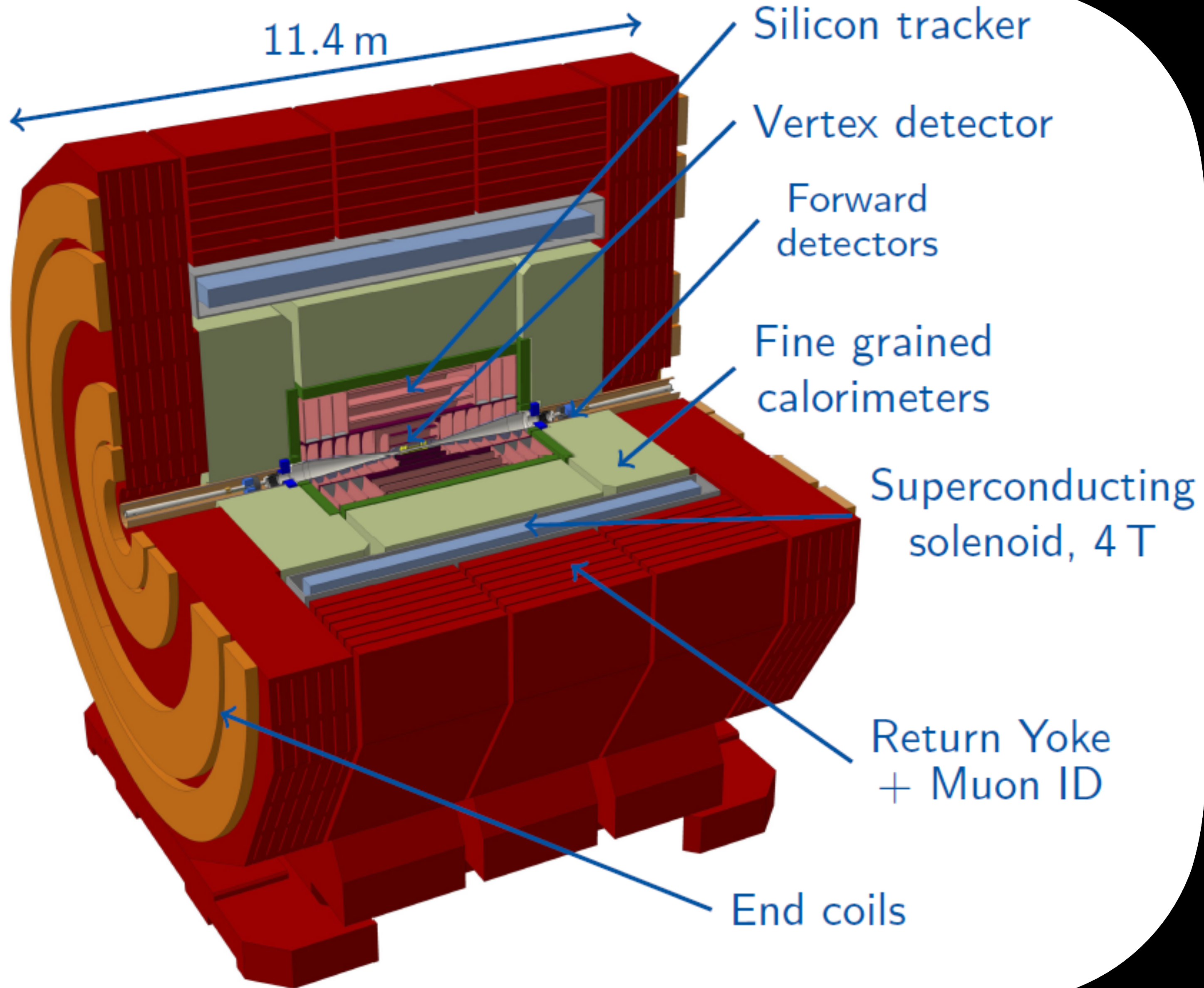
CLIC: CLICdet

SiD/ILD inspired detector



12.8 m

11.4 m



Final focus magnets (QD0)
outside detector:

→ increase HCAL forward acceptance₂₀

• Silicon vertex detector + tracker

• $R = 1.5 \text{ m}$

• B-field: 4 Tesla

• Calorimeter: Fine grained — particle flow analysis

FCC-ee: CLD – CLIC inspired detector

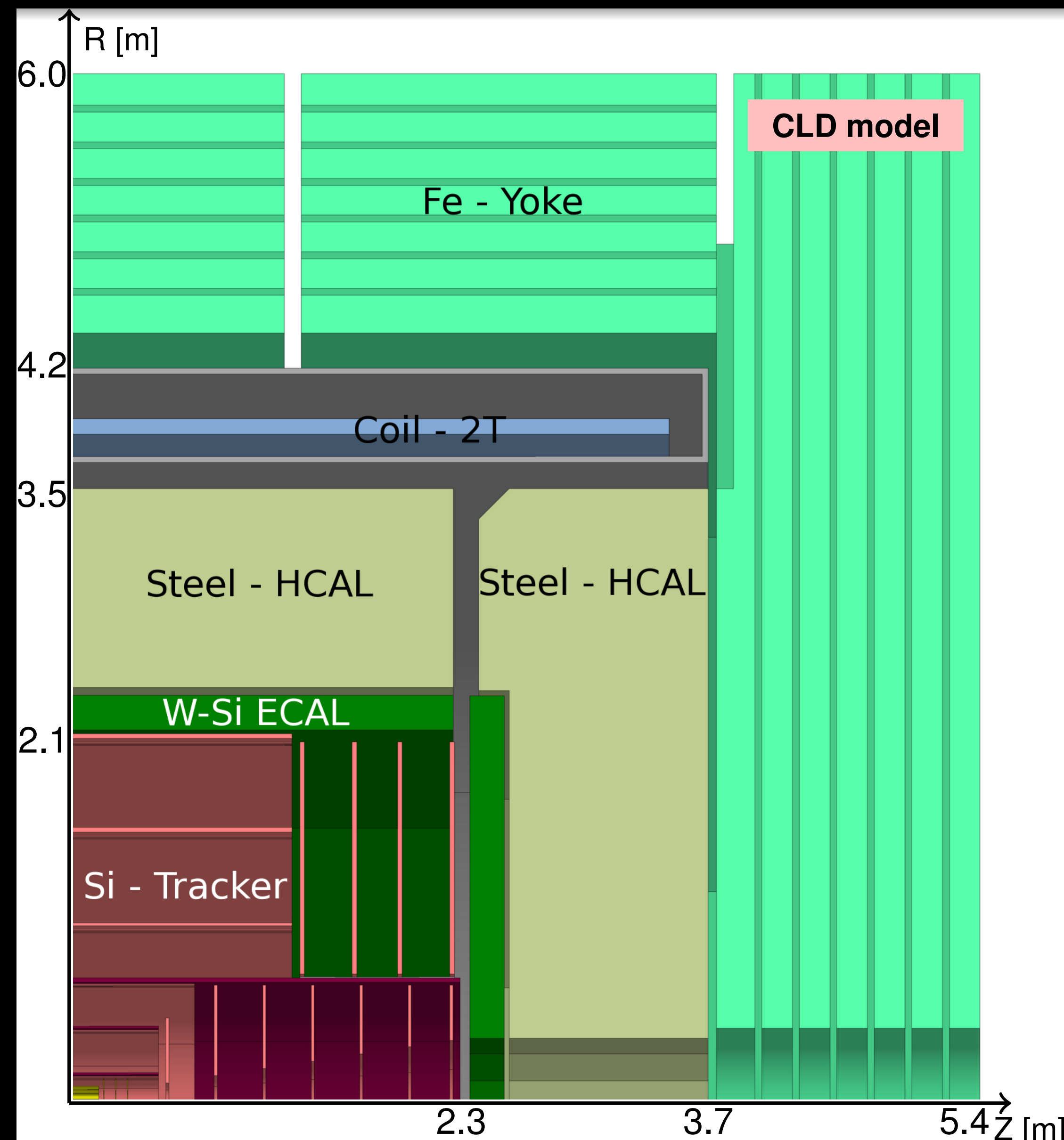
Final focus magnet inside detector: $L^* = 2.2$ m

Lower magnetic field to not disturb beam

Larger tracker radius

Smaller radius HCAL, given lower \sqrt{s}

	CLICdet		CLD
VTX Barrel	31-60 mm	⇒	17-59 mm
VTX Endcap	Spirals	⇒	Disks
Tracker radius	1486 mm	⇒	2100 mm
ECAL thickness	40 layers, $22 X_0$	⇒	40 layers, $22 X_0$
HCAL thickness	60 layers, $7.5 \lambda_I$	⇒	44 layers, $5.5 \lambda_I$
Yoke thickness	1989 mm	⇒	1521 mm
MDI (forward region)		⇒	< 150 mrad
Solenoid field	4 Tesla	⇒	2 Tesla

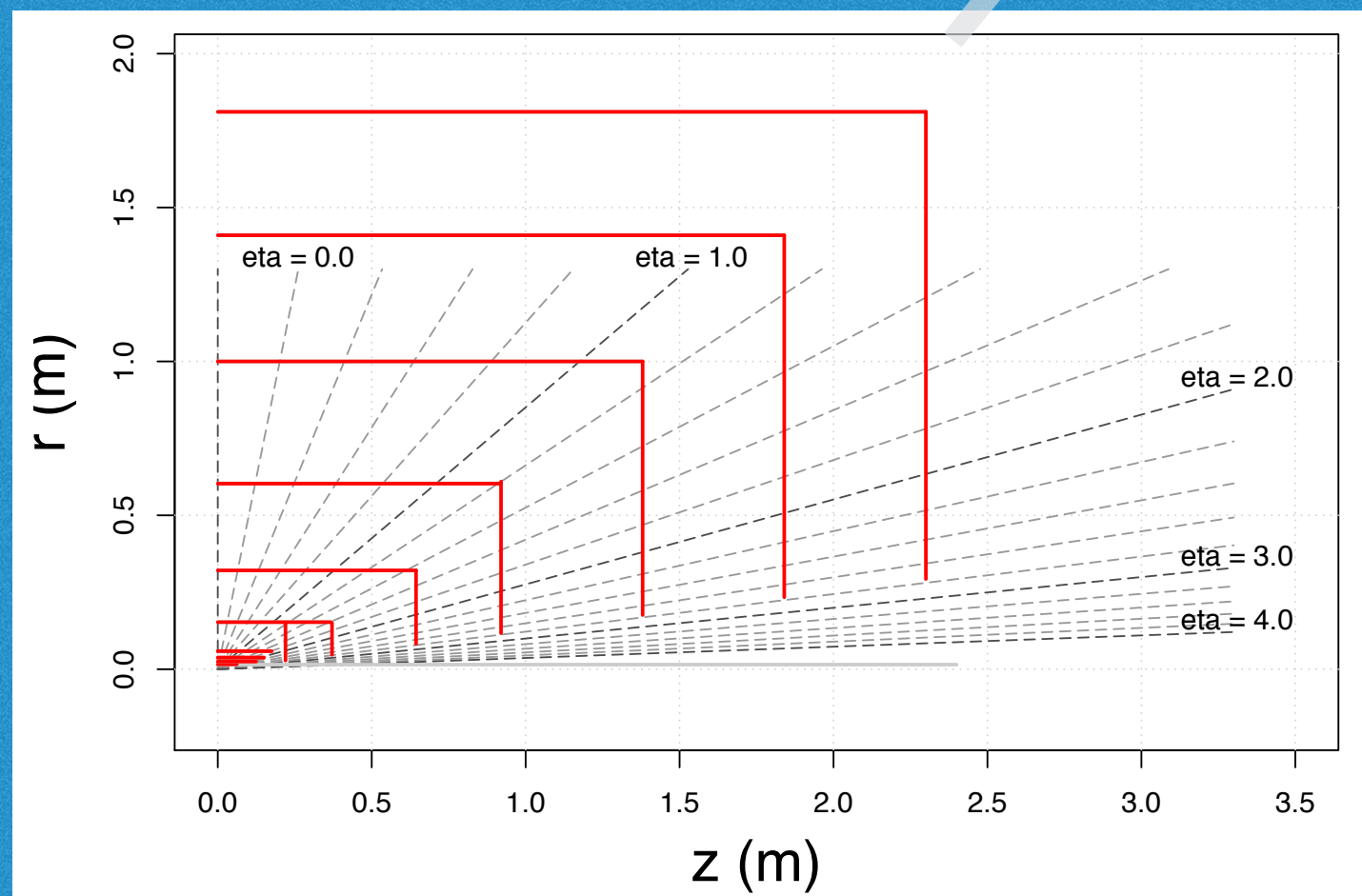
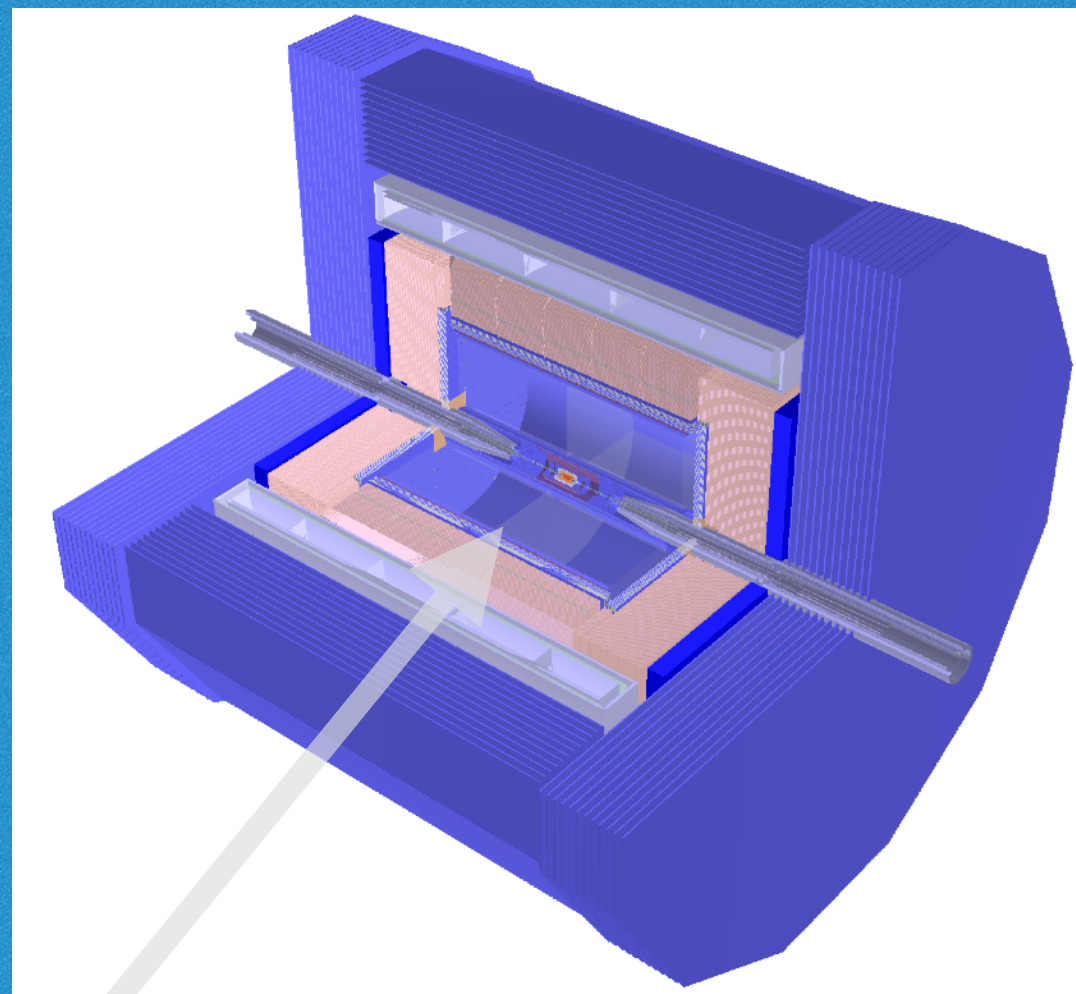


Post-CDR: beam pipe at IP radius reduced from 15 mm to 10 mm

CEPC: 2.5 detector concepts

Particle Flow Approach

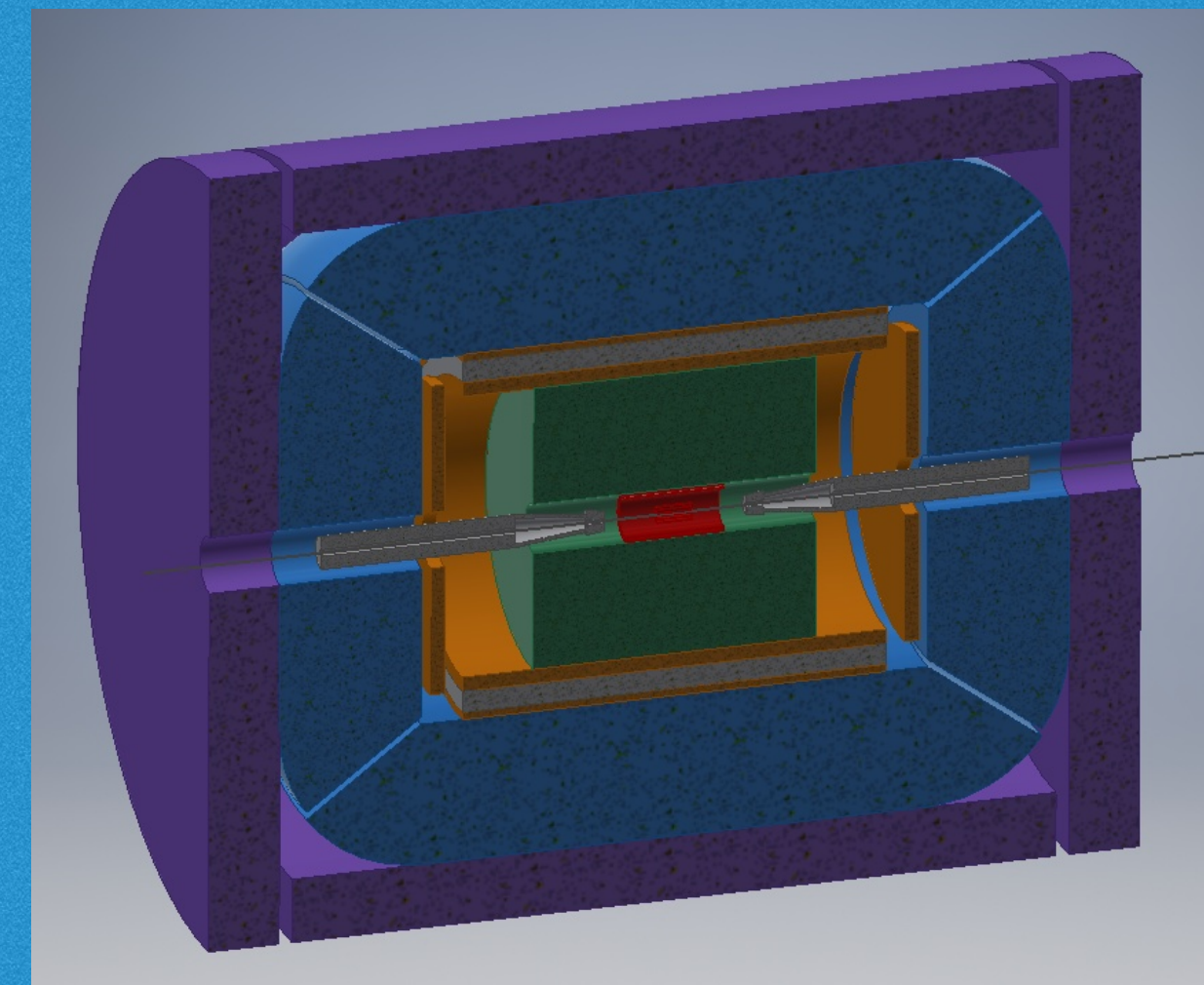
Baseline detector
ILD-like
(3 Tesla)



Full silicon
tracker
concept

CEPC plans for
2 interaction points

Low
magnetic field
concept
(2 Tesla)

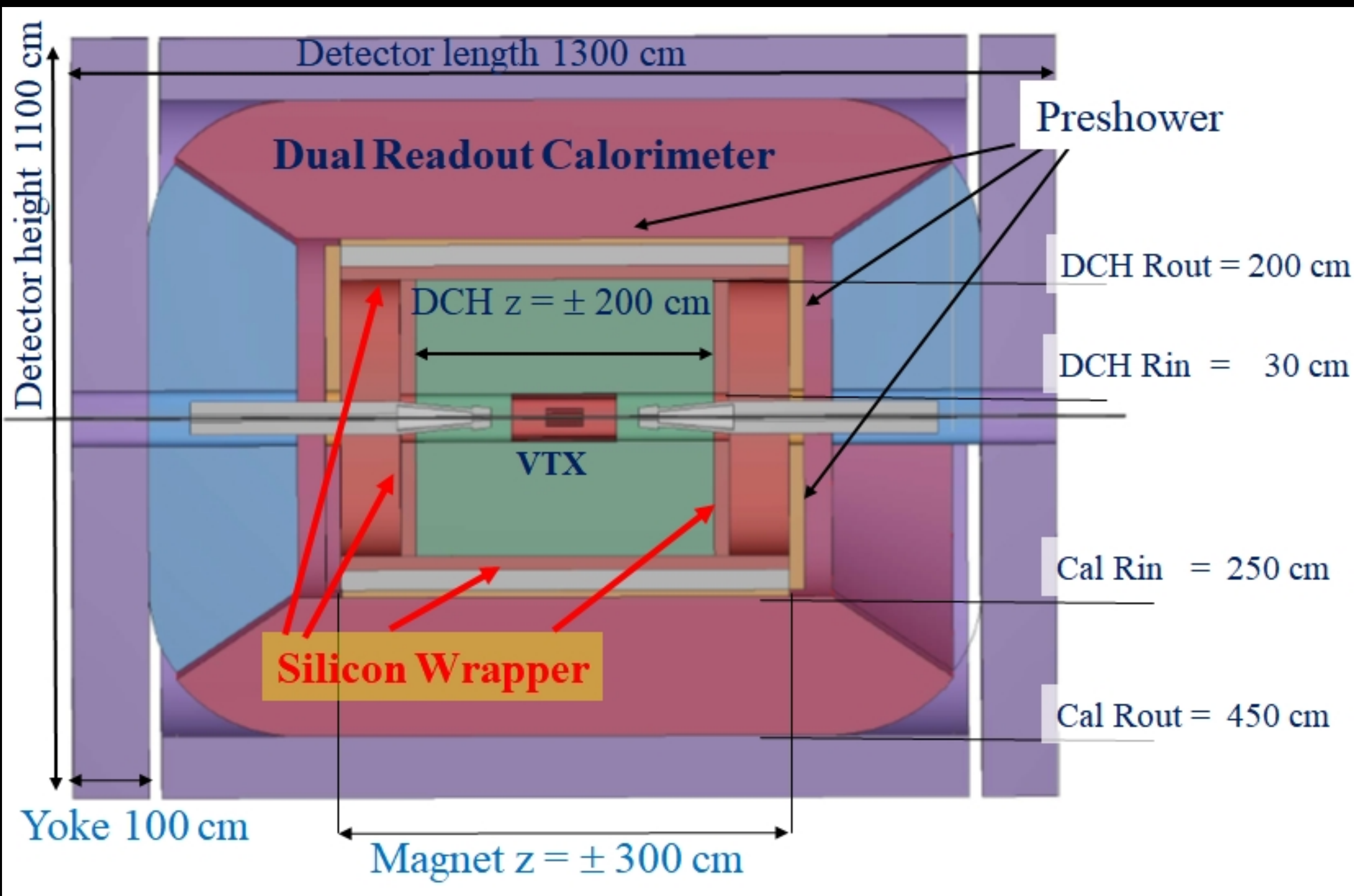


IDEA - also proposed for FCC-ee

Final **two** detectors likely to be a mix and match of different options

CEPC + FCC-ee: IDEA

Only concept with calorimeter outside the coil



Magnet: 2 Tesla, 2.1 m radius

Thin (~ 30 cm), low-mass ($\sim 0.8 X_0$)

Vertex: Similar to CEPC default

* **Drift chamber:** 4 m long; Radius ~ 30 -200 cm, $\sim 1.6\% X_0$, 112 layers

Preshower: $\sim 1 X_0$

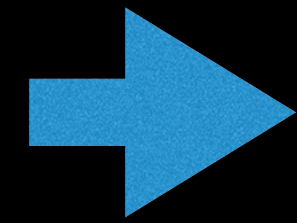
* **Dual-readout calorimeter:** 2 m / $8 \lambda_{int}$

* **(yoke) muon chambers (MPGD)**

Detector Challenges

Machine-detector interface (MDI) in circular colliders

High luminosities



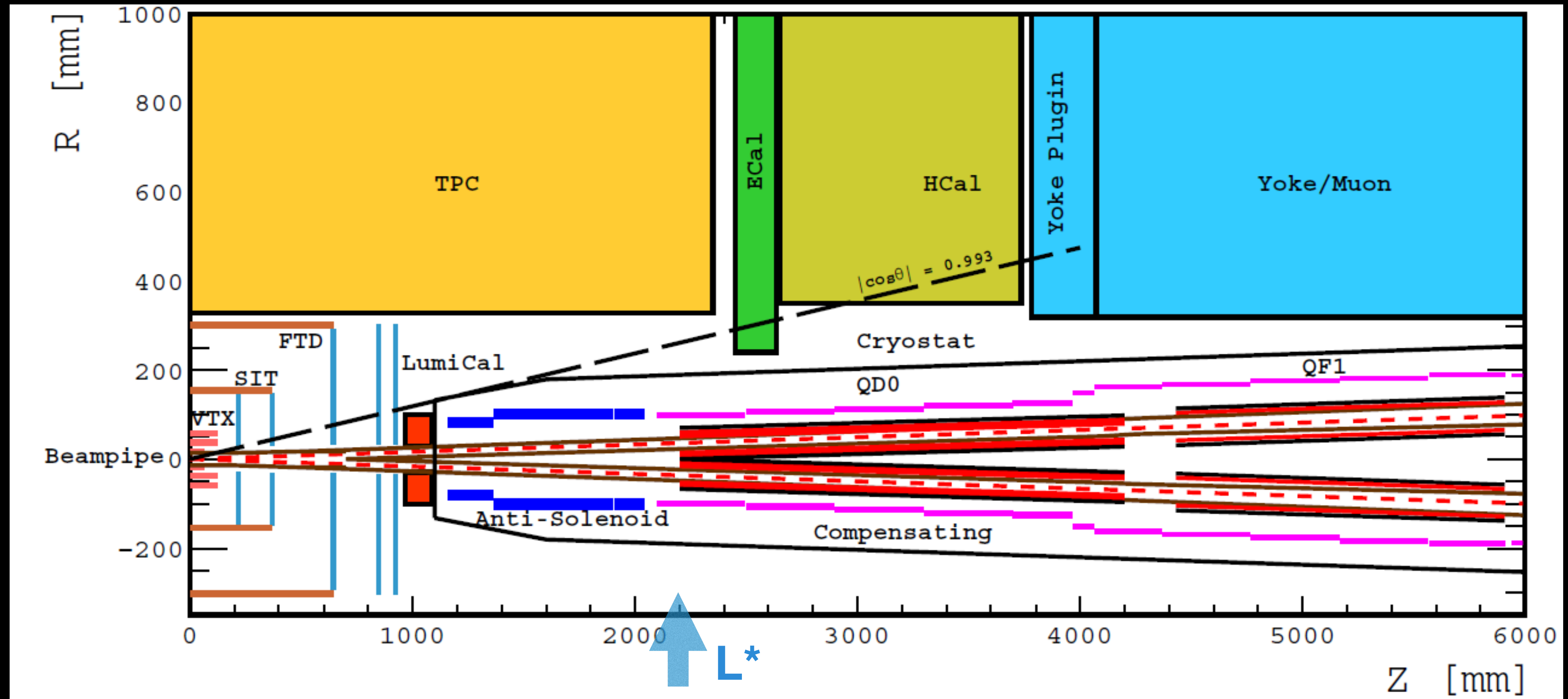
Final focusing quadrupole (QD0) needs to be very close to IP

$L^* = 2.2 \text{ m}$ at FCC-ee and CEPC

Detector acceptance:
 $> \pm 150 \text{ mrad}$

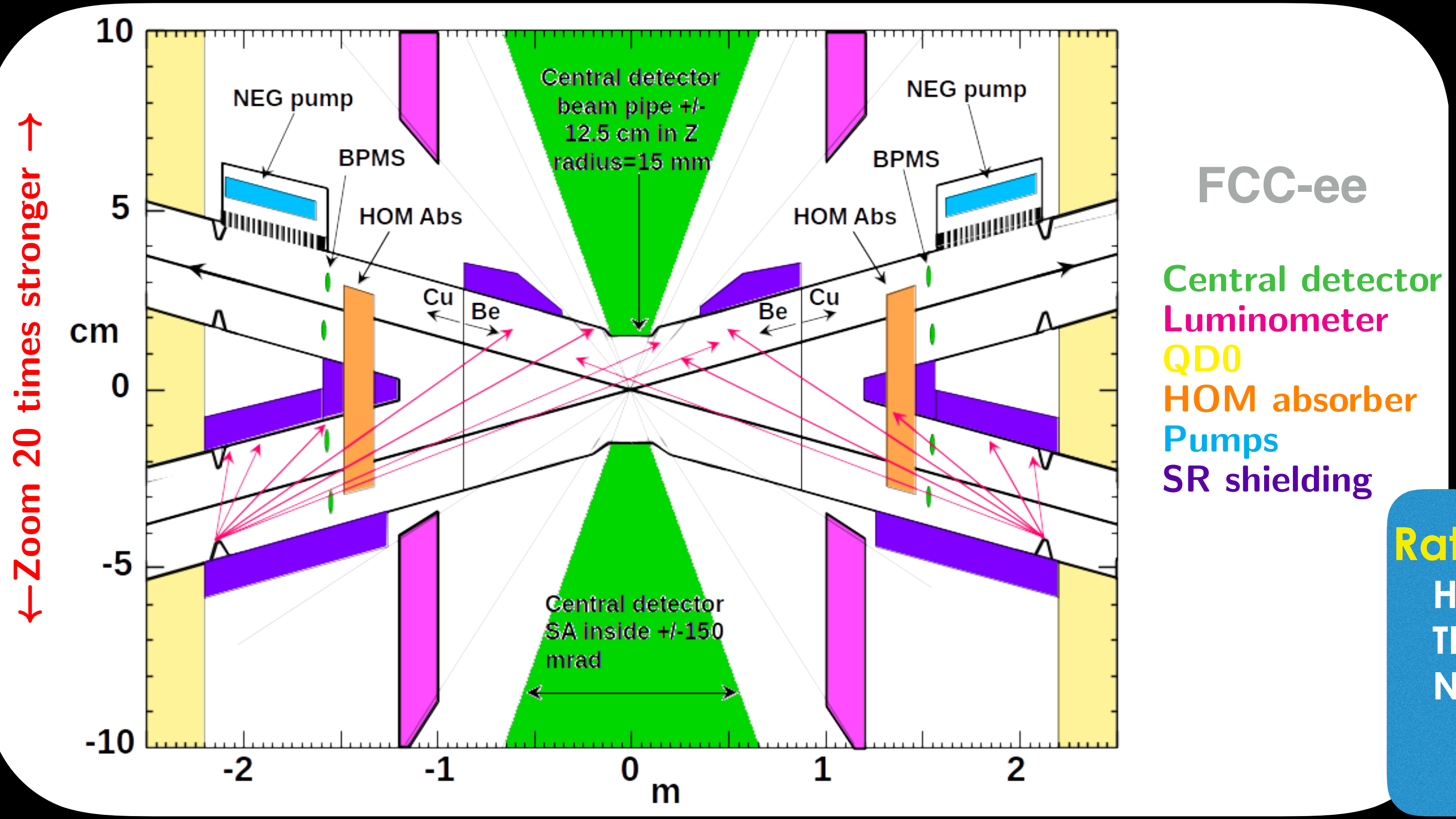
Solenoid magnetic field limited:
2-3 Tesla

due to beam emittance blow up



Synchrotron radiation in circular colliders: Shielding

Shielding added to prevent synchrotron radiation/secondary radiation to enter the detector



Rates at the inner layer (16 mm):

Hit density: ~ 2.5 hits/cm²/BX
TID: 2.5 MRad/year
NIEL: 10^{12} 1MeV n_{eq}/cm²

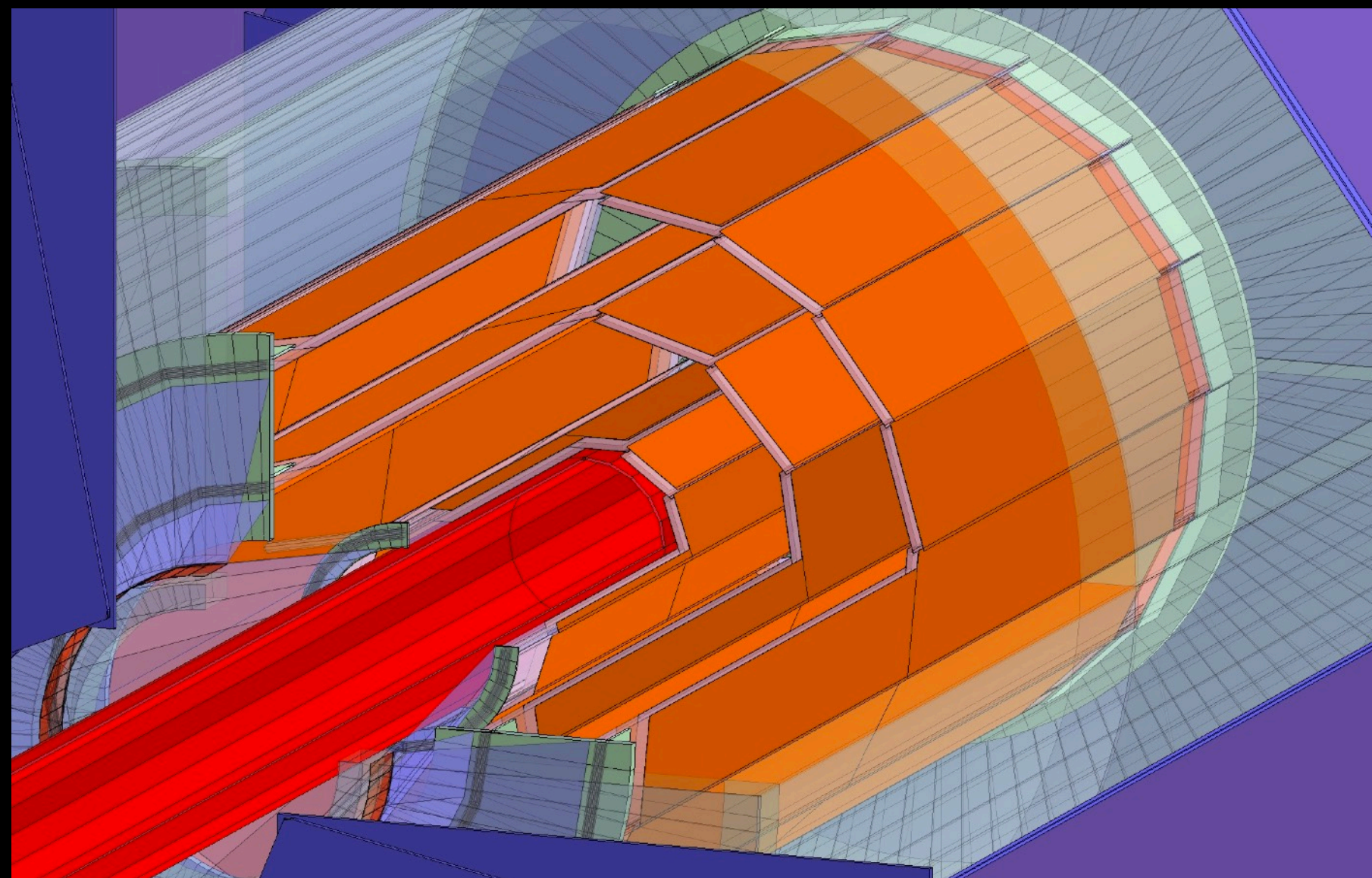
(Safety factors of 10 applied)

Cooling of beampipe needed → increases material budget near the interaction point (IP)

Challenges in vertex detectors

Vertex detector design
driven by needs of **flavor tagging**

- Extremely accurate/precise
- Extremely light



Large surfaces: $\sim 1 \text{ m}^2$

Single point resolution
 $\sigma < 3 - 5 \mu\text{m}$



Pixel pitch
 $\sim 16 - 25 \mu\text{m}$

Low material budget
 $< 0.1 - 0.3\% X_0$ per layer

Thin sensors and ASICs
Light-weight support

Power pulsing (LC)
Air cooling

Low power dissipation
 $\leq 50 \text{ mW/cm}^2$

Time stamping

$\sim 10 \text{ ns}$ (CLIC)

$\sim 30 \text{ ns} - \mu\text{s}$ (ILC/CC)

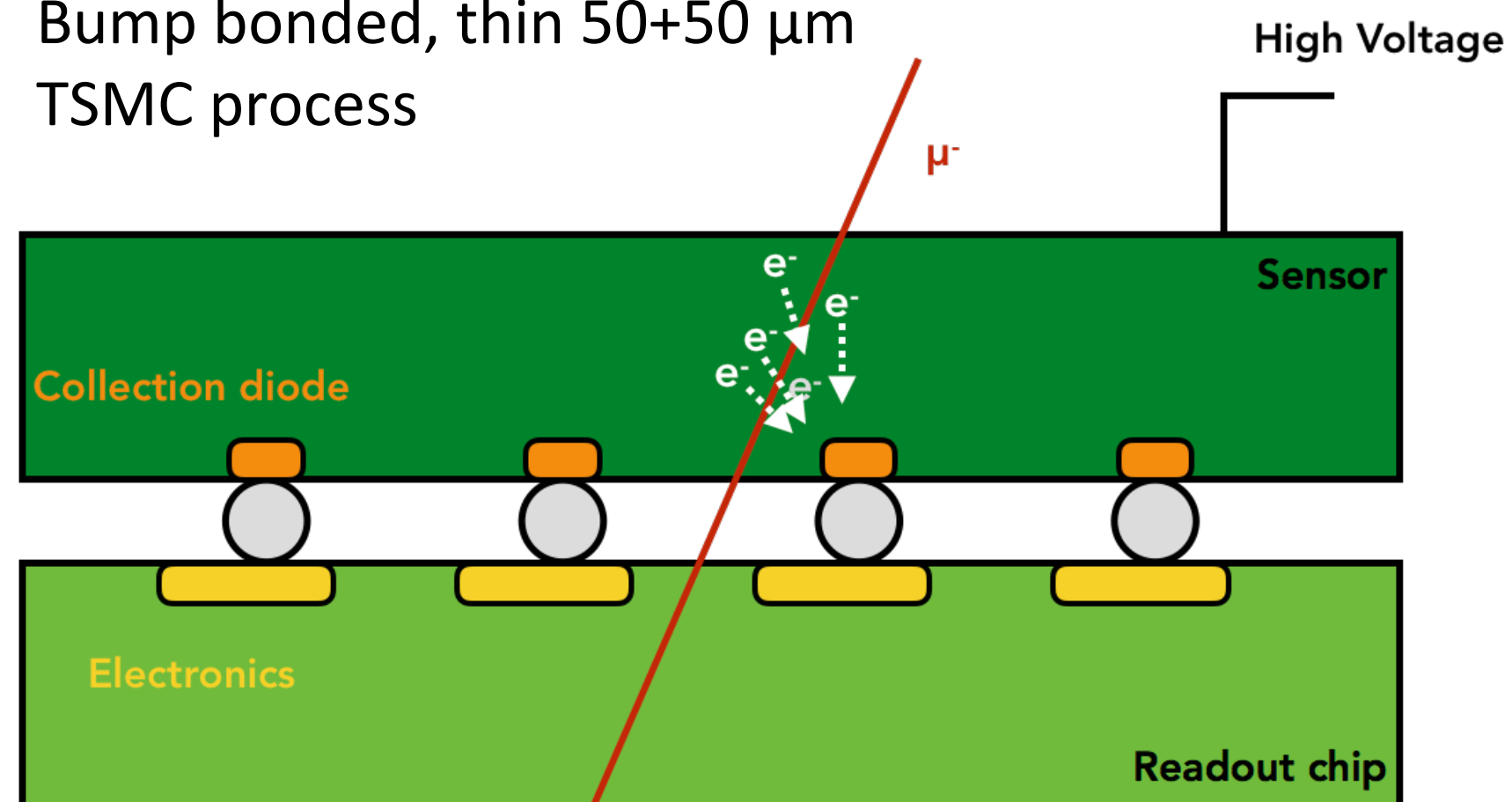
Circular colliders: continuous operation \rightarrow more cooling \rightarrow more material

Silicon pixel-detector technologies

CLICpix
HV-CMOS
hybrid

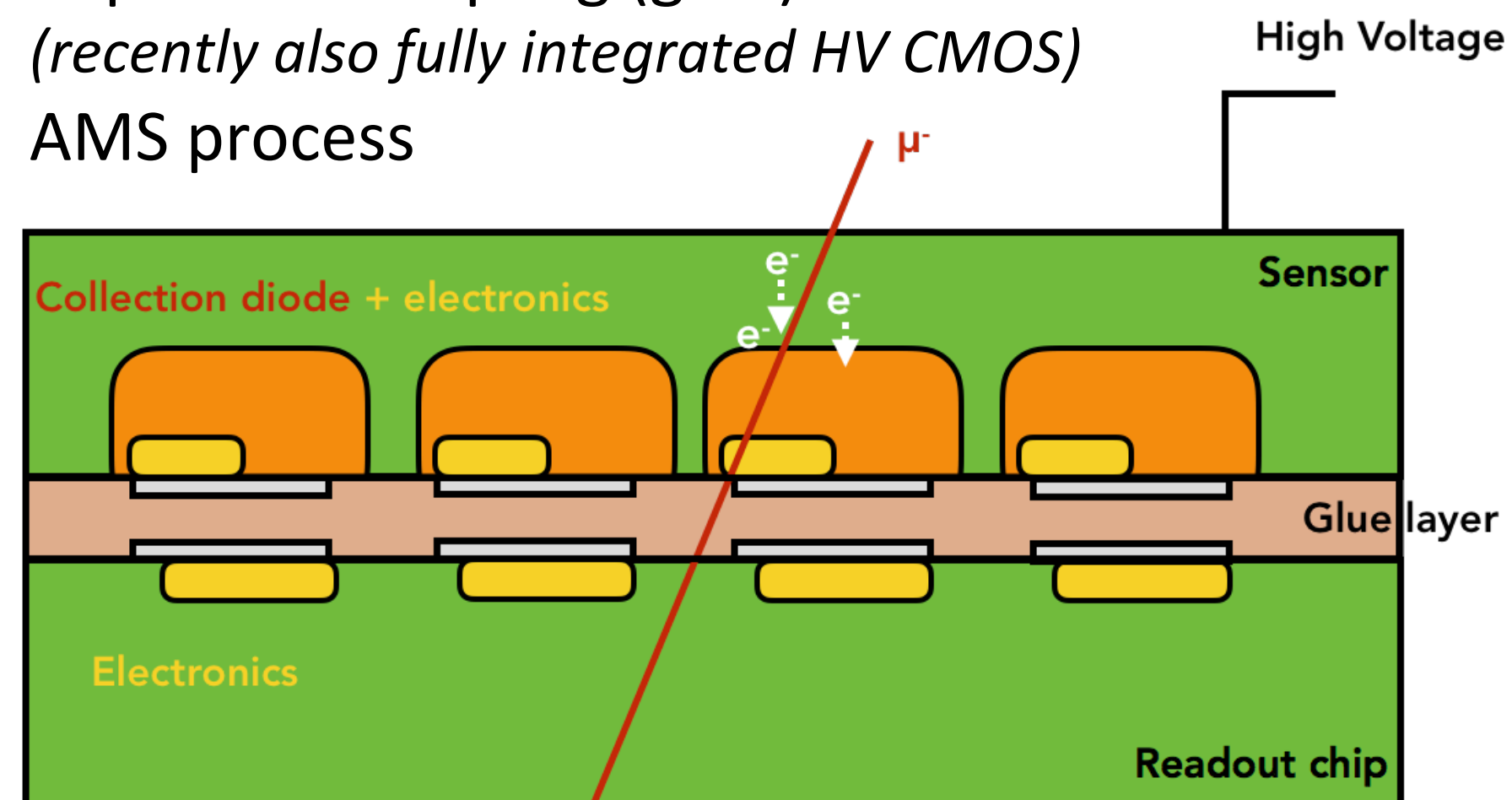
Hybrid: Si sensor + ASIC (65 nm)

Bump bonded, thin 50+50 μm
TSMC process



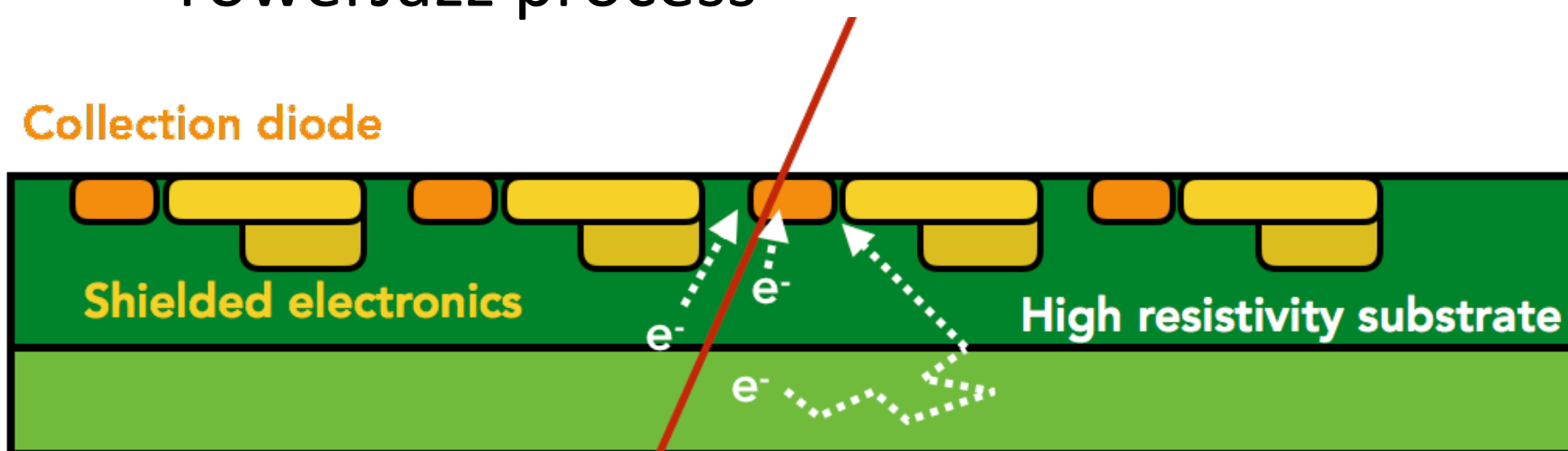
Hybrid: HV CMOS active sensor + ASIC (65 nm)

Capacitive coupling (glue)
(recently also fully integrated HV CMOS)
AMS process



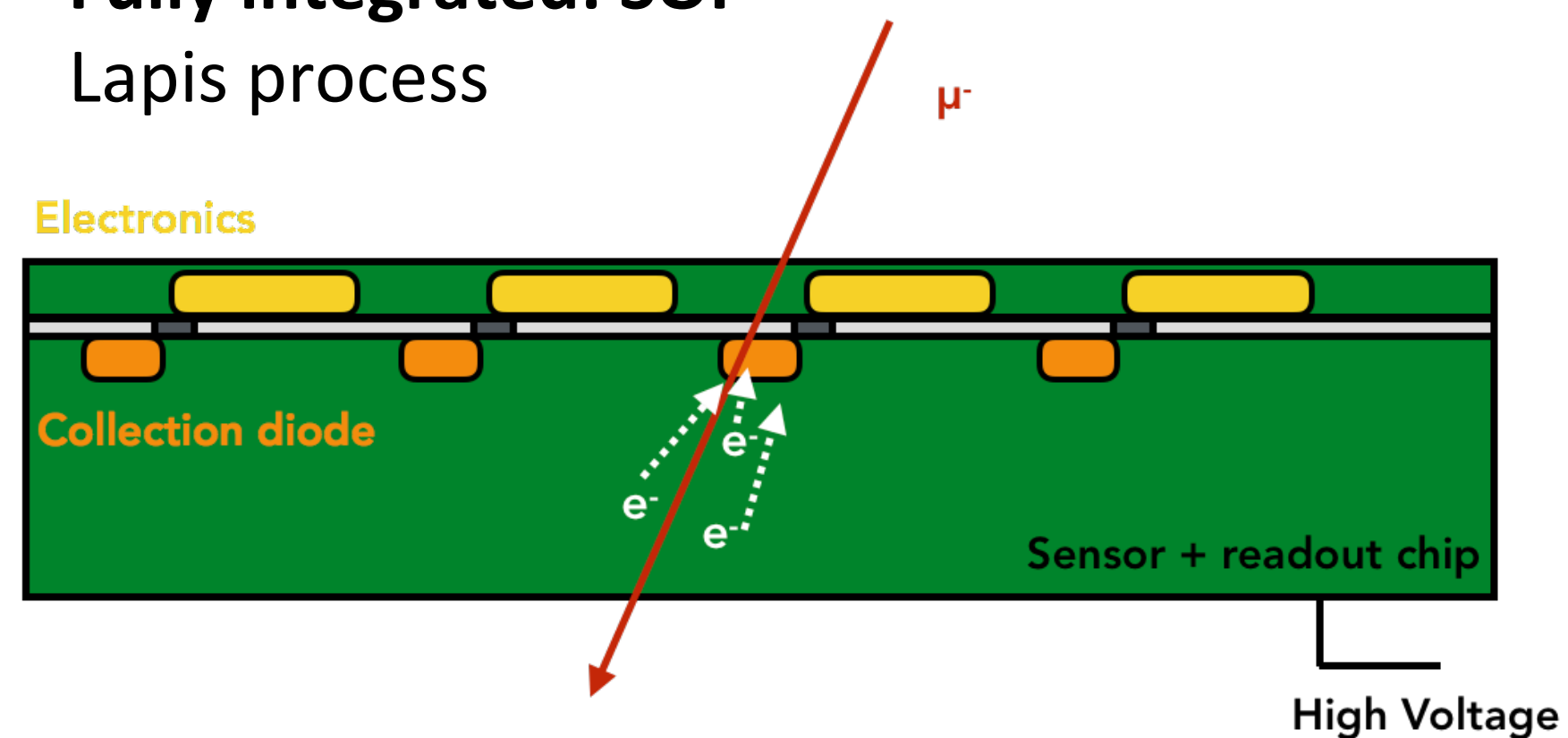
Fully integrated: HR CMOS

TowerJazz process



Fully integrated: SOI

Lapis process



SOI
Silicon
-On
-Insulator

MAPS
HV-CMOS
HR-CMOS
Mimosa CPS

Systematics R&D studies have focused on Pixel implementation, with Pixel sizes around $25 \times 25 \mu\text{m}^2$
Studies equally valid for the main tracker, even though it will have larger cell sizes

Monolithic Active Pixel Sensor (MAPS)

Fully Integrated CMOS Technology

- ◆ CMOS Image Pixel Sensors —> benefit from industrialization
 - Commercial process (8" or 12" wafers)
 - Multiple vendors
 - Potentially cheaper interconnection processes available
 - Thin sensor (50–100 μm) have less material

Early Generations

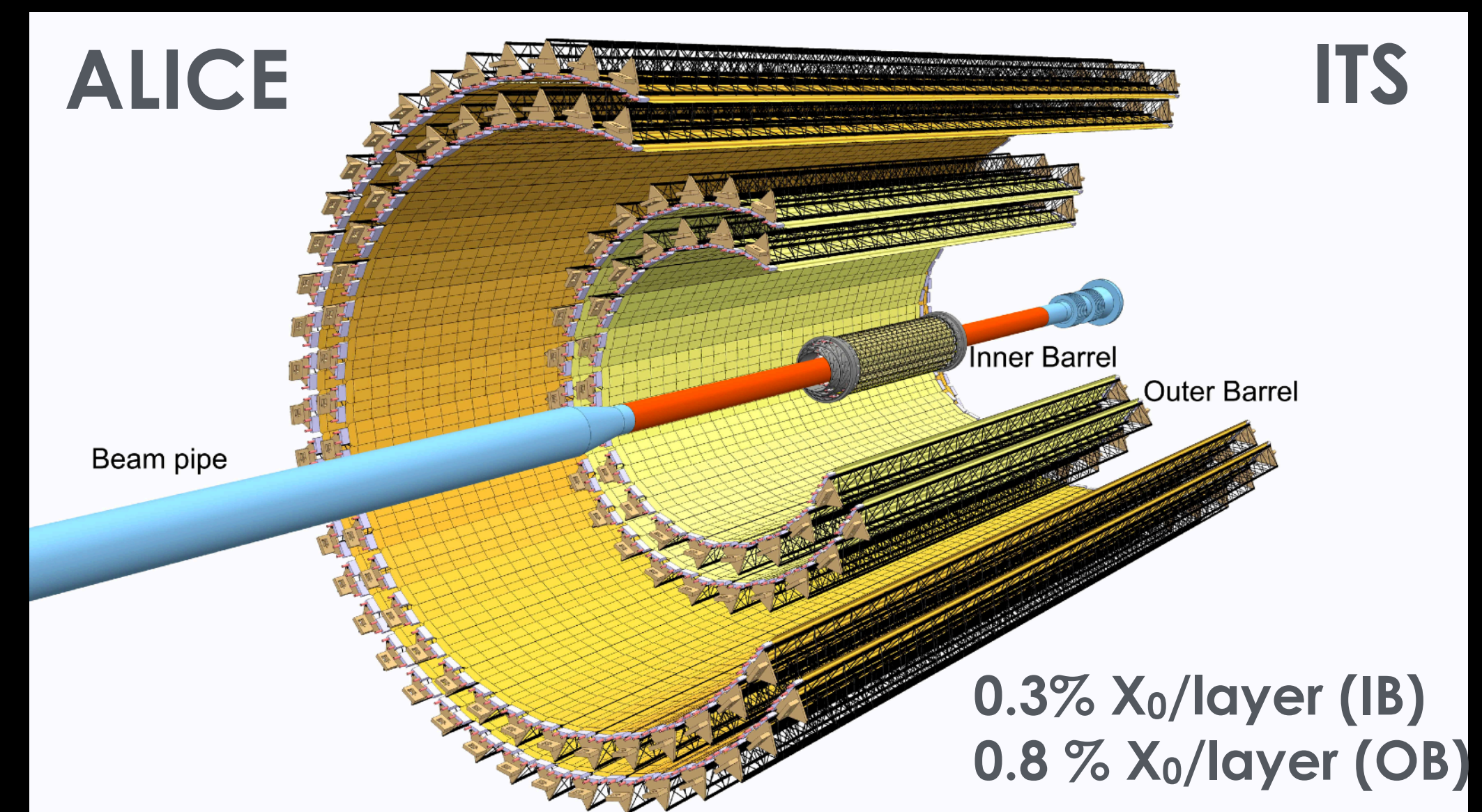
- ◆ Charge collection mainly by diffusion
- ◆ Timing limited by rolling–shutter readout (μs)

Recent advances

- ◆ Moving towards smaller feature size (TowerJazz 180 nm)
- ◆ Promising timing performance

Successfully deployed in HEP, with increasingly demanding requirements:

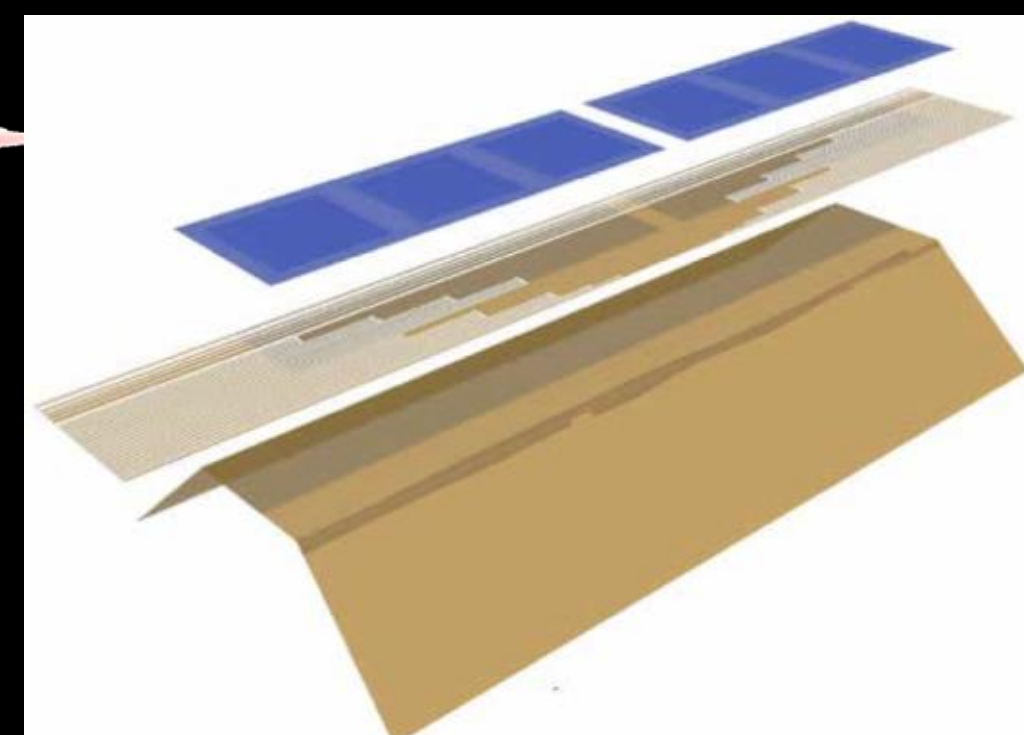
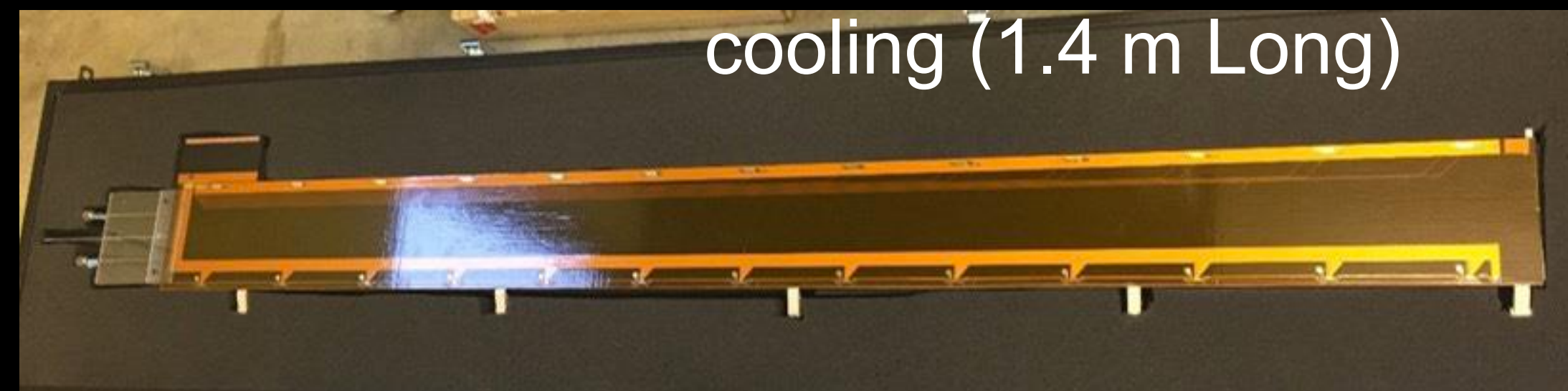
- Test-beam telescopes
- STAR @ RHIC
- CBM MVD @ FAIR
- ALICE ITS upgrade
- Baseline technology for **ILD VTX**, under study for **CEPC** and **CLIC**



MATERIAL REDUCTION

ATLAS ITK module support structure with copper-Kapton co-cured tape and embedded CO2 cooling (1.4 m Long)

- Non conventional use of Carbon Fibre Reinforced Plastic (CFRP) materials for Vertex Detectors to match the requirement of minimum material budget, high rigidity, thermal management.



- 50 μm DMAPS
- 25 μm Kapton Flexprint
- 50 μm Kapton support frame
- < 1‰ Radiation length



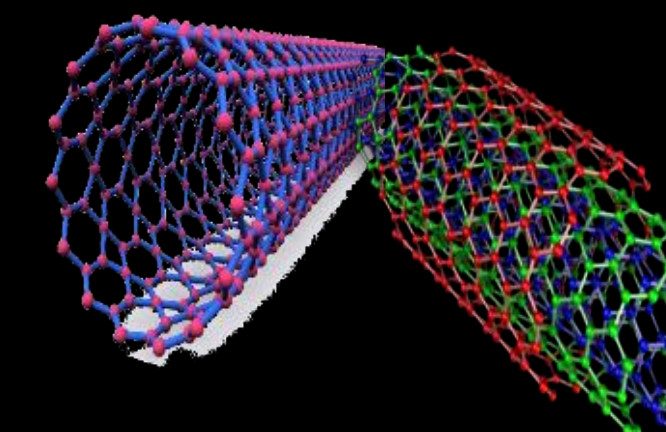
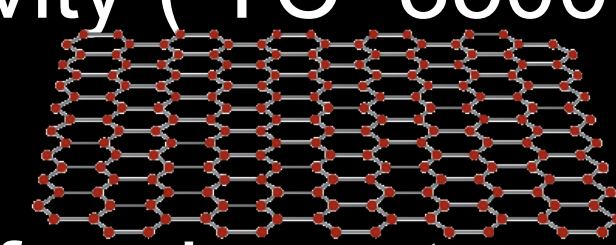
Carbon Nanotubes

Allotrope of carbon with a cylindrical nanostructure
Very high Thermal Conductivity (TC=3500 W/mK)

Graphene

One atomic-layer thin film of carbon atoms in honeycomb lattice. Graphene shows outstanding thermal performance, the intrinsic TC of a single layer is 3000-5000 W/mK

High thermal conductive carbon nanotube



Challenges in **tracking** detectors

Goal: very good momentum resolution, with preferably good PID capabilities

Different detectors, each with large $B \times R^2$

- **SiD, CLICdet, CEPC:** all silicon tracker
- **ILD, IDEA, CEPC:** silicon + gaseous tracking

Silicon tracker challenges

Large surface area of $O(100 \text{ m}^2)$

Solution: Integrated sensors with large pixels/strips ($\sim 30 \mu\text{m} \times 1\text{-}10 \text{ mm}$)

Maintain efficiency and good timing
(despite large detector area)

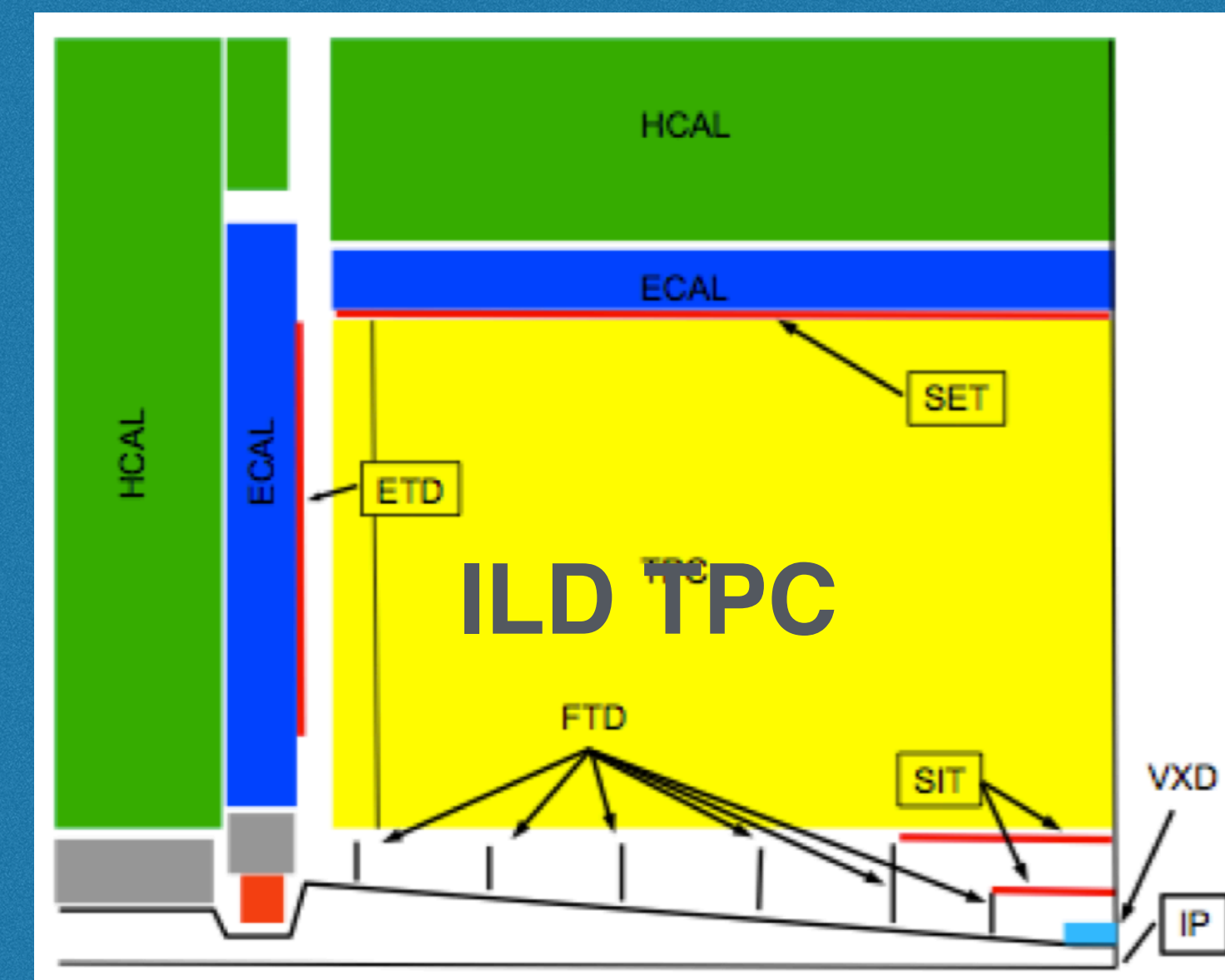
Mechanical stiffness
with low-mass materials

Light-weight cooling methods

Gas detector challenges

Hit timing and momentum resolution

Solution: Silicon wrapper around detectors

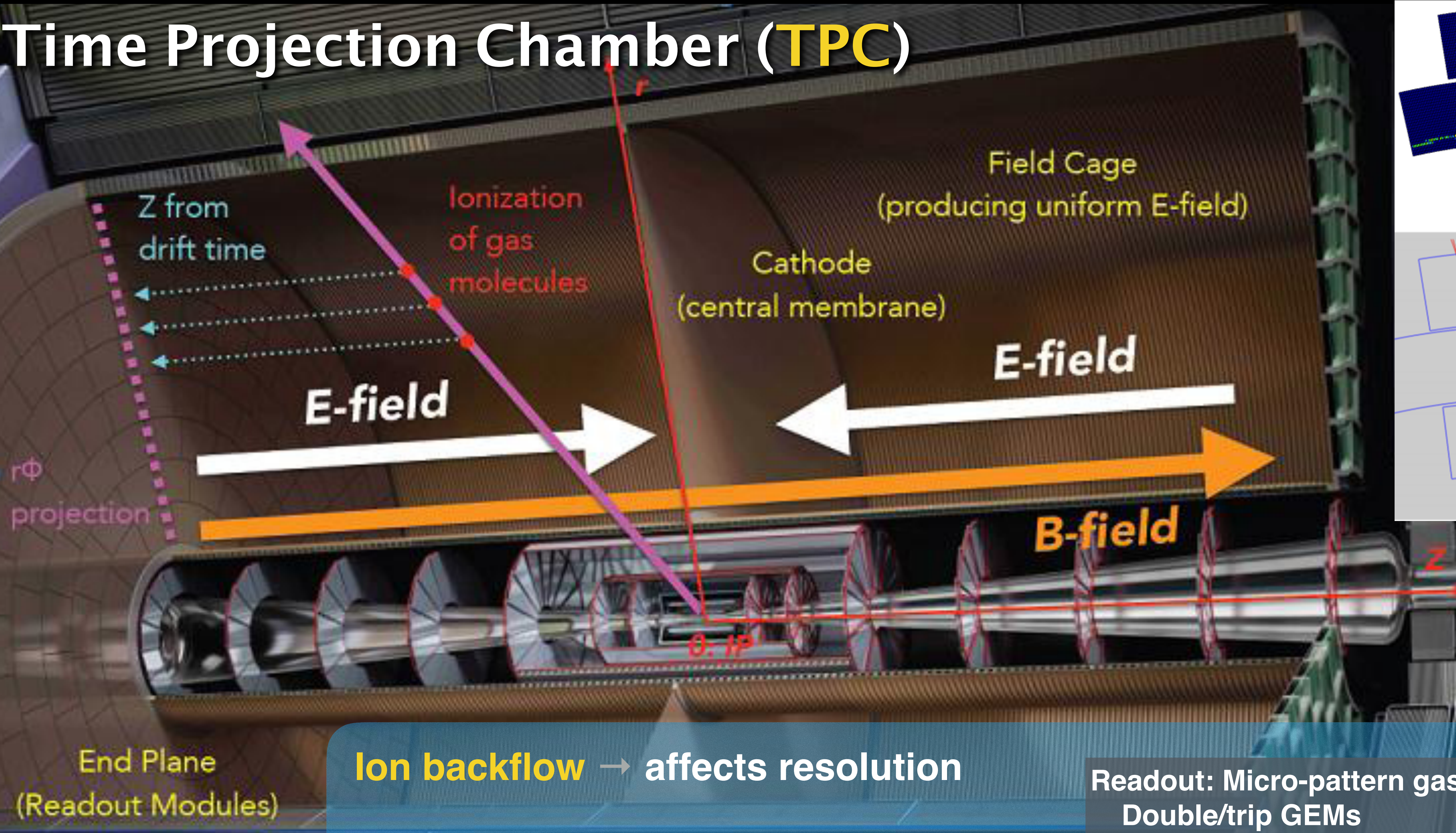


Occupancies at high event rates

Meets requirements for ILC

Under study for Z-pole running at CEPC

Time Projection Chamber (TPC)



Ion backflow → affects resolution

Solution: Gating concepts and new readout modules under study

Readout: Micro-pattern gas detectors
Double/trip GEMs
Resistive micromegas
Integrated pixel readout

Particle flow calorimeters (ILC, CLIC, CEPC and FCC-ee)

3%-4% jet energy resolution reachable with **Particle Flow Analysis (PFA)**

Average jet composition

60% charged particles

30% photons

10% neutral hadrons

Use best information

60% tracker

ECAL

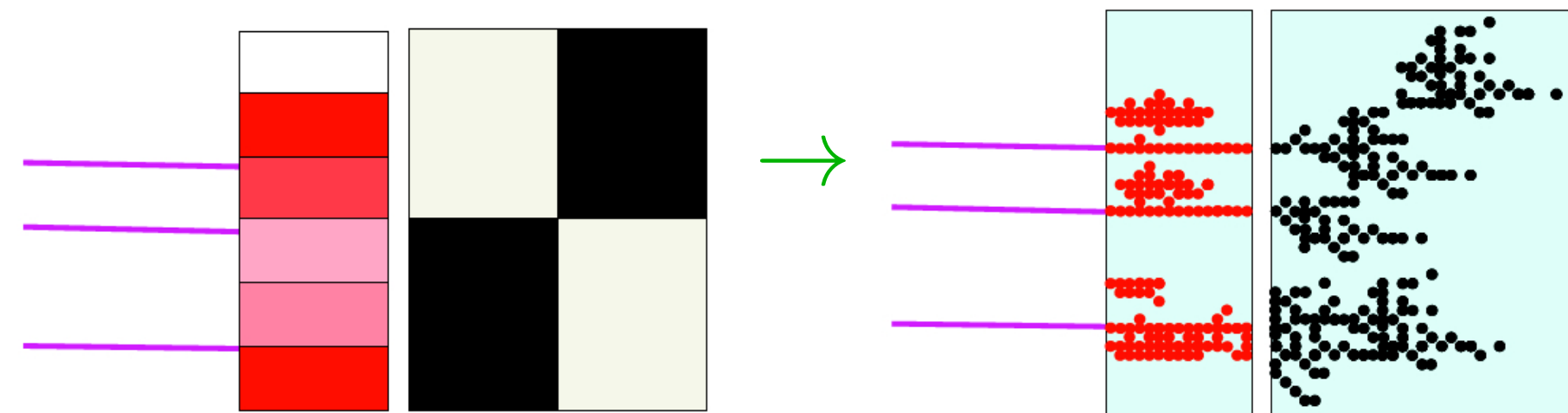
HCAL

Full detector solution

Particle Flow Analysis: Hardware + Software

- **Hardware:** Resolve energy deposits from different particles

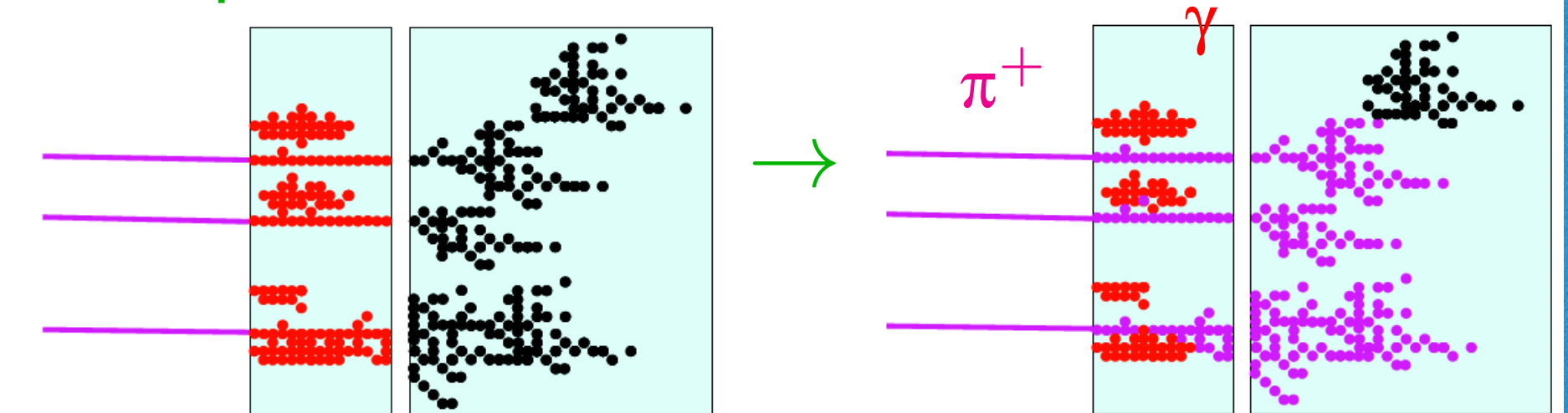
→ High granularity calorimeters



$$E_{\text{jet}} = E_{\text{ECAL}} + E_{\text{HCAL}}$$

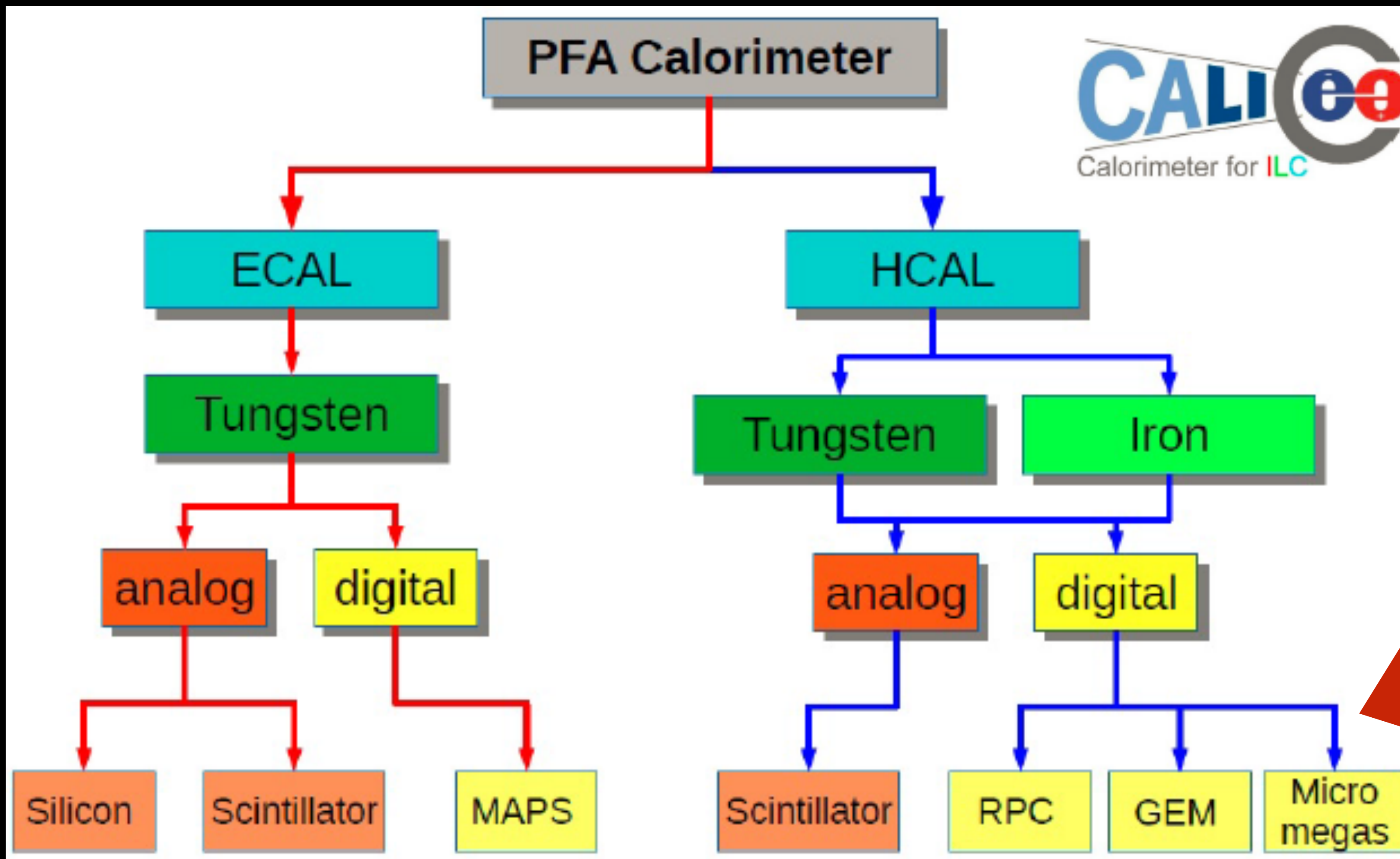
- **Software:** Identify energy deposits from each individual particle

→ Sophisticated reco. software



$$E_{\text{jet}} = E_{\text{track}} + E_{\gamma} + E_n$$

Particle Flow calorimeter options



Detector challenges:

- Compact design
- Calibration of channels
- Cooling
- Cost

Scintillator tiles/strips
(here $3 \times 3 \text{ cm}^2$) + SiPMs



Test beam experiments at DESY, CERN, FNAL: 2006 - 2015

First physics prototypes of up to $\sim 1 \text{ m}^3$, $\sim 2 \text{ m}^3$ (with Tail Catcher Muon Tracker)

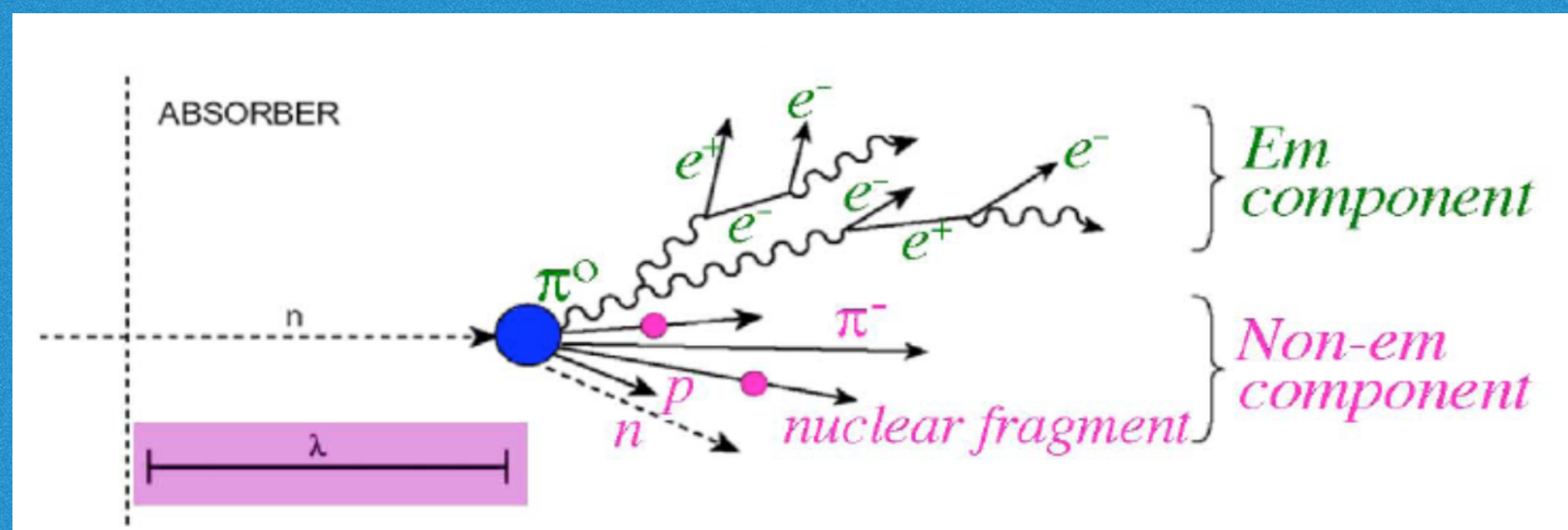
Studies started on a Crystal (LYSO:Ce + PbWO) ECAL/ Dual readout calorimetry

Dual Readout Calorimeter

Based on the DREAM/RD52 collaboration

Dual readout (DR) calorimeter measures both:

- Electromagnetic component
- Non-electromagnetic component



Fluctuations in event-by-event calorimeter response affect the energy resolution

Measure simultaneously:

Cherenkov light (sensitive to relativistic particles)
Scintillator light (sensitive to total deposited energy)

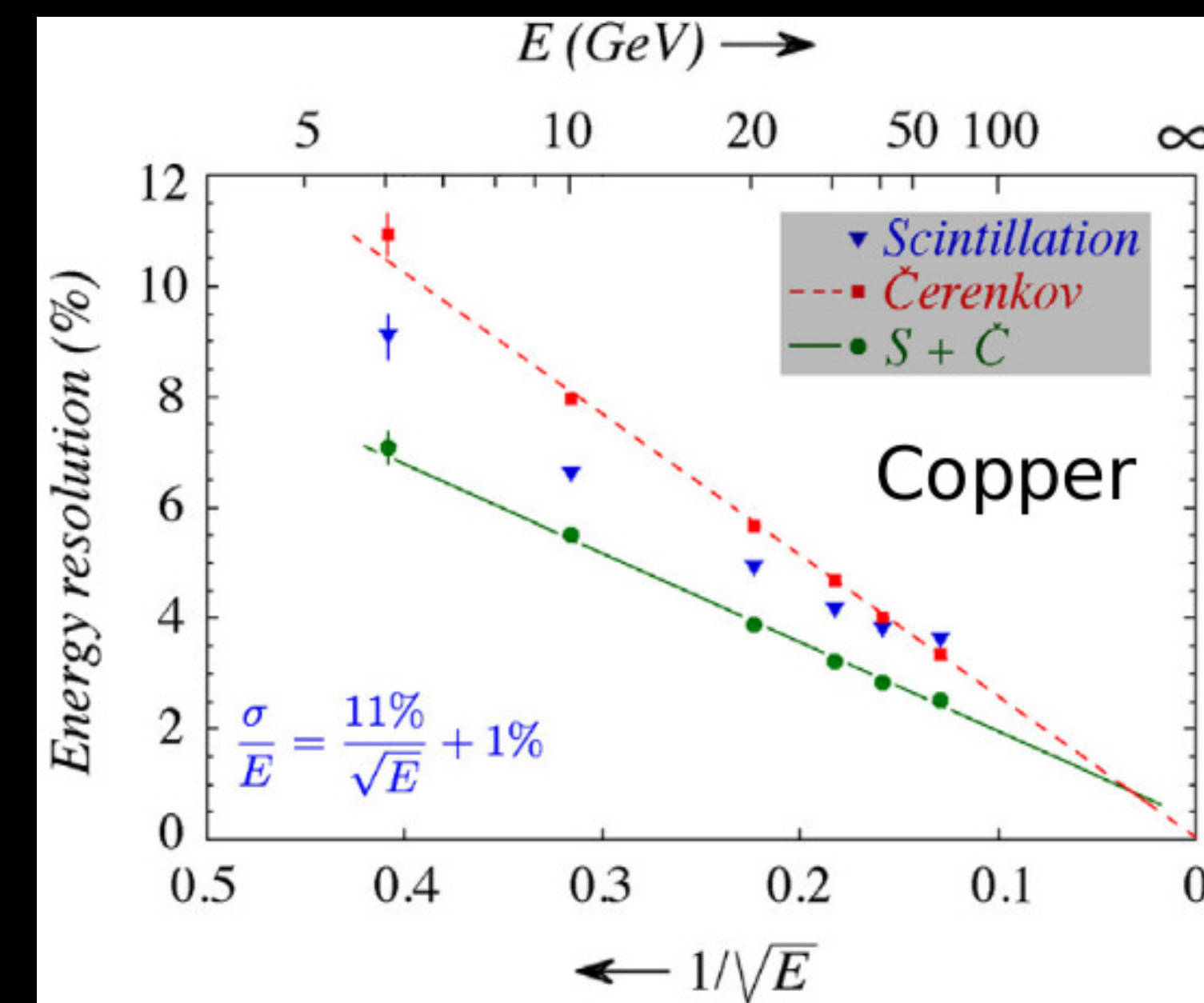
Expected resolution:

EM: $\sim 10\%/\sqrt{E}$

Hadronic: 30-40%/sqrt(E)

Several prototypes from RD52 have been built

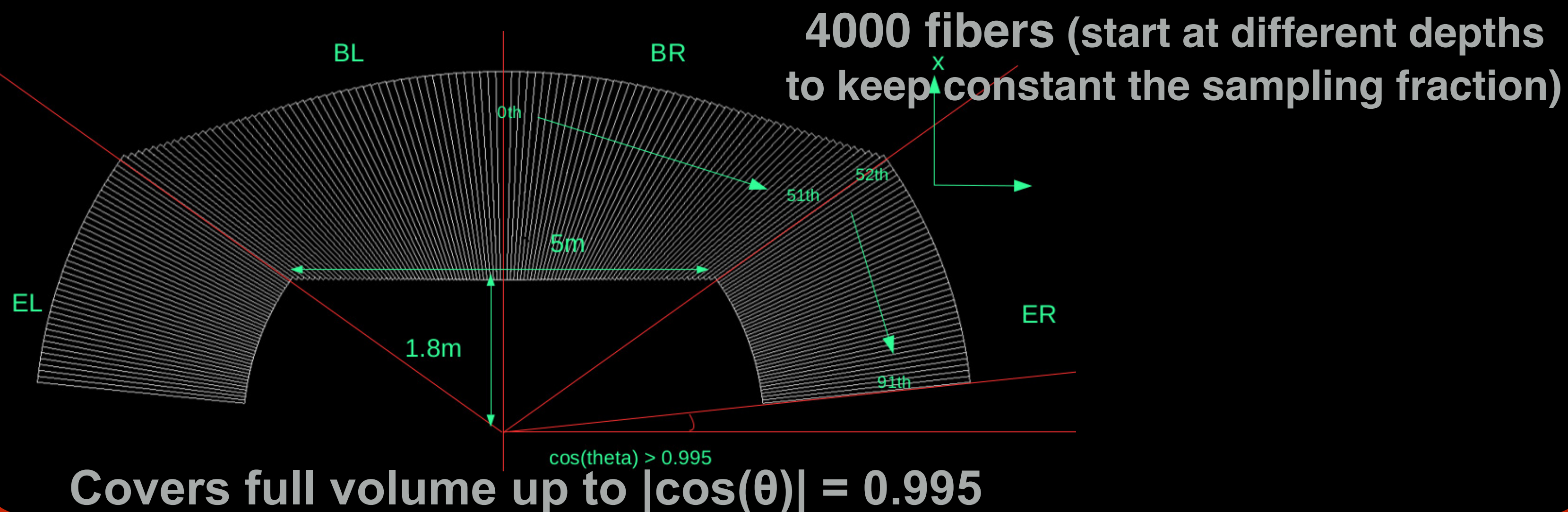
Energy resolution for electrons



Dual Readout Calorimeter

Based on the DREAM/RD52 collaboration

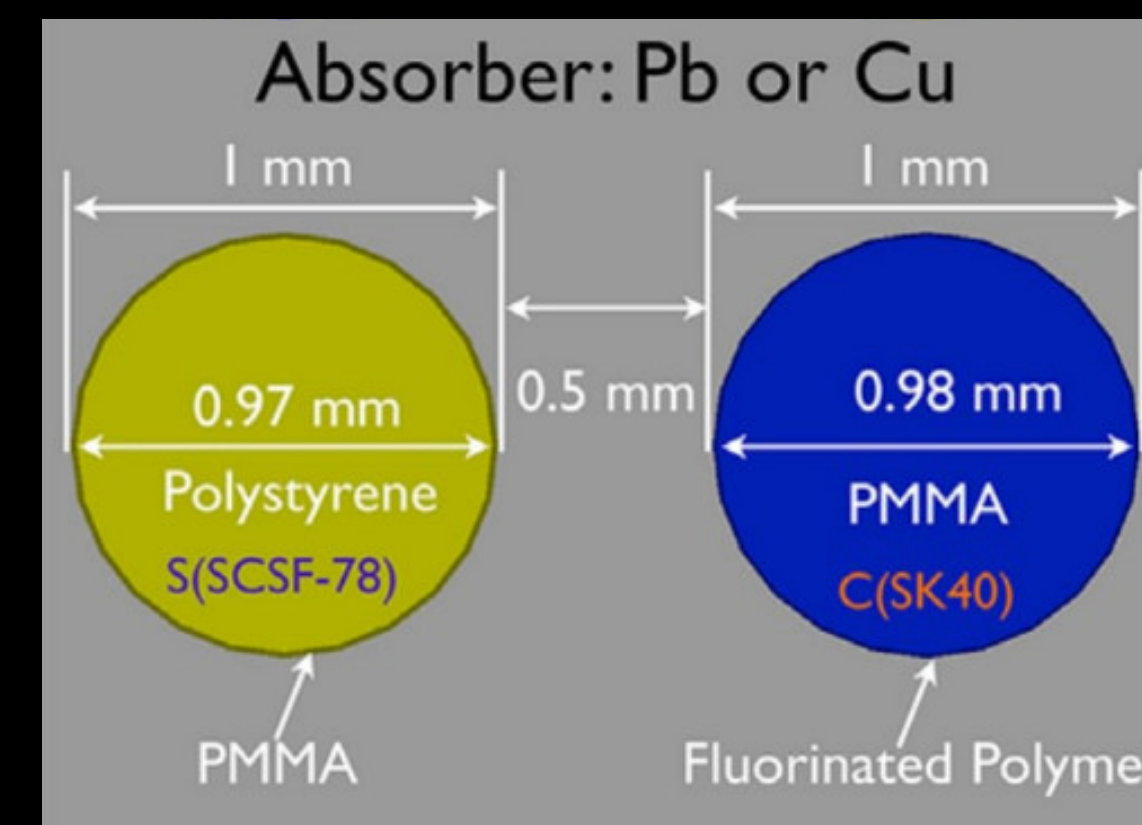
Projective 4π layout implemented into CEPC simulation
(based on 4th Detector Collaboration design)



Expected resolution:

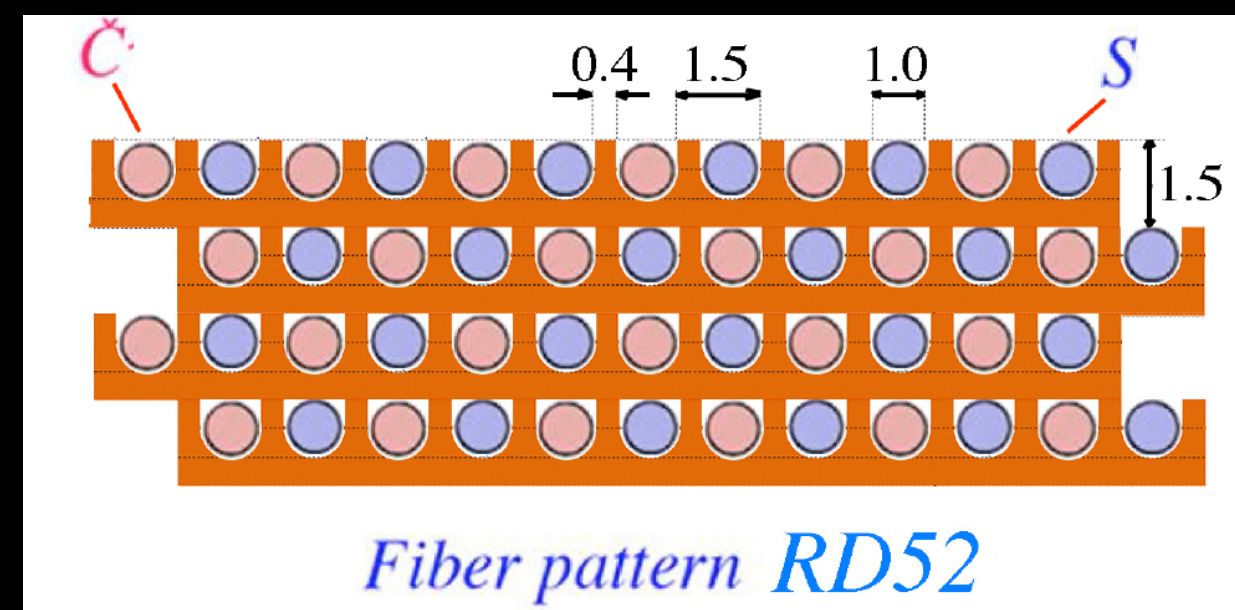
EM: $\sim 10\%/\sqrt{E}$

Hadronic: $30\text{-}40\%/\sqrt{E}$



Demonstration in test beam experiments

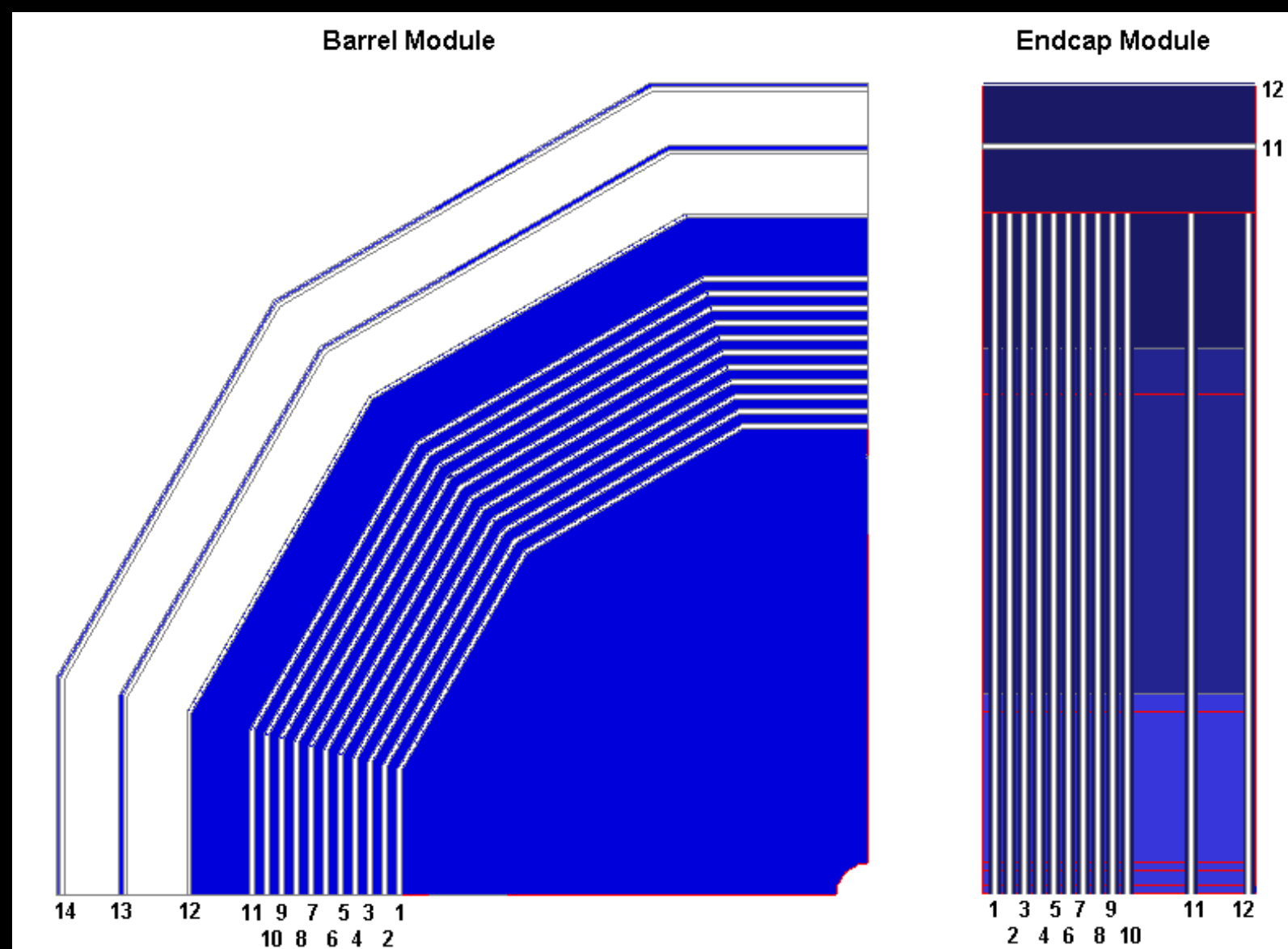
Studying different readout schemes
PMT vs SiPM



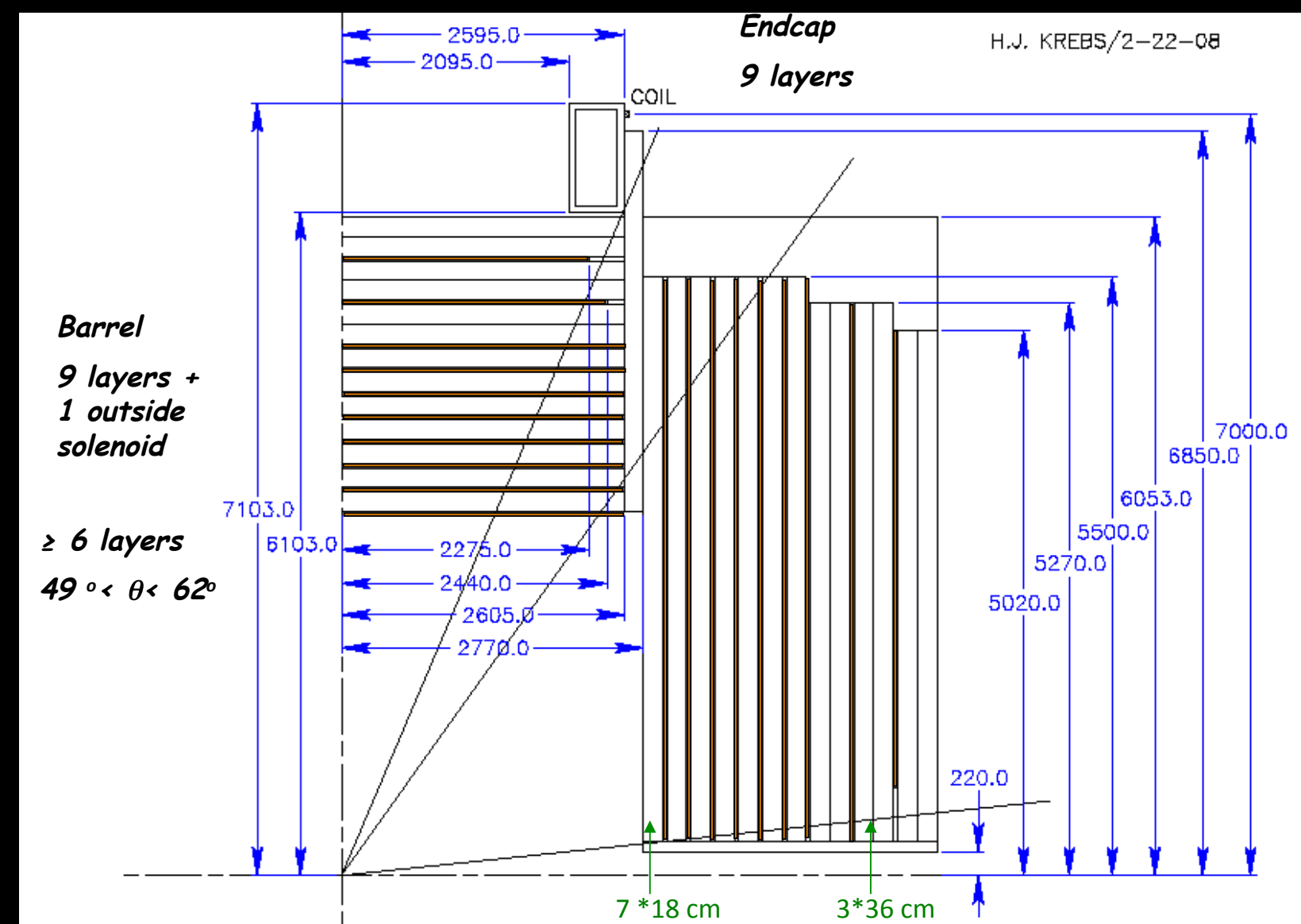
NEED: large size prototype
that could contain
full hadronic shower

Muon Systems

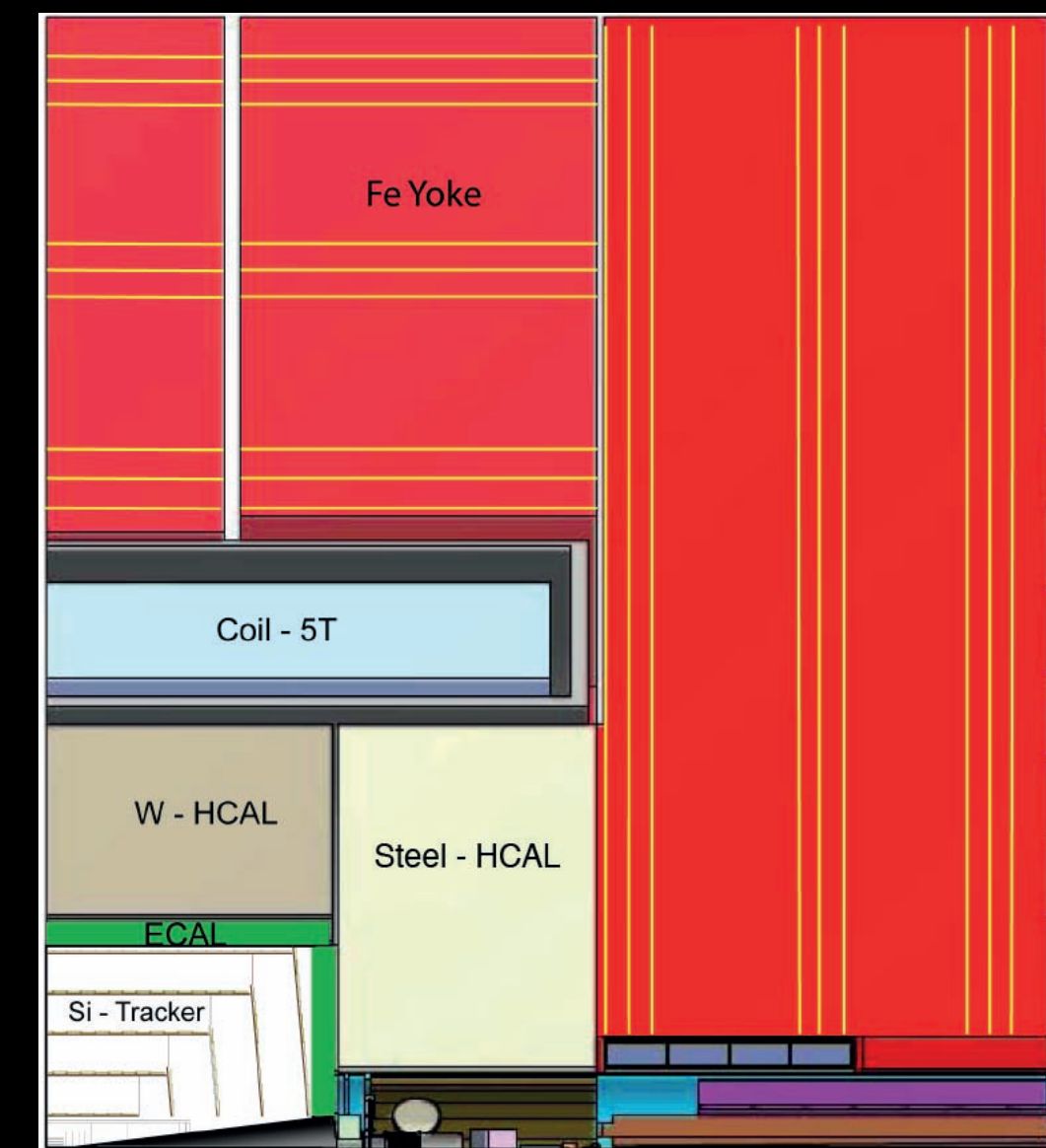
ILD: 12-14 sensitive layers



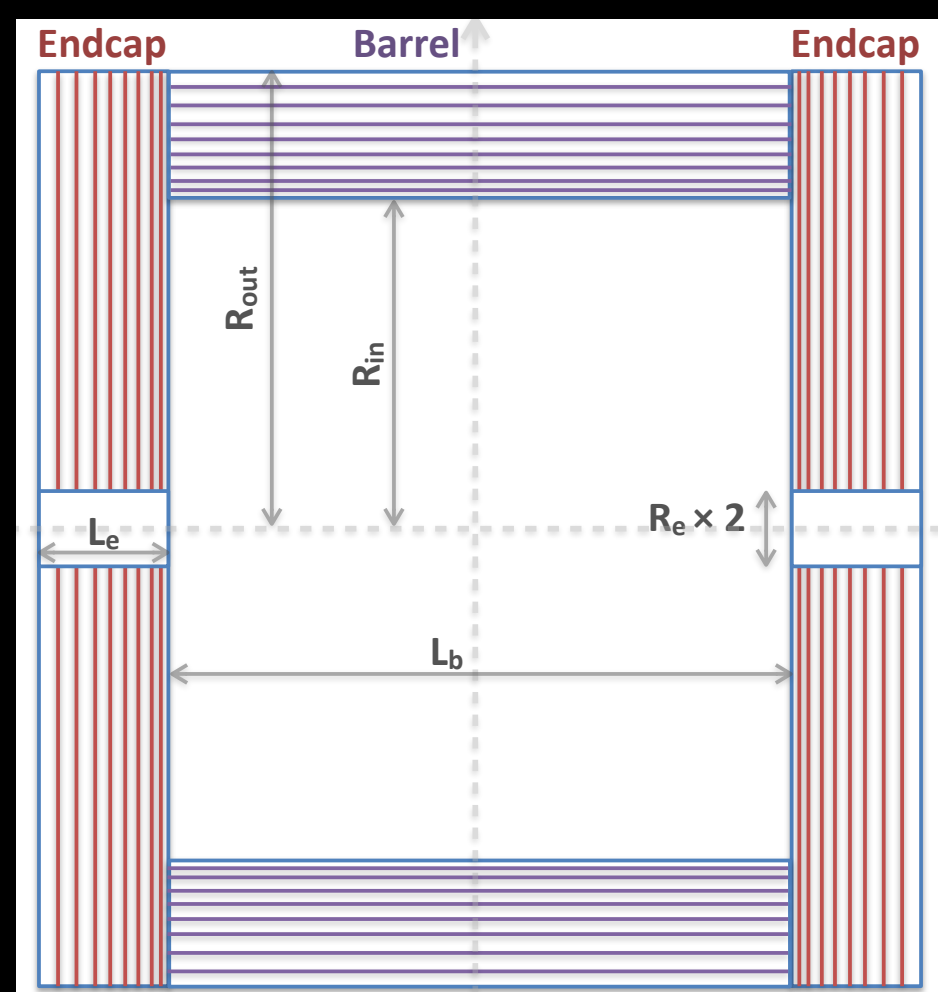
SiD: 9-10 sensitive layers



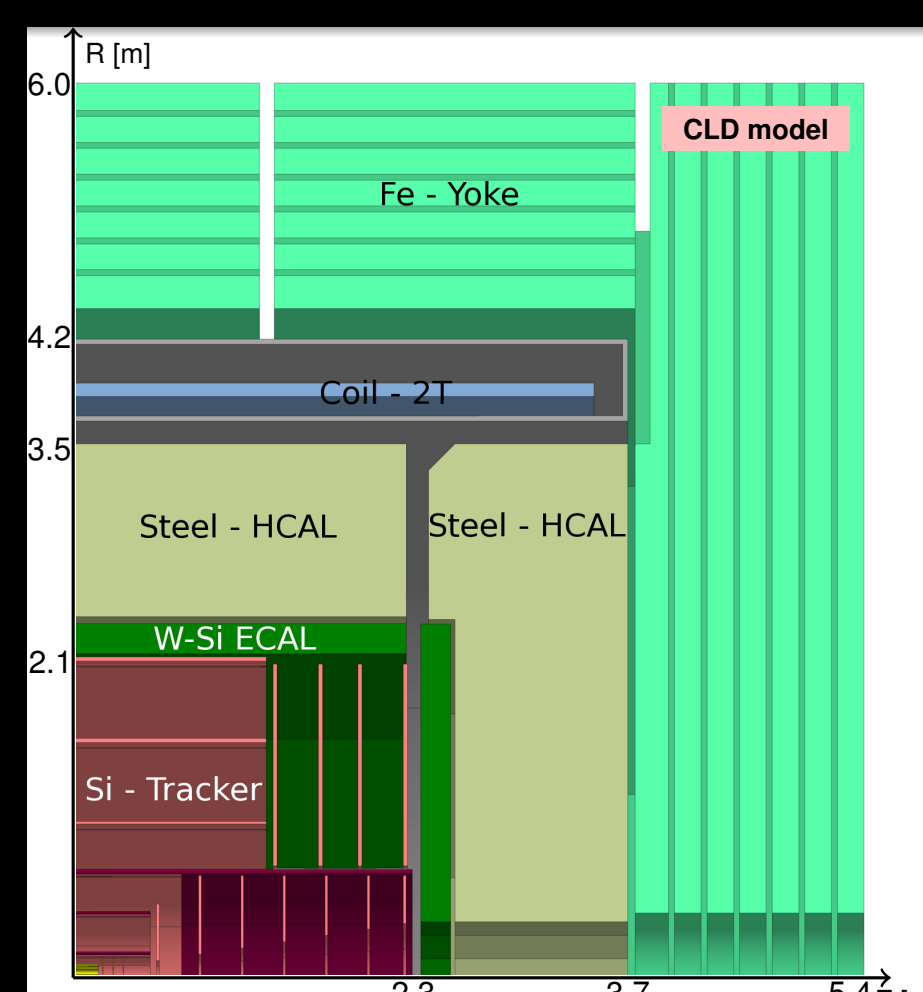
CLICdet: 9 sensitive layers



CEPC: 8 sensitive layers



FCC-ee - CLD: 6+1 sensitive layers



Technologies considered

- Resistive Plate Chambers (RPC)
- Thin Gap Chambers (TGC)
- Micromegas
- Gas Electron Multiplier (GEM)
- Scintillator Strips
- μ Rwell

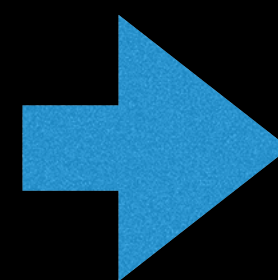
Detector for FCC-hh

100 km, ~100 TeV, pp collider

Pileup: number of pp collisions per bunch crossing (BC)

LHC: 30 collisions/BC

HL-LHC: 140 collisions/BC

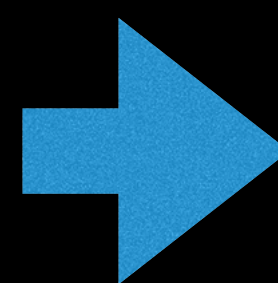
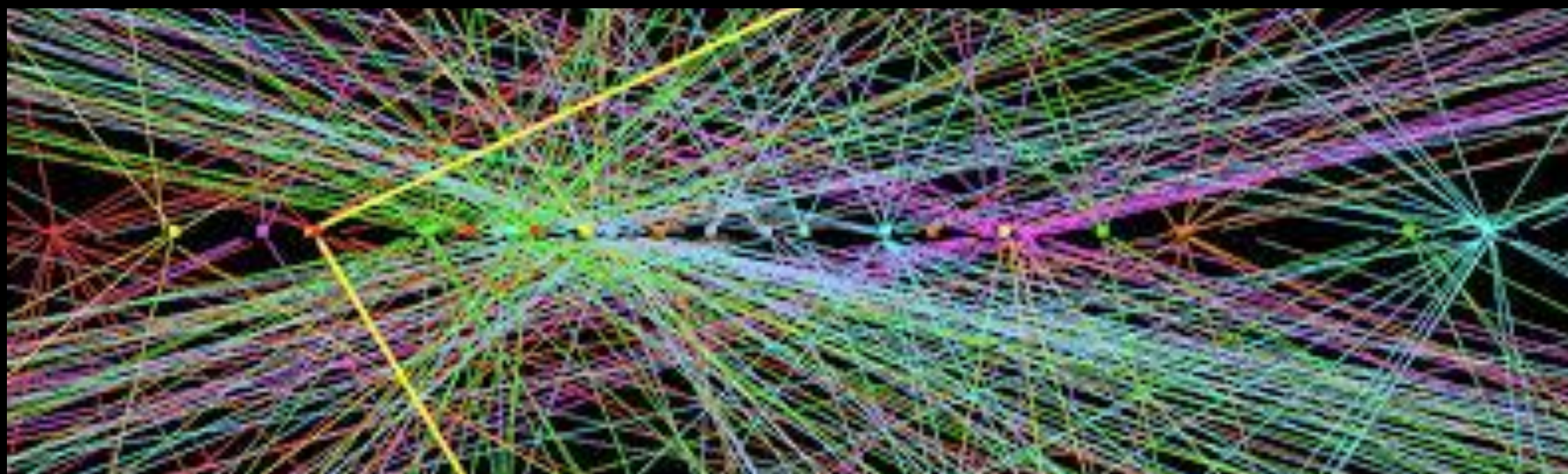


FCC-hh: 1000 collisions/BC

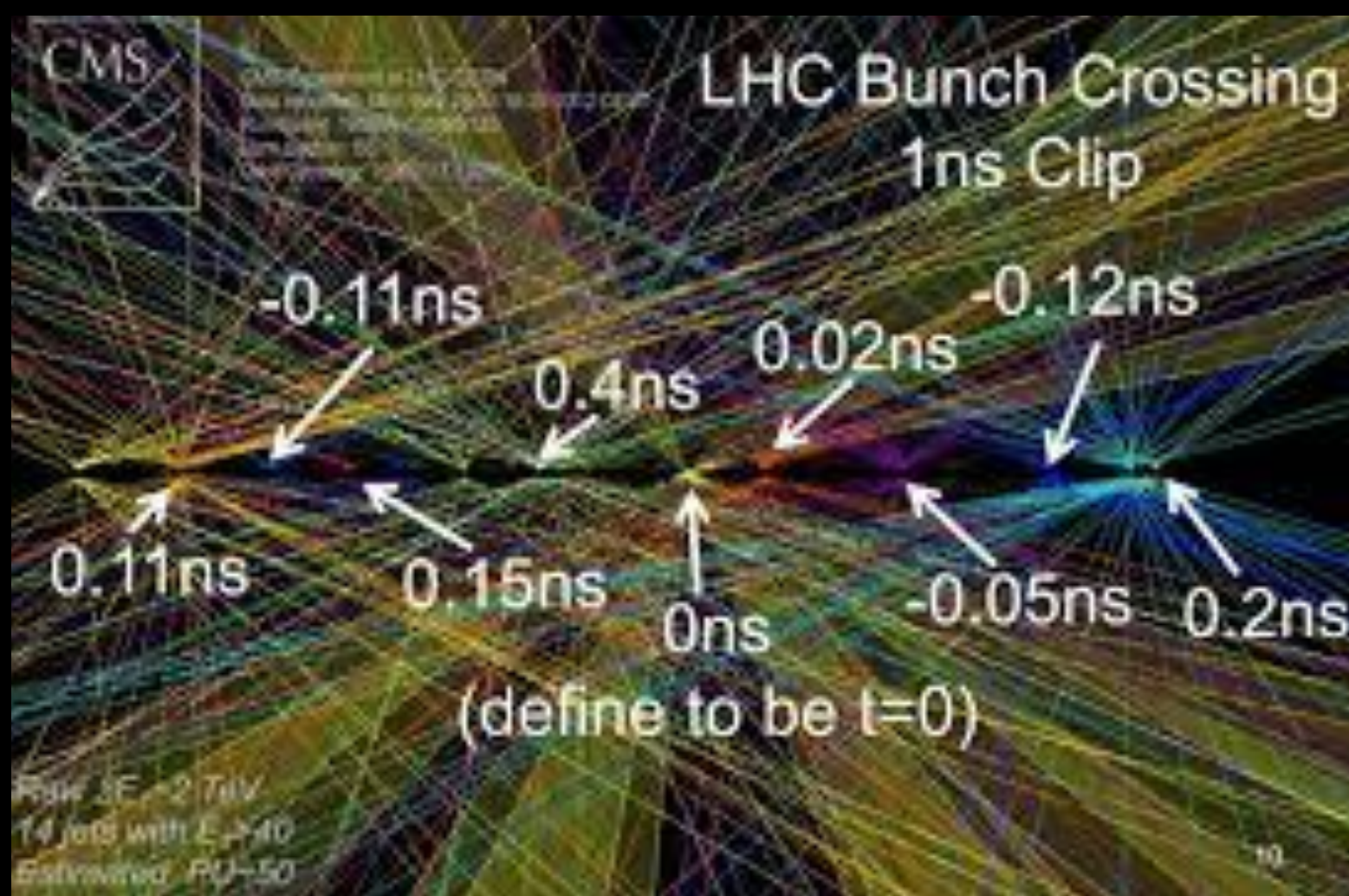
Pileup: number of pp collisions per bunch crossing (BC)

LHC: 30 collisions/BC

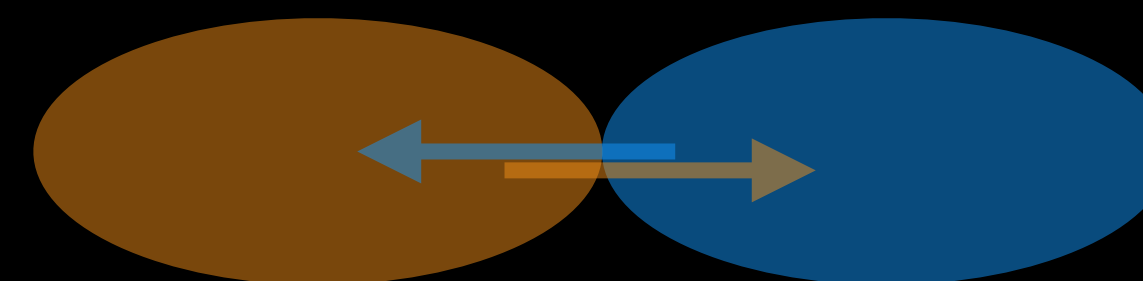
HL-LHC: 140 collisions/BC



FCC-hh: 1000 collisions/BC



Timescale difference of collisions within BC used for identification/reconstruction

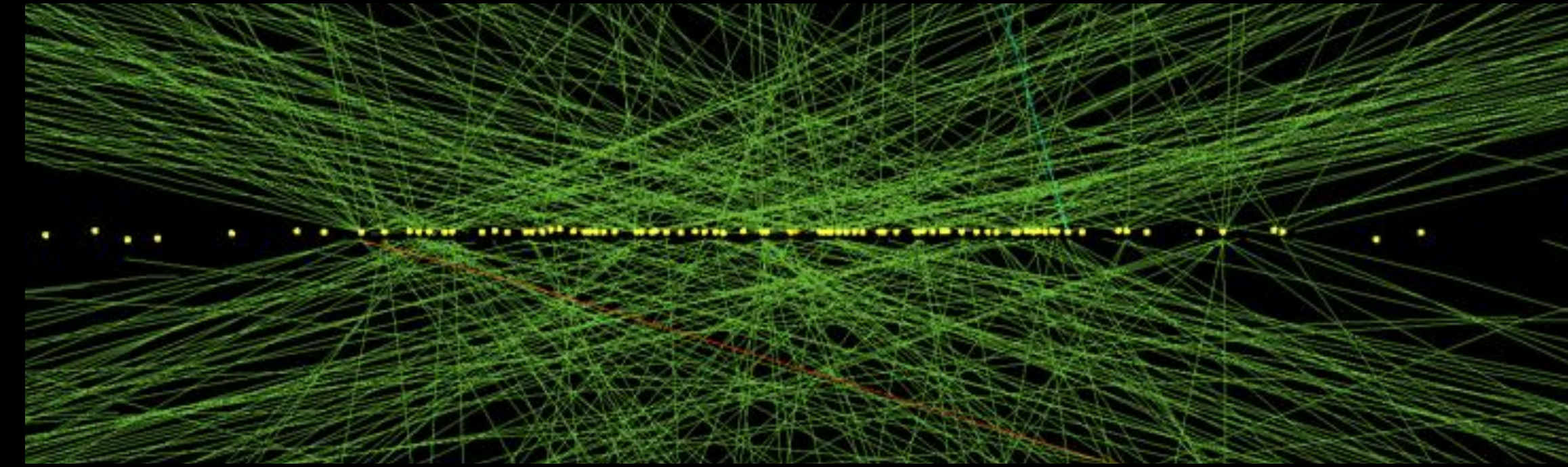
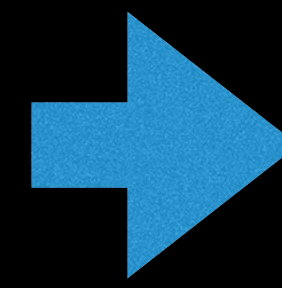


10-20 ps time resolution required

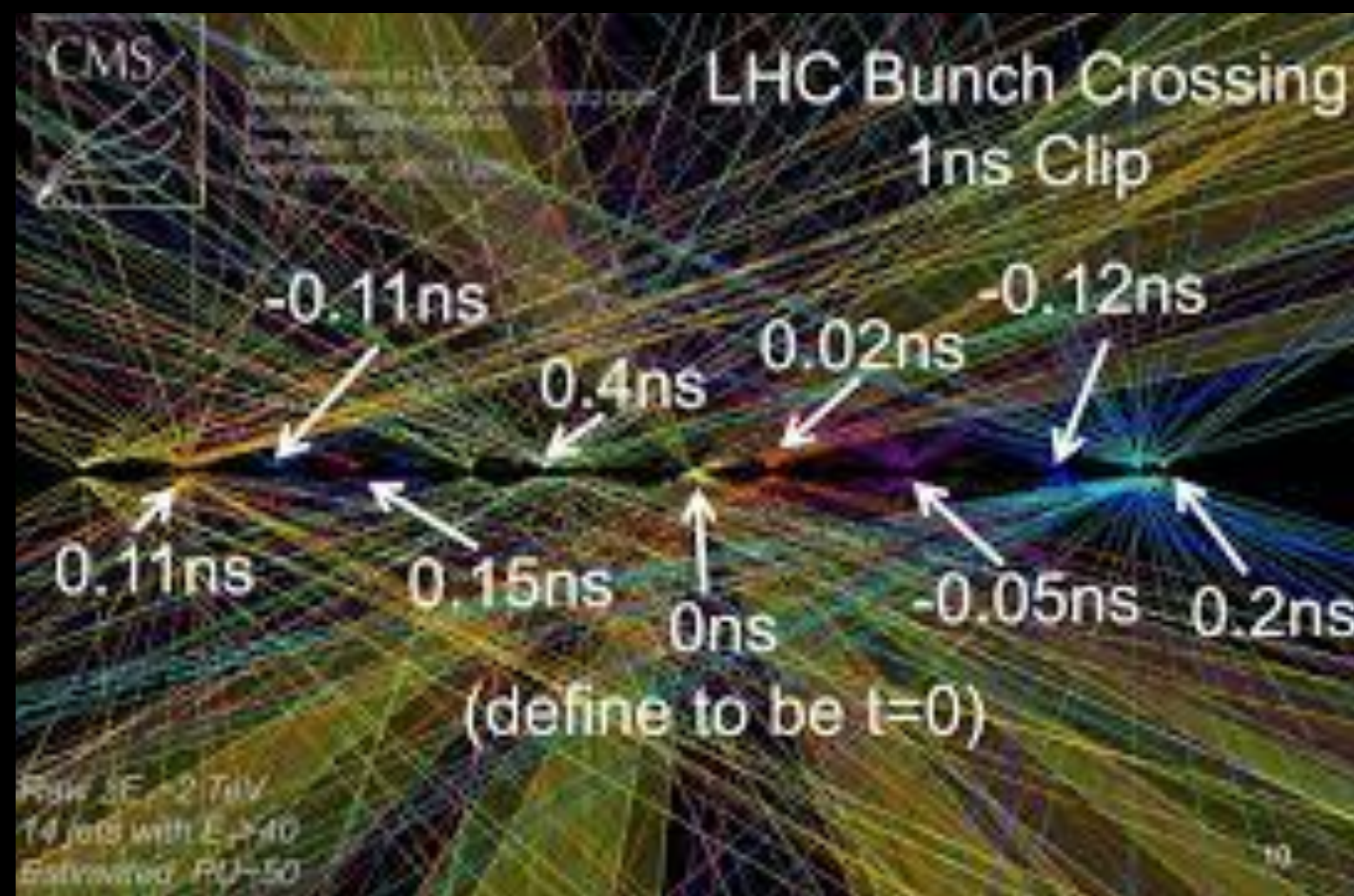
Pileup: number of pp collisions per bunch crossing (BC)

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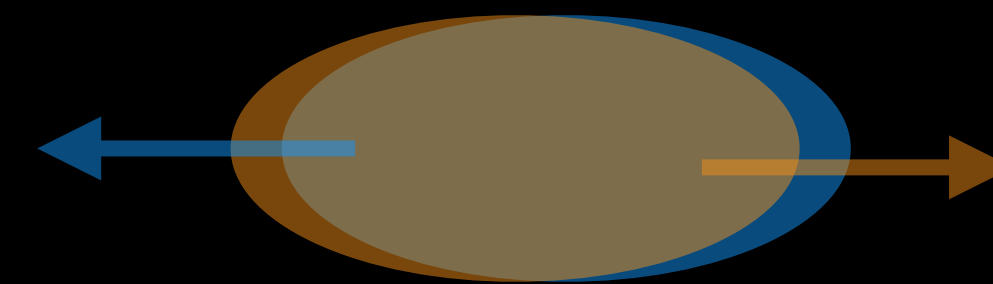
HL-LHC: 140 collisions/BC



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Timescale difference of collisions within BC used for identification/reconstruction

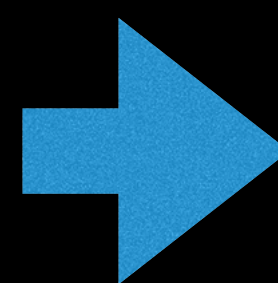
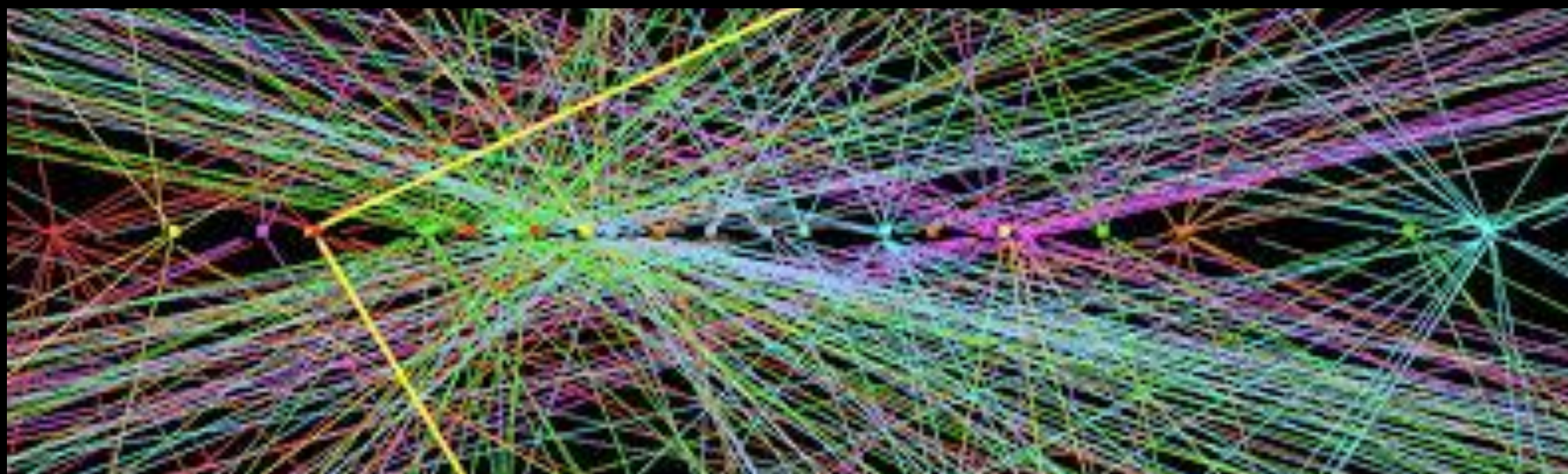


10-20 ps time resolution required

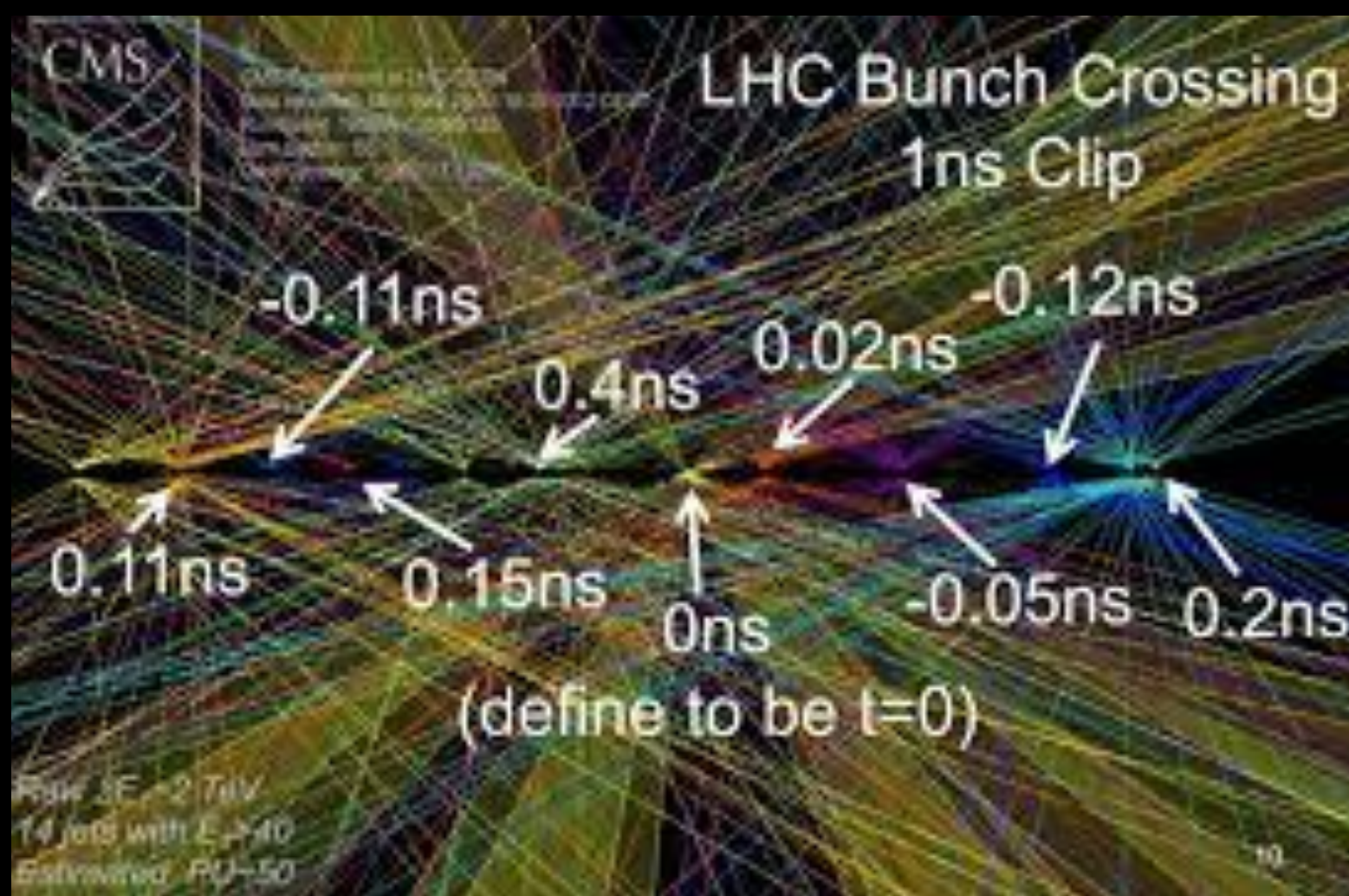
Pileup: number of pp collisions per bunch crossing (BC)

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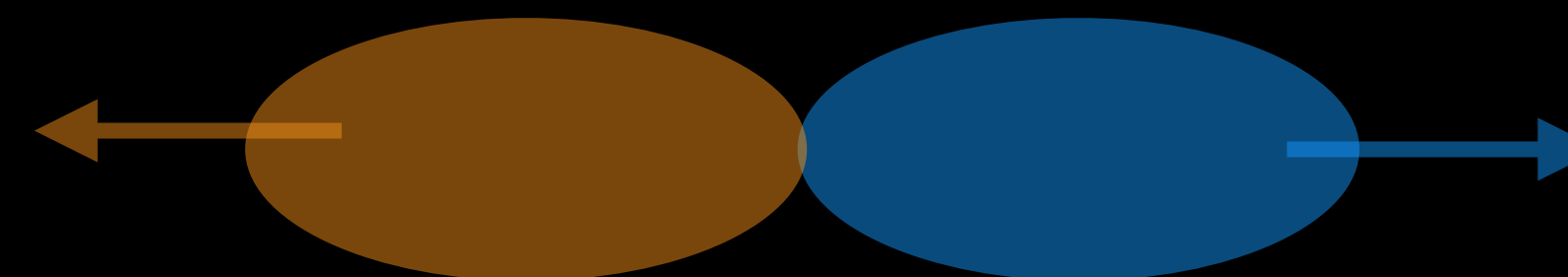
HL-LHC: 140 collisions/BC



FCC-hh: 1000 collisions/BC



Timescale difference of collisions within BC used for identification/reconstruction



10-20 ps time resolution required

Parameter table

Parameter	Unit	LHC	HL-LHC	HE-LHC	FCC-hh
E_{cm}	TeV	14	14	27	100
Circumference	km	26.7	26.7	26.7	97.8
Peak \mathcal{L} , nominal (ultimate)	$10^{34} \text{ cm}^{-2} \text{ s}^{-1}$	1 (2)	5 (7.5)	16	30
Bunch spacing	ns	25	25	25	25
Number of bunches		2808	2760	2808	10600
Goal $\int \mathcal{L}$	ab^{-1}	0.3	3	10	30
σ_{inel} [331]	mb	80	80	86	103
σ_{tot} [331]	mb	108	108	120	150
BC rate	MHz	31.6	31.0	31.6	32.5
Peak pp collision rate	GHz	0.8	4	14	31
Peak av. PU events/BC, nominal (ultimate)		25 (50)	130 (200)	435	950
Rms luminous region σ_z	mm	45	57	57	49
Line PU density	mm^{-1}	0.2	1.0	3.2	8.1
Time PU density	ps^{-1}	0.1	0.29	0.97	2.43
$dN_{ch}/d\eta _{\eta=0}$ [331]		6.0	6.0	7.2	10.2
Charged tracks per collision N_{ch} [331]		70	70	85	122
Rate of charged tracks	GHz	59	297	1234	3942
$\langle p_T \rangle$ [331]	GeV/c	0.56	0.56	0.6	0.7
Bending radius for $\langle p_T \rangle$ at B=4 T	cm	47	47	49	59

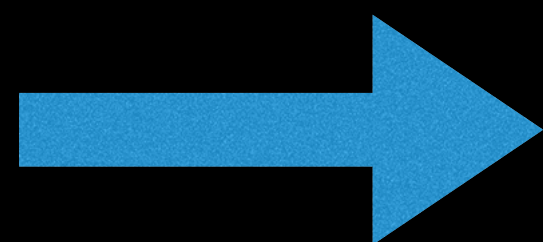
$30 \times 10^{34} \text{ cm}^{-2} \text{ s}^{-1}$
Luminosity

31 GHz
collision rate

4 THz
track rate

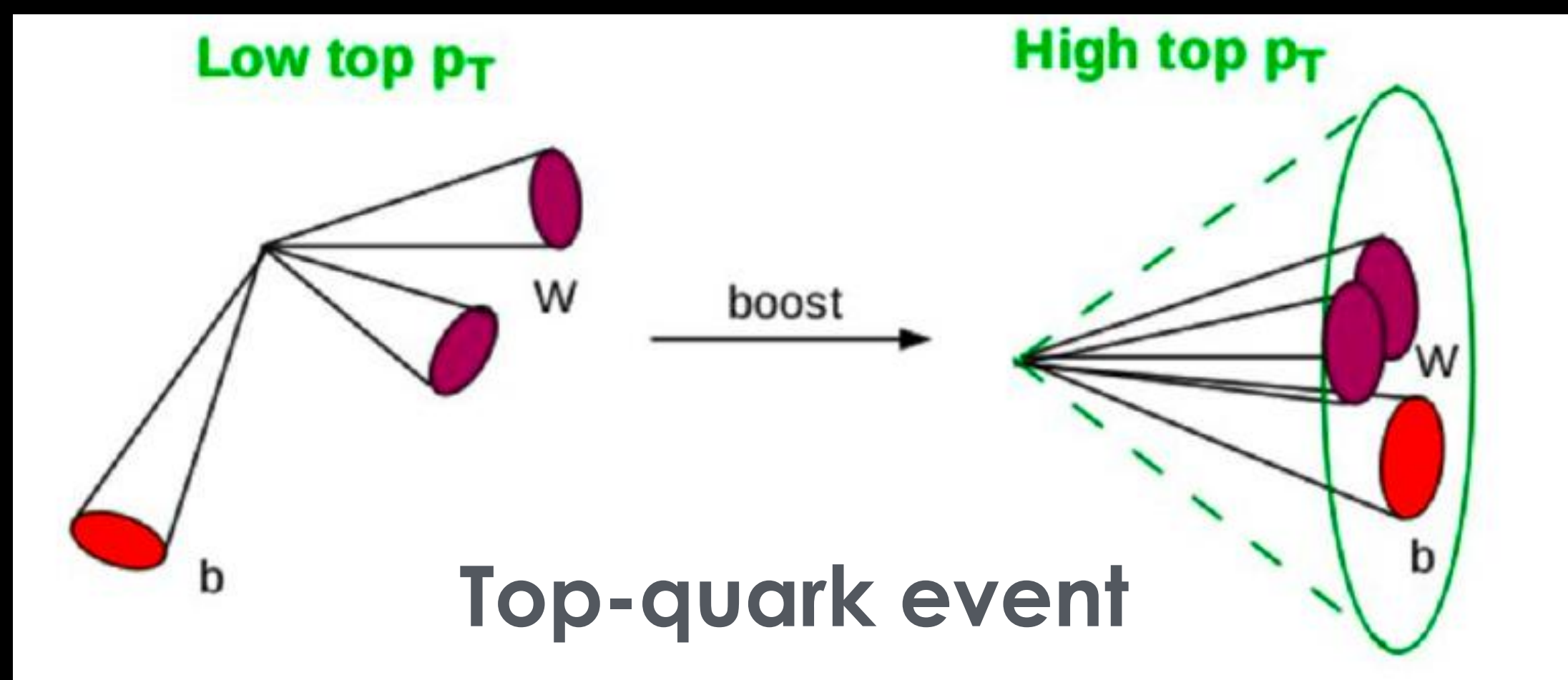
Physics requirements

100 TeV Collisions



Physics Objects will be more boosted

Overlapping physics objects



Long-lived particles travel longer

5 TeV τ -lepton can travel 10 cm before decaying

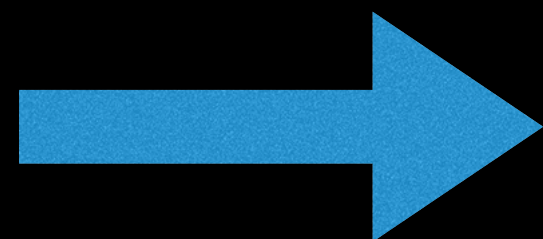
5 TeV b -hadron can travel 50 cm before decaying

Requirements of high granularity
(both in tracker and calorimeters)

Requirement of extensive
precise tracking/vertexing systems

Physics requirements

100 TeV Collisions



Physics Objects will be more boosted

Tracking

Tracks target resolution:

$$\sigma(p_T)/p_T = (10 - 20) \% @ 10 \text{ TeV}$$

10% @ 1 TeV at LHC

$$\sigma(p_T)/p_T < 1\% \text{ for low } p_T \text{ tracks}$$

(multiple scattering limit)

Muons target resolution:

$$\sigma(p)/p = 5 \% @ 10 \text{ TeV } (\eta \sim 0)$$

Calorimeter

Keep constant term as small as possible

Electron/photon target resolution:

$$\sigma(E)/E = 10\%/\sqrt{E} \oplus 1\%$$

Jets target resolution:

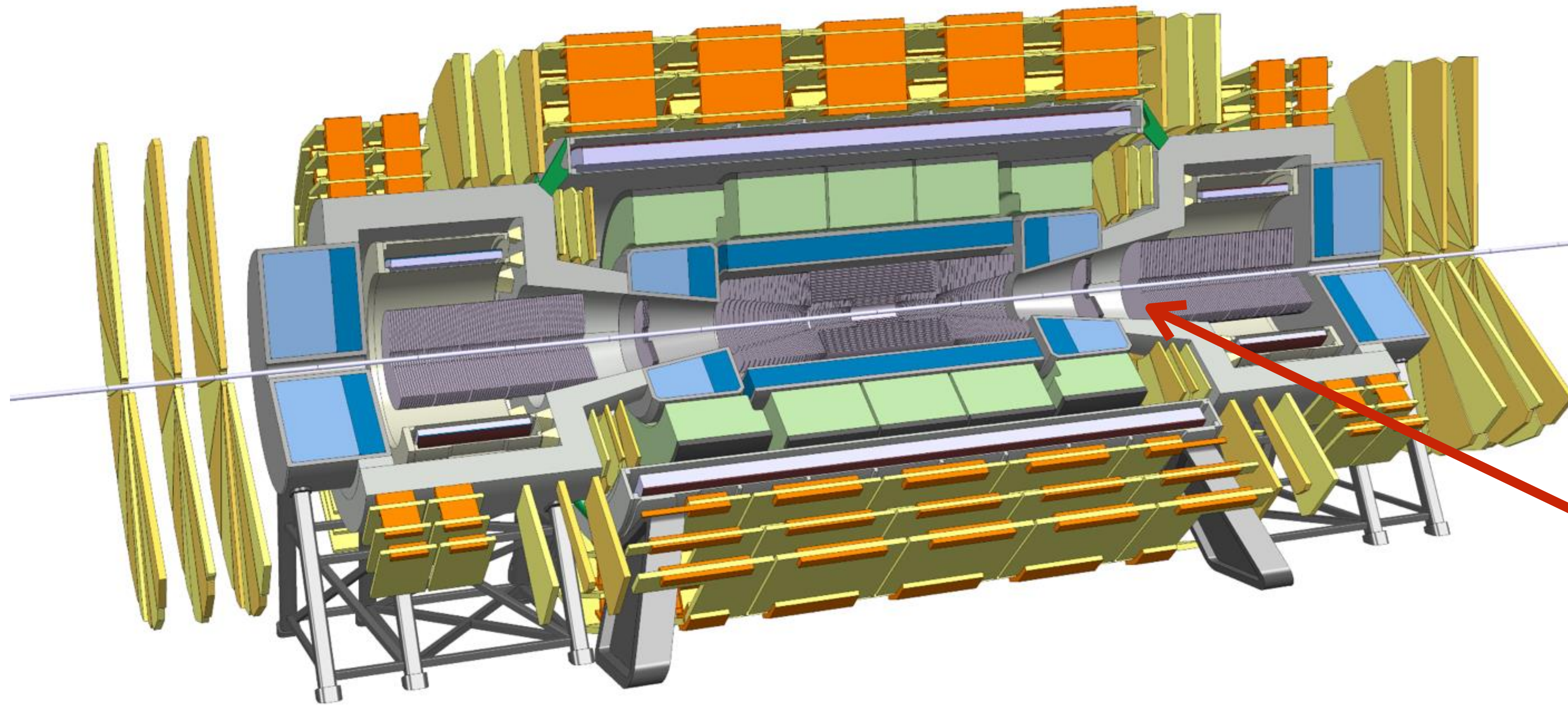
$$\sigma(E)/E = (50 - 60)\%/\sqrt{E} \oplus 3\%$$

Transverse granularity 4× better than
ATLAS and CMS

Reference detector for FCC-hh

Challenging radiation levels

HL-LHC muon system should work for most of FCC-hh detector areas



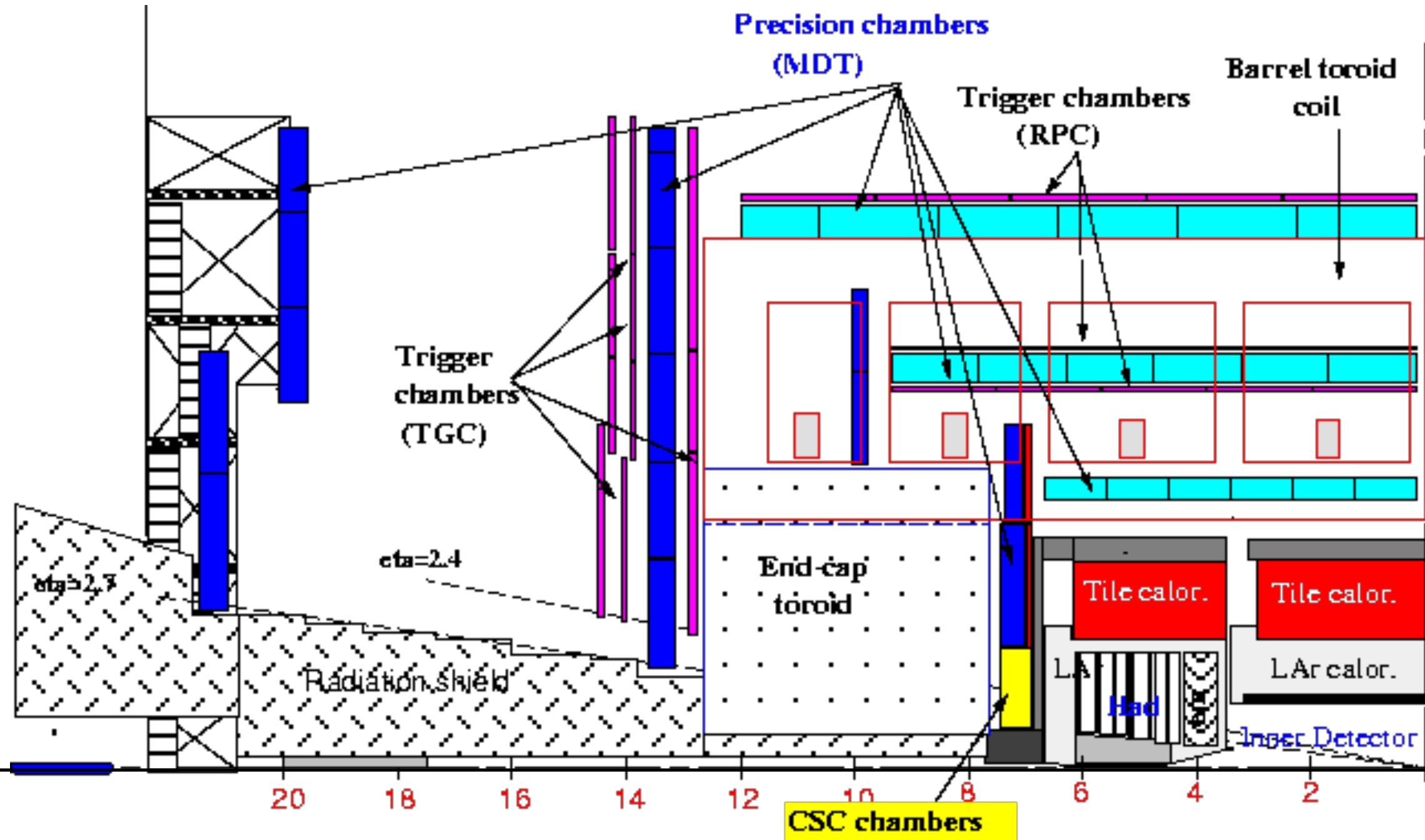
- 4T 10m solenoid
- Forward solenoids
- Silicon tracker
- Barrel ECAL LAr
- Barrel HCAL Fe/Sci
- Endcap HCAL/ECAL LAr
- Forward HCAL/ECAL LAr

Need high-granularity

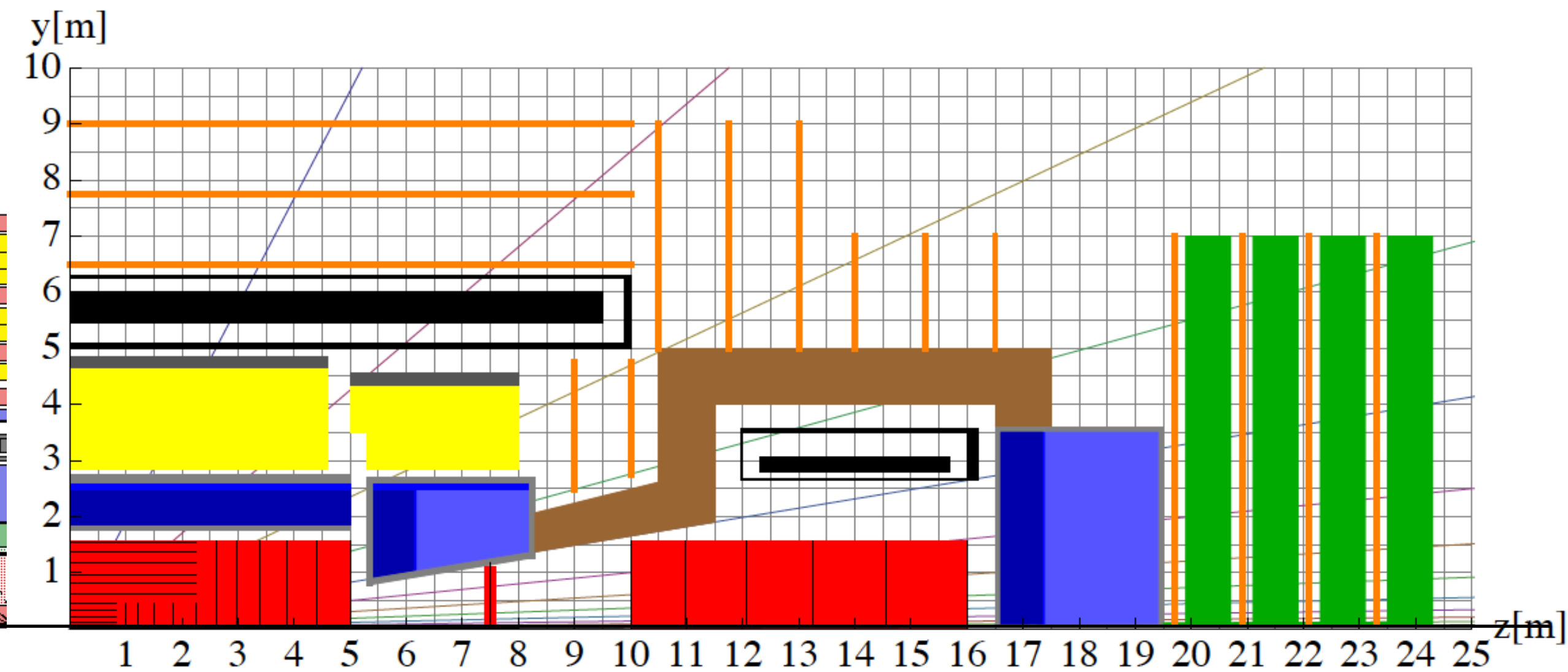
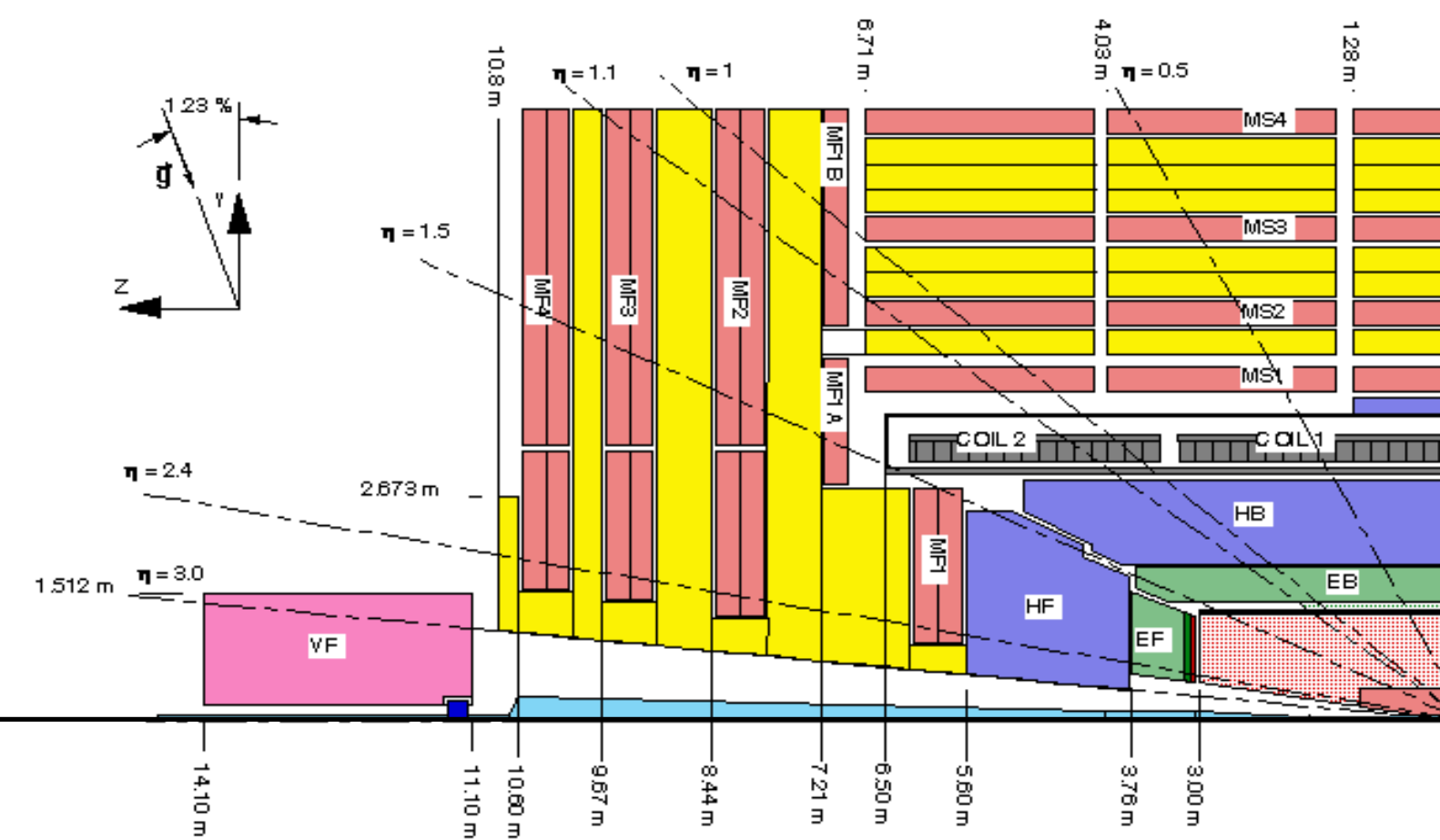
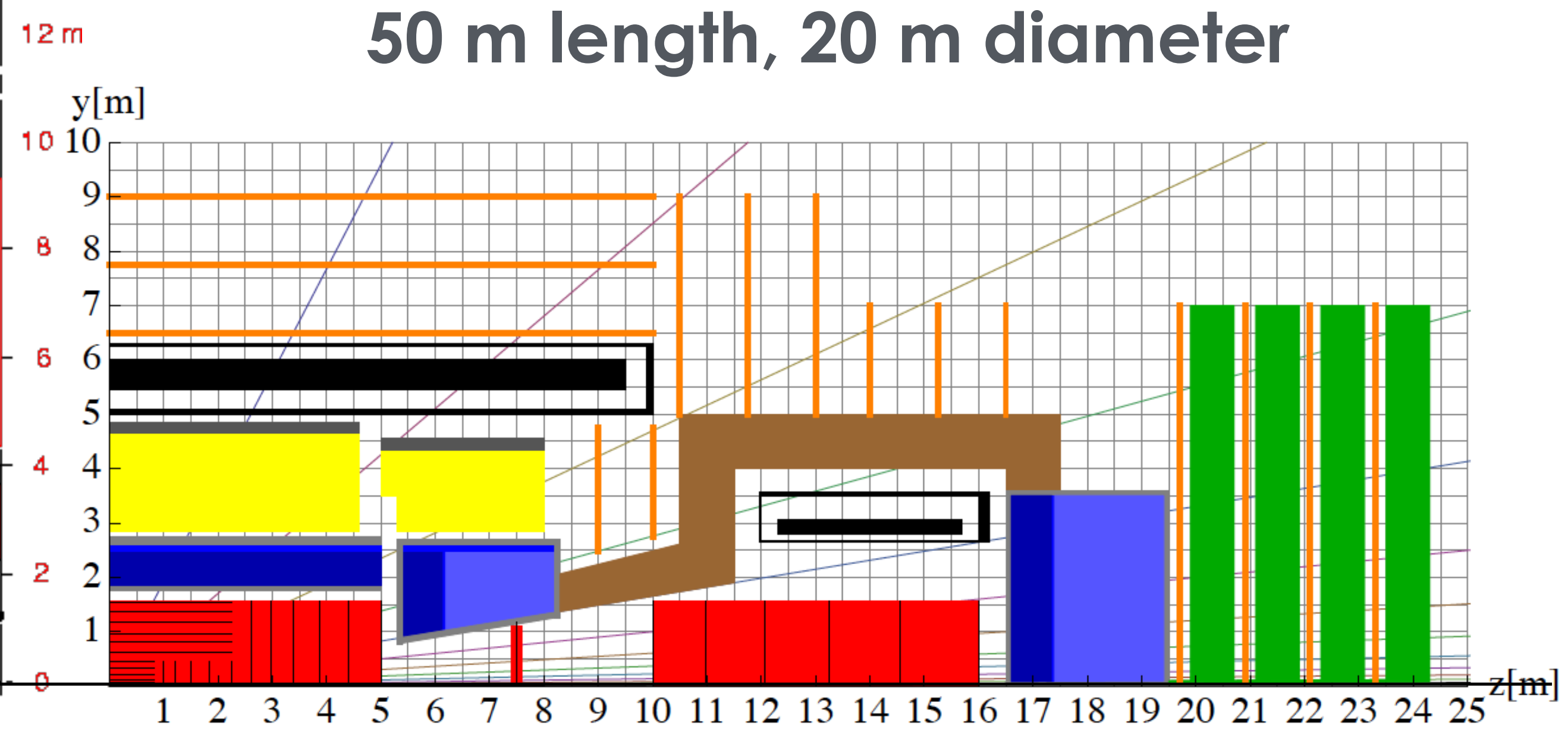
> 20 tracker disks

$L^* \sim 40$ m in contrast to ~ 2 m for FCC-ee/CEPC

Comparison with ATLAS and CMS



50 m length, 20 m diameter



Major **Technology R&D** for Future Experiments

Silicon detectors

Gas detectors

Calorimetry

Detector magnets

Major **Technology R&D** for Future Experiments

Silicon detectors	LGAD sensor Monolithic CMOS sensors
Gas detectors	Large area gaseous detector Novel materials and fabrication techniques
Calorimetry	Silicon based calorimetry Scintillators+SiPM based detectors Liquid Argon detectors Dual Readout calorimetry
Detector magnets	Reinforced super conductors Ultra-light cryostat Advanced magnet powering systems

Major **Technology R&D** for Future Experiments

Silicon detectors

Detector mechanics

Gas detectors

IC technologies

Calorimetry

High speed electronics

Detector magnets

Software

Major **Technology R&D** for Future Experiments

Silicon detectors	Low-mass mechanical structures High performance cooling	Detector mechanics
Gas detectors	Mainstream CMOS technologies (28/16 nm)	IC technologies
Calorimetry	ASICs for up to 56 Gb/s data links High performance FPGAs Optoelectronics	High speed electronics
Detector magnets	Faster simulation Heterogeneous computing frameworks (GPUs, FPGA) Efficient analysis facilities Efficient resource sharing across experiments	Software

Final remarks

The discover of the Higgs at 125 GeV made e^+e^- **circular** machines a possibility,
in addition to **linear** e^+e^- colliders

These precision machines have a broad physics potential and push for new technological advances in detectors

Hadronic machines continue to be tool for the exploration of the highest energies

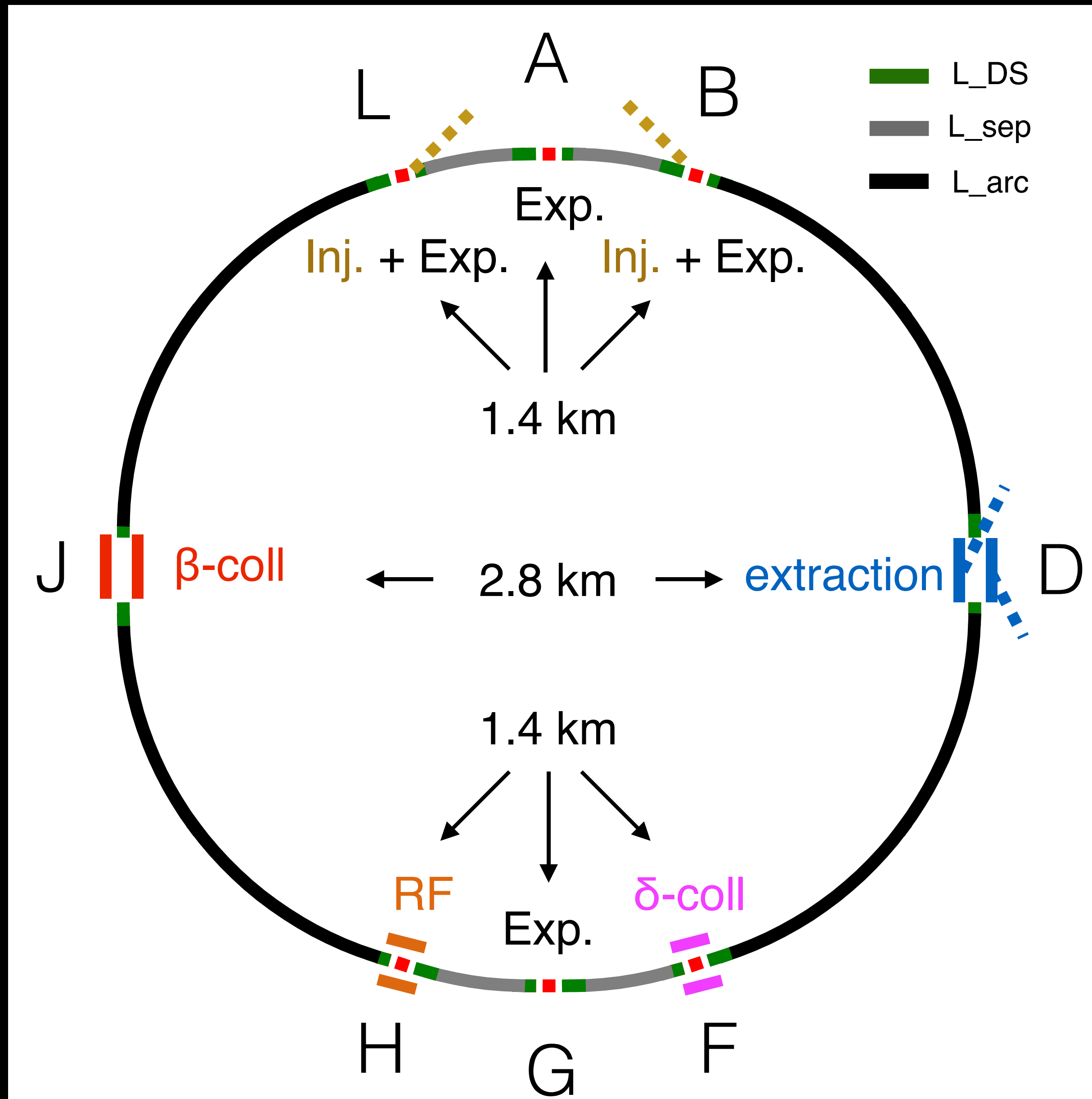
Current proposals bring detector challenges associated with the large event rates and radiation levels

There are currently many concurrent studies on detector concepts with demanding requirements from physics goals and experimental conditions

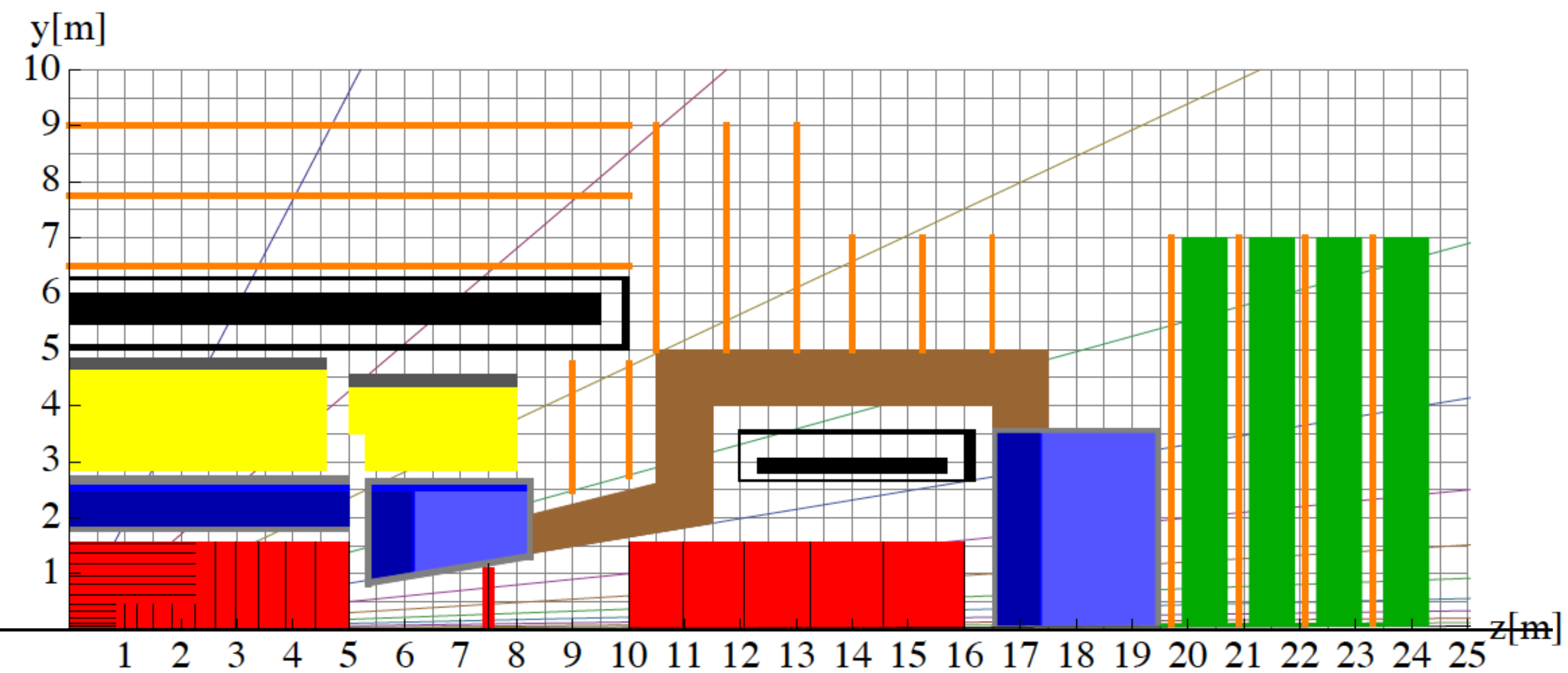
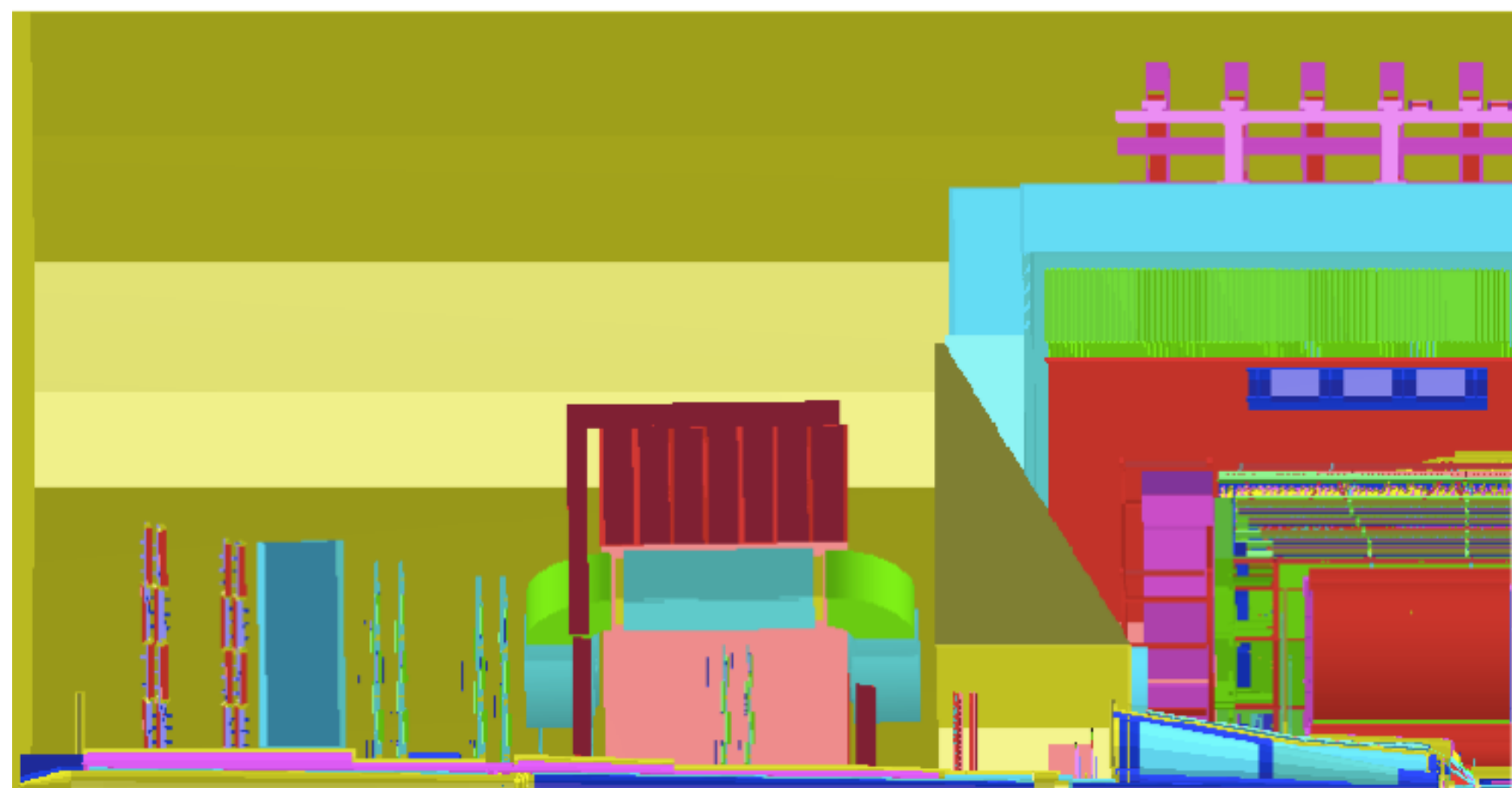
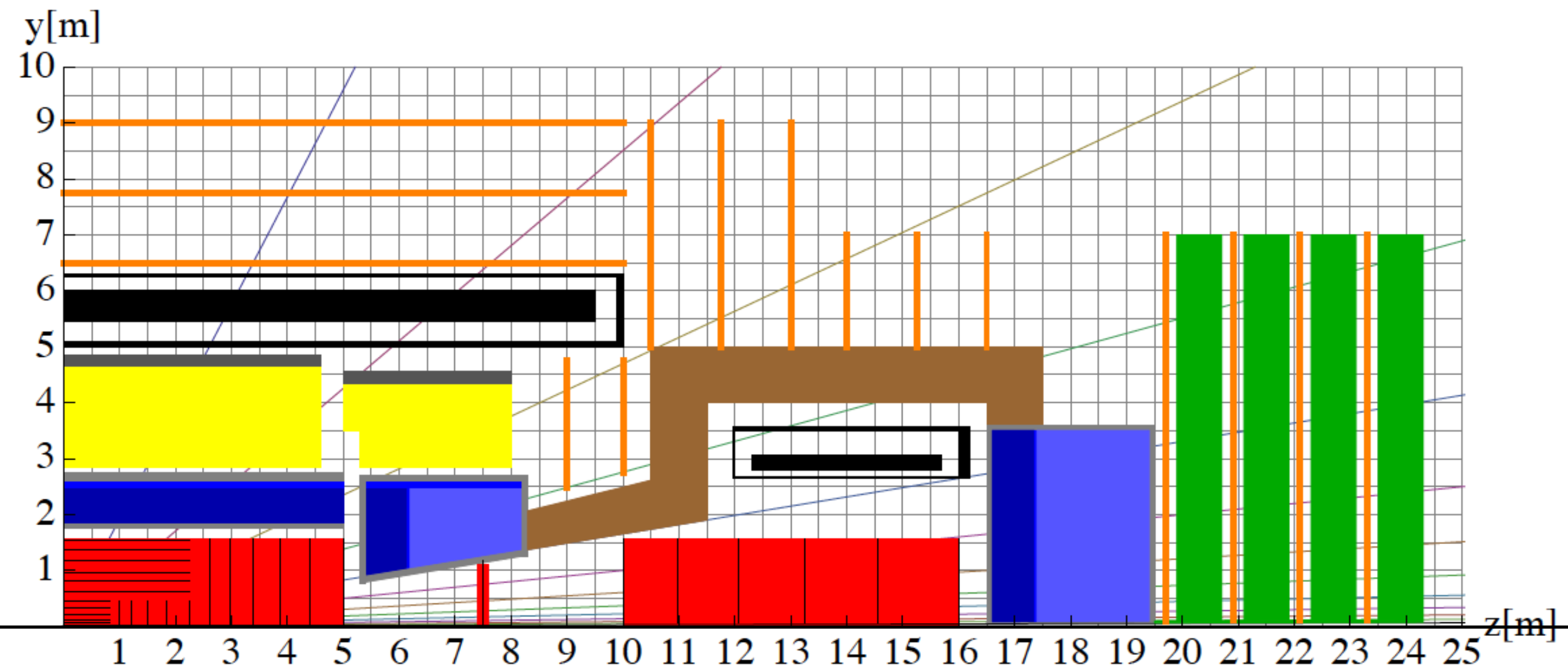
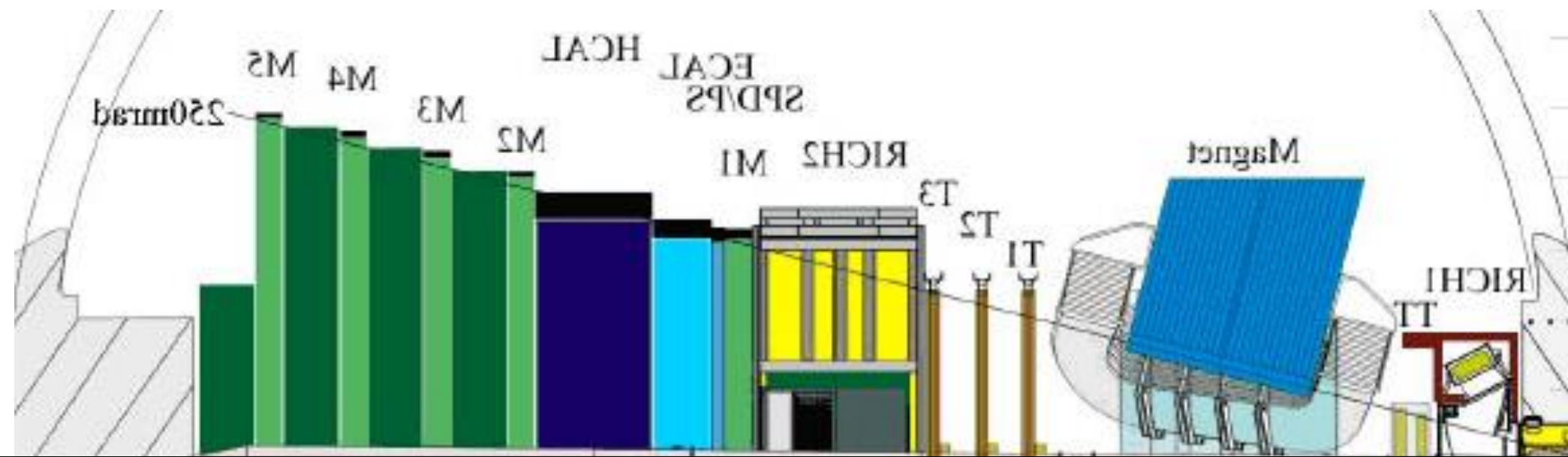
Large synergies between collider projects and already approved experiments

Active detector collaborations and R&D spin-offs

FCC-hh Collider Ring and Experiments



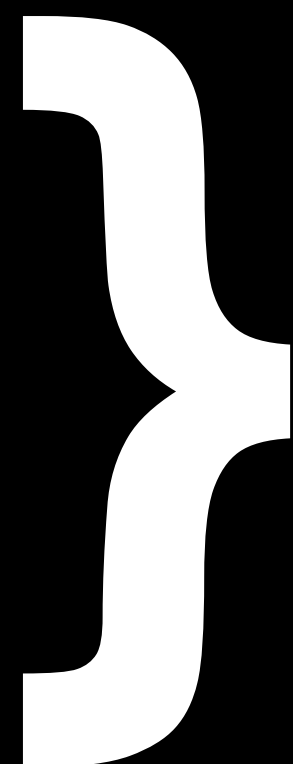
Comparison with LHCb and ALICE



Interaction region: Machine Detector Interface

Machine induced backgrounds

- Radiative Bhabha scattering
- Beam-beam interactions
- Synchrotron radiation
- Beam-gas interactions



Studies for new configuration being finalized

Higgs operation
($E_{cm} = 240 \text{ GeV}$)

Rates at the inner layer (16 mm):

Hit density: $\sim 2.5 \text{ hits/cm}^2/\text{BX}$
TID: 2.5 MRad/year
NIEL: $10^{12} \text{ 1MeV } n_{eq}/\text{cm}^2$

(Safety factors of 10 applied)

